SIEMENS

SIMATIC

Overview Safety instructions Mounting and connecting the device Industrial PC SIMATIC IPC677D Commissioning the device Operating the device and device functions **Operating Instructions** Expanding the device and assigning device parameters Maintaining and servicing your device **Technical information Technical support** Meaning of the symbols on your device

Preface

1

2

3

4

5

6

7

8

Α

Β

С

List of abbreviations

Legal information

Warning notice system

This manual contains notices you have to observe in order to ensure your personal safety, as well as to prevent damage to property. The notices referring to your personal safety are highlighted in the manual by a safety alert symbol, notices referring only to property damage have no safety alert symbol. These notices shown below are graded according to the degree of danger.

indicates that death or severe personal injury will result if proper precautions are not taken.

indicates that death or severe personal injury **may** result if proper precautions are not taken.

indicates that minor personal injury can result if proper precautions are not taken.

NOTICE

indicates that property damage can result if proper precautions are not taken.

If more than one degree of danger is present, the warning notice representing the highest degree of danger will be used. A notice warning of injury to persons with a safety alert symbol may also include a warning relating to property damage.

Qualified Personnel

The product/system described in this documentation may be operated only by **personnel qualified** for the specific task in accordance with the relevant documentation, in particular its warning notices and safety instructions. Qualified personnel are those who, based on their training and experience, are capable of identifying risks and avoiding potential hazards when working with these products/systems.

Proper use of Siemens products

Note the following:

Siemens products may only be used for the applications described in the catalog and in the relevant technical documentation. If products and components from other manufacturers are used, these must be recommended or approved by Siemens. Proper transport, storage, installation, assembly, commissioning, operation and maintenance are required to ensure that the products operate safely and without any problems. The permissible ambient conditions must be complied with. The information in the relevant documentation must be observed.

Trademarks

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Disclaimer of Liability

We have reviewed the contents of this publication to ensure consistency with the hardware and software described. Since variance cannot be precluded entirely, we cannot guarantee full consistency. However, the information in this publication is reviewed regularly and any necessary corrections are included in subsequent editions.

Preface

Purpose of the operating instructions

These operating instructions contain all the information you need for commissioning and operating the SIMATIC IPC677D.

It is intended both for programming and testing personnel who commission the device and connect it with other units (automation systems, programming devices), as well as for service and maintenance personnel who install add-ons or carry out fault/error analyses.

Basic knowledge required

A solid background in personal computers and Microsoft operating systems is required to understand this manual. General knowledge in the field automation control engineering is recommended.

Scope of the operating instructions

These operating instructions apply to devices with the following order numbers 6AV7260.....

Scope of the documentation

The documentation for the IPC includes the following:

- SIMATIC IPC677D Quick Install Guide with product information about the device, for example important notes
- SIMATIC IPC677D operating instructions

The documentation is supplied with the IPC in German and English in electronic form as a PDF file on the Documentation and Drivers CD/DVD.

Conventions

In these operating instructions, the term "device" is also used to refer to the "SIMATIC IPC677D".

The SIMATIC IPC677D consists of an operator panel with touch screen and a SIMATIC IPC627D computer unit. In these operating instructions, you also find descriptions and illustrations of the SIMATIC IPC627D which apply to the SIMATIC IPC677D.

"CP" is used as an abbreviation for "CP 1616 onboard" (for PROFINET) or "CP 5622" (for PROFIBUS).

In these operating instructions, "Windows Embedded Standard" is also used as a standard term for "Windows Embedded Standard 7". "Windows 7" is used as an abbreviation for "Windows 7 Ultimate".

A touch device generally refers to a device with a capacitive touch screen or a resistive touch screen. Touch screen is the general term for a capacitive multi-touch screen and resistive single touch screen.

Note

A note is important information about the product, handling the product or a reference to specific sections of the documentation that require special consideration.

History

The following editions of these operating instructions have already been published:

| Edition | Comments | |
|---------|---|--|
| 12/2013 | First edition | |
| 06/2014 | 06/2014 Description of devices with capacitive multi-touch screen | |
| 09/2014 | 09/2014 Revision: HDD in a removable drive bay and RAID | |
| | Update with IPC Wizard 2.1 and corrections | |
| 06/2019 | Revision: Power supply, Windows 10 | |

See also

Technical specifications (Page 131) Certificates and approvals (Page 117)

Table of contents

| | Preface. | | |
|---|--|---|----------------|
| 1 | Overview | Overview | |
| | 1.1 1.1.1 1.1.2 | Product description Applications Features | 12 |
| | 1.2 1.2.1 1.2.2 1.2.3 | Design of the device Operator controls and interfaces Status displays PROFINET status displays | 16 18 |
| | 1.3 | Accessories | 20 |
| 2 | Safety in | structions | |
| | 2.1 | General safety instructions | 21 |
| | 2.2 | Notes on usage | 25 |
| 3 | Mounting | Mounting and connecting the device | |
| | 3.1 3.1.1 3.1.2 3.1.3 3.1.4 | Preparing for mounting Checking the delivery package Device identification data Permitted mounting positions Preparing the mounting cutout | 27 29 31 |
| | 3.2 3.2.1 3.2.2 3.2.3 3.2.4 3.2.5 | Mounting the device Installation guidelines Mounting clips or mounting brackets, position for IP65 Mounting the device with mounting clips Mounting the device with mounting brackets Position of the mounting clips for IP66-complaint installation | |
| | 3.3 3.3.1 3.3.2 3.3.3 3.3.4 3.3.5 3.3.6 3.3.6 3.3.7 3.3.8 | Connecting the device Wiring information Connecting the Equipotential Bonding Circuit Connecting 100-240 VAC power supply. Connecting the 24 VDC power supply. Connecting peripheral equipment Connecting the device to networks. PROFINET Connecting Ethernet/USB strain relief. | |
| | 3.3.9 | Connecting the PROFINET strain relief | 54 |

| 4.1 4.2 4.3 | Notes on commissioning and operation Switching on the device | |
|--|---|--|
| | Switching on the device | |
| 1.3 | 8 | 56 |
| | Automatic switching on of the device | 57 |
| 1.4 | Windows Action Center | 57 |
| 4.5 4.5.1 4.5.2 | Notes on different device configurations RAID1 system (optional) Notes on the DVD burner | 58 |
| 4.6 | Switching off the device | 61 |
| Operating the device and device functions | | 62 |
| 5.1 | Operator input options | 62 |
| 5.2 | Operating a device with resistive single touch screen | 63 |
| 5.3 | Operating a device with capacitive multi-touch screen | |
| 5.4 | IPC Wizard functions | |
| 5.5 5.5.1 5.5.1.2 5.5.1.3 5.5.1.4 5.5.2 5.5.3 5.5.4 5.5.5 5.5.6 | Active Management Technology (AMT) | |
| Expanding t | he device and assigning device parameters | |
| 6.1 | Opening the Device | |
| 6.2 | Expanding memory | |
| 5.3 5.3.1 5.3.2 | Notes on the expansion cards | 81 |
| 5.4 5.4.1 5.4.2 5.4.3 5.4.4 5.4.5 | Installation options for internal drives | |
| | 5.4 5.5 5.6 xpanding t 1 2 3 3.1 3.2 4 4.1 4.2 4.3 4.3 4.4 | 5.4 Buffer memory SRAM (optional) |

| 7 | Maintaining and servicing your device | | |
|---|---------------------------------------|--|-----|
| | 7.1 | Maintenance | 91 |
| | 7.2 7.2.1 7.2.2 | Managing RAID systems Example for a RAID1 system during the boot phase of the system RAID software | 91 |
| | 7.2.2 | Checking the status of the RAID system | |
| | 7.2.4 | Displaying a defective hard disk of a RAID system in the RAID software | |
| | 7.2.5 | Special feature: Replacing hard disk in the RAID system when switched off | |
| | 7.2.6 | Integrating a new hard disk drive in the RAID system | |
| | 7.3 | Service and spare parts | 97 |
| | 7.4 | Cleaning the Device Front | 99 |
| | 7.5 | Separating the control unit from the computer unit | 100 |
| | 7.6 | Connecting the control unit with the computer unit | 102 |
| | 7.7 | Removing and installing hardware | 104 |
| | 7.7.1 | Replacing a defective hard disk drive in the RAID system | 104 |
| | 7.7.2 | Removing and installing the hard disk in the removable drive bay | 105 |
| | 7.7.3 | Replacing the Backup Battery | |
| | 7.7.4 | Removing and installing the power supply | |
| | 7.7.5 | Removing and installing the bus board | |
| | 7.7.6 | Removing and installing the power supply fan | |
| | 7.7.7 | Removing and installing the device fan | |
| | 7.7.8 | Replacing the processor | |
| | 7.8 | Recycling and disposal | |
| | 7.9 | Installing operating system, software and drivers | |
| | 7.9.1 | Installing the operating system | |
| | 7.9.2 | Installing software and drivers | 116 |
| 8 | Technical information | | |
| | 8.1 | Certificates and approvals | 117 |
| | 8.1.1 | KC Mark (Korea) | 119 |
| | 8.2 | Directives and declarations | |
| | 8.2.1 | CE marking | 120 |
| | 8.2.2 | ESD guideline | |
| | 8.3 | Dimension drawings | |
| | 8.3.1 | Dimension drawing of 15" device with capacitive multi-touch screen | |
| | 8.3.2 | Dimension drawing of 19" device with capacitive multi-touch screen | |
| | 8.3.3 | Dimension drawing of 22" device with capacitive multi-touch screen | |
| | 8.3.4 8.3.5 | Dimension drawing of 15" device with resistive single touch screen Dimension drawing of 19" device with resistive single touch screen | |
| | 8.3.6 | Dimension drawing of 22" device with resistive single touch screen | |
| | 8.3.7 | Dimensional drawing for the installation of expansion cards | |
| | | | |

| 8.4 8.4.1 8.4.2 8.4.3 8.4.4 8.4.5 | Technical specifications General technical specifications Ambient conditions Current and power requirements AC voltage supply DC power supply. | 131 135 136 137 |
|---|--|--|
| 8.5 8.5.1 8.5.1.1 8.5.1.2 8.5.1.3 8.5.1.4 8.5.2 8.5.2.1 8.5.2.1 8.5.2.2 | Hardware descriptions Motherboard Structure and functions of the motherboard Position of the interfaces on the motherboard Internal interfaces Front ports Bus board Layout and principle of operation PCI slot pin assignment | 140 140 141 142 144 145 145 |
| 0.3.2.2 8.5.2.3 8.5.2.4 8.5.3 8.5.3.1 8.5.3.2 8.5.3.3 8.5.3.4 8.5.3.5 8.5.3.6 | PCI slot pin assignment Pin assignment 12 V power supply connection for expansion cards PCI Express slot x16 pin assignment External ports COM1/COM2 DisplayPort DVI-I Ethernet USB 3.0 PROFIBUS | 148 149 151 151 152 153 154 154 |
| 8.5.3.7 8.5.4 8.5.4.1 8.5.4.2 8.5.5 8.5.6 8.5.6.1 8.5.6.2 8.5.6.3 8.5.6.3 8.5.6.4 | PROFINET System resources Currently allocated system resources System resources used by the BIOS/DOS Assignment of expansion interfaces to the software in the TIA Portal (CP assignment) CP 1616 onboard communications processor Properties Typical Communication Partners Firmware Loader Further actions in STEP 7/NCM PC | 156 156 156 163 164 164 165 167 |
| 8.6 8.6.1 8.6.2 8.6.3 8.6.4 8.6.5 8.6.6 8.6.7 | BIOS description Overview Opening the BIOS selection menu Configuration Exit menu General BIOS Setup settings BIOS update Alarm, error and system messages | 170 170 171 173 175 176 181 |

| | 8.7 | Active Management Technology (AMT) | |
|---|---------------------------------------|---|-----|
| | 8.7.1 | | |
| | 8.7.2 | Overview of AMT | |
| | 8.7.3 | Enabling Intel® AMT / basic configuration. | |
| | 8.7.4 8.7.5 | Resetting the Intel® AMT to the default settings and disabling AMT Determining the network address | |
| | 8.7.6 | Forcing user consent | |
| | 8.8 | Functional scope in Windows | |
| | 8.8.1 | Windows Embedded Standard 7 Professional | |
| Α | Technical support | | 190 |
| | A.1 | Service and support | 190 |
| | A.2 | Troubleshooting | 191 |
| в | Meaning of the symbols on your device | | |
| | B.1 | Meaning of the symbols on your device | 194 |
| | B.2 | Safety | 194 |
| | B.3 | Operator controls | 194 |
| | B.4 | Certificates, approvals and markings | 195 |
| | B.5 | Interfaces | 196 |
| | B.6 | Directives and declarations | 197 |
| С | List of abbreviations | | 198 |
| | C.1 | Abbreviations | 198 |
| | Glossary | | 204 |
| | Index | | 212 |

Overview

1.1 Product description

Devices with capacitive multi-touch screen



Devices with resistive single touch screen



Features

The SIMATIC IPC677D provides high-level industrial functionality.

- Compact design
- Maintenance-free operation
- Rugged

The color display is equipped with TFT technology in widescreen format and LED backlighting.

Device with a resistive single touch screen comes with a front-side USB port for connection of external peripheral devices.

Device variants

The delivery note contains information on the precise scope of functions and product package for your device.

The SIMATIC IPC677D is available in the following device variants, which differ in regard to the display size, operating method and optional expansions.

Devices with capacitive multi-touch screen

- Display:
 - 15" display, resolution 1366 × 768 pixels
 - 19" display, resolution 1366 × 768 pixels
 - 22" display, resolution 1920 × 1080 pixels

Devices with resistive single touch screen

- Display:
 - 15" display, resolution 1280 × 800 pixels
 - 19" display, resolution 1366 × 768 pixels
 - 22" display, resolution 1920 × 1080 pixels

Operating systems

The following operating systems are approved for the devices:

- Windows 7 Ultimate (32/64-bit)
- Windows Embedded Standard 7 P (32/64-bit)

1.1 Product description

1.1.1 Applications

The device are available for industrial PC systems for high-performance and space-saving applications in particular in the field of machine, plant and control cabinet engineering:

- Measuring and controlling process and machine data, for example, automated washing systems, assembling machines and packaging machines
- Operating and visualization tasks, for example, information terminals and large-scale displays in automobile manufacturing
- Data logging and processing, for example, system data logging and distributed process control

1.1.2 Features

| Basic data | | |
|--------------------------------|---|--|
| Installation | In control cabinet | |
| Processor | Intel Xeon E3-1268L v3 2.3 (3.3) GHz, 4 cores, GT2, 8 MB cache, HT, AMT | |
| | • Intel Core i3-4330TE 2.4 GHz, 2 cores, GT2, 3 MB cache | |
| | • Intel Celeron G1820TE 2.2 GHz, 2 cores, GT1, 2 MB cache | |
| Main memory | Maximum memory configuration 16 GB with the following memory modules: | |
| | without ECC: | |
| | 2 GB DDR3 SDRAM | |
| | 4 GB DDR3 SDRAM | |
| | 8 GB DDR3 SDRAM | |
| | with ECC: | |
| | 4 GB DDR3 ECC | |
| | 8 GB DDR3 ECC | |
| Equipment options with ex- | • 2 × PCI | |
| pansion cards | • 1 × PCI, 1 × PCIe x16 Gen3 | |
| | • 1 × PCle x4 Gen2, 1 × PCle x16 Gen3 | |
| Maximum bandwidth of PCI slots | 133 Mbps | |
| Maximum bandwidth of PCI | Gen 2: 5 GT/s (500 Mbps) bandwidth per lane | |
| slots | Gen 3: 8 GT/s (985 Mbps) bandwidth per lane | |

1.1 Product description

| Basic data | | |
|---|--|--|
| Graphics | Intel® HD Graphics Controller P4600/4700 GT1/GT2 2D and 3D engine integrated in chipset Dynamic Video Memory Technology (requires up to 512 MB in main memory) DVI/VGA resolution up to 1920 × 1200 pixels Graphics memory is claimed in main memory (dynamic UMA) Triple Head Mode | |
| | DisplayPort resolutions depend on the graphics controller in the CPU, which is represented by the processor: | |
| | Celeron G1820TE: GT1 (HD Graphics), maximum resolutions up to 2560 × 1600 | |
| | Core I3-4330TE: GT2 (HD Graphics 4600), maximum resolutions up to 3840 × 2160 | |
| | XEON E3-1268L v3: GT2 (HD Graphics 4600) maximum resolutions up to 3840 × 2160 | |
| Power supply | • 120 V / 230 VAC, 190 W; wide range | |
| | • 24 VDC, 210 W | |
| | AC and DC power supply with short-term power failure backup in accordance with NAMUR: maximum of 20 ms at 0.85 rated voltage. | |
| The 24 VDC power supply is protected against reverse p nection. | | |
| Drives and storage media | | |
| Hard disk | • 1 × 3.5" ≥ 500 GB, SATA | |
| | 2 × 2.5" ≥ 250 GB, SATA only with RAID1 system for automatic data mirroring on two hard disks | |
| SSD (Solid State Disk) | 2.5" ≥ 240 GB Standard | |
| USB stick | External, can be connected via USB port | |
| DVD drive | DVD burner (slimline), optional | |
| | • DVD+/-R/RW, CD, CD-RW, DVD-RAM | |
| | Double layer functionality | |

1.1 Product description

| Basic data | | |
|--------------|--|--|
| Interfaces | | |
| Ethernet | 2 × 10/100/1000 Mbps, (2 x RJ45) | |
| | Wake on LAN, Remote Boot and teaming are supported: | |
| PROFIBUS/MPI | 12 Mbps, electrically isolated, compatible with CP 5622, optional | |
| PROFINET | 3 × 10/100 bps, CP 1616 on-board, RJ45, optional | |
| USB | Front: 1 × USB 3.0 high current | |
| | (only for devices with resistive single touch screen) | |
| | • External: 4 × USB 3.0 high current | |
| | (a maximum of 2 can be operated as high current at the same time) | |
| | • External, optional: 1 × USB 2.0 high current, 1 × low current | |
| | Internal: 1 × USB 3.0 high current for internal USB stick/dongle | |
| СОМ | Serial V.24 port | |
| COM2/LPT | optional | |
| Monitor | • 1 x DVI-I (VGA monitors can be connected with a DVI/VGA adapter acquired separately) | |
| | 1 x DisplayPort | |

| Software | |
|-------------------|---|
| Operating systems | Without |
| | Windows 7 Ultimate 32-bit ^{1, 2} |
| | • Windows 7 Ultimate 64-bit ^{1, 2} |
| | Windows Embedded Standard 7 Professional 32-bit³ |
| | • Windows 10 Enterprise 2016 LTSB 64-bit ^{1, 4, 5} |
| | Windows 10 Enterprise IoT 2015 LTSB 64-bit ^{1, 4, 5} |

¹ MUI: Multi-language user interface; English, German, French, Italian, Spanish

² Pre-installed / Recovery and Restore DVD enclosed

³ Pre-installed on SSD ≥80 GB / Restore DVD enclosed.

⁴ Pre-installed or included on USB flash drive

⁵ Activation is not absolutely necessary for full functionality of Windows. Activation occurs automatically as soon as the IPC has been connected to the Internet and was able to connect to the Microsoft activation servers.

| Optional software | |
|---|--|
| SIMATIC IPC DiagMonitor V5.0.2 or higher | Software tool for local as well as remote monitoring of SIMATIC PCs: |
| | Watchdog |
| | Temperature |
| | Fan speed |
| | Hard disk monitoring (SMART) |
| | Communication: |
| | Ethernet interface (SNMP protocol) |
| | OPC for integrating in SIMATIC software |
| | Client server architecture |
| | Structure of log files |
| SIMATIC IPC Image & Partition Crea- tor V3.5.1 or higher | Software tool for local data backup and hard disk parti- tioning |

1.2 Design of the device

1.2 Design of the device

1.2.1 Operator controls and interfaces

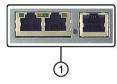
Device with PROFIBUS interface

| | 2 |) (3) (4) | |
|-------------|--|---|--|
| | | | |
| | 1 | | |
| 1 | PROFIBUS DP/MPI fieldbus | PROFIBUS DP/MPI interface (RS 485, isolated), 9-pin sub D socket | |
| 2 | On/off switch | You switch on the device with the on/off switch. This requires that the BIOS setup entry "After Power Failure" is set to "Power On". The on/off switch does not isolate the device from the power supply. Position "ON", when the "-)" symbol is pressed inward on the device. | |
| 3 | 100-240 VAC | Position "OFF" is the factory state. Power supply connection | |
| 4 | 2 × Ethernet | X1P1, left: RJ45 Ethernet port 1 (exclusive PCI interrupt) with 10/100/1000 Mbps, iAMT capable X2P1, right: RJ45 Ethernet port 2 (shared PCI interrupt) with 10/100/1000 Mbps | |
| 6 7 9 | 4 × USB COM1 DisplayPort DVI-I PCI/PCIe expansion cards, COM2/LPT and USB on expansion card (optional) | USB 3.0 high current, backward compatible with USB 2.0/1.1 Serial interface DisplayPort connection for digital monitor DVI connector for CRT or LCD monitor with DVI port behind the cover | |

| ① On/off button | The on/off button has three functions: |
|-------------------|--|
| | Switch on the PC: Briefly press once |
| | Shut down operating system and switch off PC: Briefly press once |
| | • Switch off PC without shutting down the operating system (hardware reset): Press for more than 4 seconds. |
| | Note: The BIOS setup entry "After Power Failure" has been set to "Power On". This means the device is switched on with the on/off switch. You then do not need to press the on/off button. |
| (1) 4 status LEDs | Status display of the operating state |

Device with PROFINET interface

The following PROFINET interface is located at the position of the PROFIBUS interface 1 in the figure above:



① CP 1616 onboard interface, three RJ45 sockets for devices with PROFINET, IRT capable

Device with COM2/LPT and USB expansion (optional)

The following expansion cards are located at the position of the cover (9) in the figure above:



Devices with resistive single-touch screen

Note

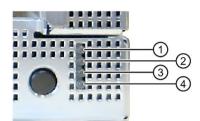
If you open the sealed cover for the front USB port, the degree of protection IP65 for the front of the device is no longer guaranteed.

Overview

1.2 Design of the device

1.2.2 Status displays

The status display consists of four two-colored LEDs.



| Position | LED | State | Description |
|----------|---------------|---------------------------------|--|
| 1 | PC ON/WD | Off | - |
| Ũ | | Green | BIOS ready to boot |
| | | Flashing green/yellow (1 Hz) | BIOS in POST, power switch on |
| | | Yellow | Idle state |
| | | Flashing red (1 Hz) | Watchdog status display: active |
| 2 | RUN/STOP / L1 | Off | - |
| | | Green | Can be controlled by user program |
| | | Yellow | Can be controlled by controller program (e.g. WinAC) |
| 3 | ERROR / L2 | Off | - |
| Ū | | Red | - |
| | | Flashing red | Can be controlled by user program or controller program (e.g. WinAC) |
| 4 | MAINT / L3 | Off | - |
| | | Yellow | - |
| | | Red | Can be controlled by controller program (e.g. WinAC) |

For additional information on controlling the LEDs or the SRAM with a Windows operating system, please refer to the chapter "Buffer memory SRAM (optional) (Page 75)". Example programs for controlling the LEDs under Windows operating systems is available on the Internet at the following address: Technical support (https://support.industry.siemens.com/cs/ww/en/)

1.2.3 PROFINET status displays

| PROFINET status display | | | |
|---------------------------------|---------------------------------------|----------------------|--|
| |] | | |
| Display | Meaning | LED | Description |
| ① SF PROFINET, op- tional | Status display for CP 1616 onboard | OFF Slow flashing | CP not available CP disabled No error, communication established Download in progress Link status error IO controller: IO device cannot be addressed IO controller: Duplicate IP address |
| | | Fast flashing | Exception error: Diagnostics via Web or SNMP no longer possible |
| | | AN | Diagnostic information availa- ble |
| | | | No communication estab- lished. |

| Virtual status displays | | | |
|--|--------------|---------|--|
| The two "virtual" CP 1616 LEDs can only be seen in the SIMATIC software and can be scanned via SNMP. | | | |
| PROFINET | Virtual LEDs | RUN | CP is active |
| | | STOP | CP is in the stop state |
| | | Flashes | There are no "slow flashing" or "fast flashing" states. |

See also

Industry Automation and Drive Technologies - Homepage (http://www.siemens.com/automation/service&support)

1.3 Accessories

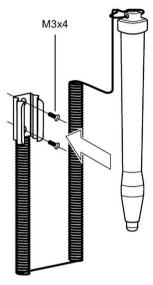
1.3 Accessories

Accessories are available for your device. These are not included in the product package. You can find Information on available accessories on the Internet at:

- Industry Mall (https://mall.industry.siemens.com)
- Expansion components and accessories (<u>http://www.automation.siemens.com/mcms/pc-based-automation/en/industrial-pc/expansion_components_accessories</u>)

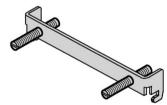
Other accessories

• Touch stylus for devices with resistive single touch screen



• Mounting bracket

If there are strict requirements for the front seal, fasten the device in a cabinet with mounting brackets.



Safety instructions

2.1 General safety instructions

Life-threatening voltages are present with an open control cabinet

When you install the device in a control cabinet, some areas or components in the open control cabinet may be carrying life-threatening voltages.

If you touch these areas or components, you may be killed by electric shock.

Switch off the power supply to the cabinet before opening it.

System expansions

NOTICE

Damage through system expansions

Device and system expansions may be faulty and can affect the entire machine or plant.

The installation of expansions can damage the device, machine or plant. Device and system expansions may violate safety rules and regulations regarding radio interference suppression. If you install or exchange system expansions and damage your device, the warranty becomes void.

Note the following for system expansions:

- Only install system expansion devices designed for this device. Contact your technical support team or where you purchased your PC to find out which system expansion devices may safely be installed.
- Observe the information on electromagnetic compatibility (Page 120).

NOTICE

"Open Type" UL508

Note that the device is classified as "Open Type" for use in the area of Industrial Control Equipment (UL508). Installation of the device in an enclosure complying with UL508 for specific permitted mounting positions (see corresponding section) is a prerequisite for approval or operation in accordance with UL508.

2.1 General safety instructions

Risk of fire through expansion cards

Expansion cards generate additional heat. The device may overheat and cause a fire.

Please note the following:

- Observe the safety and installation instructions for the expansion cards.
- If in doubt, install the device in an enclosure that is compliant with sections 4.6 and 4.7.3 of the IEC/EN/DIN-EN 60950-1 standard.

Battery and rechargeable battery

Risk of explosion and release of harmful substances

Improper handling of lithium batteries can result in an explosion of the batteries.

Explosion of the batteries and the released pollutants can cause severe physical injury. Worn batteries jeopardize the function of the device.

Note the following when handling lithium batteries:

- Replace used batteries in good time; see the section "Replacing the backup battery" in the operating instructions.
- Replace the lithium battery only with an identical battery or types recommended by the manufacturer (order no.: A5E00331143).
- Do not throw lithium batteries into fire, do not solder on the cell body, do not recharge, do not open, do not short-circuit, do not reverse polarity, do not heat above 100°C and protect from direct sunlight, moisture and condensation.

High frequency radiation

NOTICE

Unintentional operating situations

High frequency radiation, e g. from a cellular phone, interferes with device functions and can result in malfunctioning of the device.

Persons are injured and the plant is damaged.

Avoid high-frequency radiation:

- Remove radiation sources from the environment of the device.
- Switch off radiating devices.
- Reduce the radio output of radiating devices.
- Observe the information on electromagnetic compatibility (Page 120).

ESD Guideline



Electrostatic sensitive devices can be labeled with an appropriate symbol.

NOTICE

Electrostatic sensitive devices (ESD)

When you touch electrostatic sensitive components, you can destroy them through voltages that are far below the human perception threshold.

If you work with components that can be destroyed by electrostatic discharge, observe the ESD Guideline (Page 121).

Industrial Security

Siemens provides products and solutions with industrial security functions that support the secure operation of plants, systems, machines and networks.

In order to protect plants, systems, machines and networks against cyber threats, it is necessary to implement – and continuously maintain – a holistic, state-of-the-art industrial security concept. Siemens' products and solutions constitute one element of such a concept.

Customers are responsible for preventing unauthorized access to their plants, systems, machines and networks. Such systems, machines and components should only be connected to an enterprise network or the internet if and to the extent such a connection is necessary and only when appropriate security measures (e.g. firewalls and/or network segmentation) are in place.

For additional information on industrial security measures that may be implemented, please visit.

Siemens' products and solutions undergo continuous development to make them more secure. Siemens strongly recommends that product updates are applied as soon as they are available and that the latest product versions are used. Use of product versions that are no longer supported, and failure to apply latest updates may increase customer's exposure to cyber threats.

To stay informed about product updates, subscribe to the Siemens Industrial Security RSS Feed under.

Disclaimer for third-party software updates

This product includes third-party software. Siemens AG only provides a warranty for updates/patches of the third-party software, if these have been distributed as part of a Siemens software update service contract or officially released by Siemens AG. Otherwise, updates/patches are undertaken at your own risk. You can find more information about our Software Update Service offer on the Internet at Software Update Service (http://www.automation.siemens.com/mcms/automation-software/en/software-update-service).

2.1 General safety instructions

Notes on protecting administrator accounts

A user with administrator privileges has extensive access and manipulation options in the system.

Therefore, ensure there are adequate safeguards for protecting the administrator accounts to prevent unauthorized changes. To do this, use secure passwords and a standard user account for normal operation. Other measures, such as the use of security policies, should be applied as needed.

See also

Industrial security (<u>http://www.siemens.com/industrialsecurity</u>) Technical support (https://support.industry.siemens.com/cs/ww/en/)

2.2 Notes on usage

NOTICE

Possible functional restrictions in case of non-validated plant operation

The device is tested and certified on the basis of the technical standards. In rare cases, functional restrictions can occur during plant operation.

Validate the correct functioning of the plant to avoid functional restrictions.

Environment

NOTICE

Ambient conditions and chemical resistance

Unsuitable environmental conditions have a negative impact on device operation. Chemical substances such as cleaners or fuels may alter the color, shape and structure of the device surface, for example, the front panel.

The device may be damaged. possibly resulting in malfunctions.

For this reason, please observe the following precautions:

- Always operate the device in closed rooms. All warranties shall be void in the case of noncompliance.
- Operate the device only in accordance with the ambient conditions specified in the technical specifications.
- Protect the device against dust, moisture and heat.
- Do not expose the device to direct sunlight or to other strong sources of light.
- Without additional safety measures, such as a supply of clean air, the device may not be used in locations with harsh operating conditions caused by acidic vapors or gases.
- Always use suitable cleaning agents. Read the information about Chemical resistance of the HMI devices and industrial PCs (https://support.industry.siemens.com/cs/ww/en/view/39718396) on the Internet.

Note

Use in an industrial environment without additional protective measures

The device has been designed for use in a normal industrial environment in accordance with IEC 60721-3-3 (pollutant class 3C2 for chemical influences, 3S2 for dust without contamination by sand).

2.2 Notes on usage

TFT displays

NOTICE

Burn-in effect and backlighting

A permanent picture with bright screen objects leads to a burn-in effect. The longer the same screen contents are displayed, the longer it will take for the burn-in effect to disappear. Screen savers reduce the risk of burn-in. The brightness of the backlighting deteriorates over the course of the screen's life cycle.

Use the "BbcScreenSaver" to extend the life of the screen and the backlighting.

Defective pixels in the display

At present, the manufacturing process of modern displays does not guarantee that all pixels of the display will be perfect. A small number of defective pixels in the display is therefore unavoidable. This does not present a functional problem as long as the defective pixels are not bunched in one location.

Additional information is available in the section "General technical specifications (Page 131)".

Mounting and connecting the device

3.1 Preparing for mounting

3.1.1 Checking the delivery package

Procedure

- 1. When accepting a delivery, please check the packaging for visible transport damage.
- 2. If any transport damage is present at the time of delivery, lodge a complaint at the shipping company in charge. Have the shipper confirm the transport damage immediately.
- 3. Unpack the device at its installation location.
- 4. Keep the original packaging in case you have to transport the unit again.

Note

Damage to the device during transport and storage

If a device is transported or stored without packaging, shocks, vibrations, pressure and moisture may impact the unprotected unit. Damaged packaging indicates that ambient conditions have already had a massive impact on the device and it may be damaged.

This may cause the device, machine or plant to malfunction.

- Keep the original packaging.
- Pack the device in the original packaging for transportation and storage.
- 5. Check the contents of the packaging and any accessories you may have ordered for completeness and damage.

3.1 Preparing for mounting

 Please inform the delivery service immediately if the package contents are incomplete or damaged or do not correspond with your order. Fax the enclosed form "SIMATIC IPC/PG Quality Control Report".

Electric shock and fire hazard due to damaged device

A damaged device can be under hazardous voltage and trigger a fire in the machine or plant.

A damaged device has unpredictable properties and states.

Death or serious injury could occur.

- Avoid installing and commissioning a damaged device.
- Label the damaged device and keep it locked away.
- Send off the device for immediate repair.

NOTICE

Damage from condensation

If the device is subjected to low temperatures or extreme fluctuations in temperature during transportation, as is the case in cold weather, for example, moisture can build up on or inside the device (condensation).

Moisture causes a short circuit in electrical circuits and damages the device.

In order to prevent damage to the device, proceed as follows:

- Store the device in a dry place.
- Bring the device to room temperature before starting it up.
- Do not expose the device to direct heat radiation from a heating device.
- If condensation develops, wait approximately 12 hours or until the device is completely dry before switching it on.
- 7. Please keep the enclosed documentation in a safe place. It belongs to the device. You need the documentation when you commission the device for the first time.
- 8. Write down the identification data of the device.

3.1.2 Device identification data

Unpacking the device

The device can be clearly identified with the help of this identification data in case of repairs or theft.

Enter the identification data in the table below:

| Identification date | Source | Value |
|---|-------------------------|---|
| Serial number | Rating plate | S VP |
| Order number of the device | Rating plate | 6AV7260 |
| Microsoft Windows Product Key Certificate of Authenticity (COA) | Back of the de- vice | Only devices with preinstalled Windows operating systems have the COA label |
| Ethernet address 1 | BIOS setup, | |
| Ethernet address 2 | "Main" menu | |
| CP 1616 onboard MAC Address Layer 2 (only for PROFINET devices) | | |
| CP 1616 onboard MAC address PROFINET (only for PROFINET devices) | | |

Rating plate

SIEMENS

| SIMATIC IP | C677D | ONBOARD MAC-ADI ETHERNET LAN: ETHERNET LAN: | RESSES: 08:0A:11:52:11:01 08:0A:11:52:11:01 | - | FS RS AA |
|--|----------------------------------|---|--|----|-------------|
| 1P | 6AV7260-XXXXX-XXXX VPN1900001 | 1PCI AND 1PCEe (x16 2x250GB HDD SATA 4GB DDR3 SDRAM E AC 100/240V INDUST MAINBOARD CV6, CI Windows 7 Ultimate Panel 22" Touch USB | DVD+/RW CC (2x2GB) RIAL PS WITH NAMUR ORE i3, 2,4Ghz PB MUI, | AE | ND |
| THIS DEVICE COMPLES WITH PART IS OF THE FCC RULES. OPERATION IS SUBJECT TO THE FOLLOWING TWO CONDITIONS: UTILINS DEVICE MAY ROLE USES HAMMUNU. INTERFERENCE, AND RULES ACCEPT ANY INTERFERENCE, AND RULE RULE WITH CARADACCEPT ANY INTERFERENCE AND RULE WITH CARADACUSE ACCEPT ANY INTERFERENCE ACCEPT ANY INTERFERENCE AND RULE WITH CARADACUSE ACCEPT ANY INTERFERENCE AND RULE WITH CARADACUS ACCEPT ANY INTERFERENCE AND RULE WITH AND RULE WITH AND RULE WITH AND RULE WITH ANY ACCEPT ANY INTERFERENCE AND RULE WITH ANY ACCEPT ANY INTERFERENCE AND RULE WITH AND RULE WITH AND RULE WITH AND RULE WITH ANY ACCEPT ANY ACCEPT ANY ACCEPT ANY ACCEPT ANY ACCEPT ANY ACCEPT ANY | | | <u>∧</u> €€ | | |
| | | | emberg | | |
| Made in Germany | | | | | |

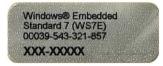
3.1 Preparing for mounting

COA label

Microsoft Windows "Product Key" from the "Certificate of Authenticity" (COA):

The COA label is present only when Windows Embedded Standard 7 or Windows 7 is installed.

• COA label of a device with the Windows Embedded Standard 7 operating system



• COA label of a device with the Windows 7 operating system



3.1.3 Permitted mounting positions

The following mounting positions are permitted for the device.

For information on the maximum permissible ambient temperatures during operation, refer to section "Ambient conditions (Page 135)".

Mounting positions according to UL508/EN60950-1

Points to note with expansion cards

Expansion cards may impose restrictions on the installation location (fire-proof enclosure) and permitted mounting positions (see Technical specifications). If the device has been fitted with expansion cards, please observe the safety and installation instructions for the expansion cards in the corresponding documentation.

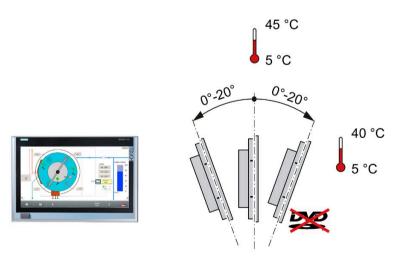
If in doubt, install the device in an enclosure that is compliant with sections 4.6 and 4.7.3 of IEC/EN/DIN EN 60950-1.

NOTICE

Operation in closed rooms

The device is approved for operation in closed rooms only. Pay attention to the ambient and environmental conditions.

Mounting in horizontal format



Note

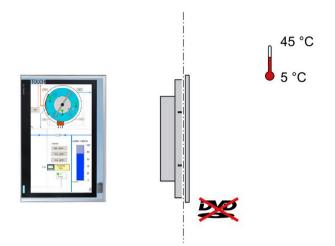
Mounting precautions

- The total power for USB and PCI/PCIe expansions cannot exceed 30 W.
- Operation of a DVD drive in the inclined position is not permitted.

3.1 Preparing for mounting

Additional mounting positions according to UL508/CSA 22.2 No. 142

Mounting in vertical format



NOTICE

CD/DVD operation not permitted with mounting in vertical format

CD/DVD drives must not be operated in this position. The CD drawer opens downward; this can lead to damage to the drawer mechanics.

Note

Mounting precautions

• The total power for USB and PCI/PCIe expansions cannot exceed 30 W.

Note

This mounting position is also permitted for Information Technology Equipment if the device is mounted in an enclosure that complies with the requirements of sections 4.6 and 4.7.3 of IEC/EN/DIN EN 60950-1.

3.1.4 Preparing the mounting cutout

Note

Stability of the mounting cutout

The material in the area of the mounting cutout must provide sufficient strength to guarantee the enduring and safe mounting of the HMI device.

The force of the clamps or operation of the device may not lead to deformation of the material in order to achieve the degrees of protection described below.

Note

Read the information in the section "Installation guidelines (Page 35)".

Requirements for complying with degree of protection

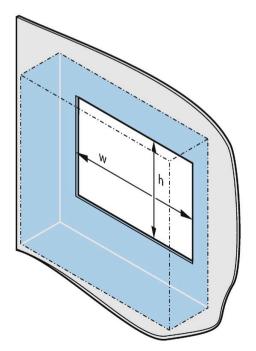
The degree of protection of the HMI device can only be guaranteed if the following requirements are met:

- Material thickness at the mounting cutout for IP65 degree of protection, or for enclosure type 4X/type 12 (indoor use only): 2 mm to 6 mm
- Permitted deviation from plane at the mounting cutout: ≤ 0.5 mm

This condition must be fulfilled for the mounted HMI device.

• Permissible surface roughness in the area of the seal: \leq 120 µm (R_z 120)

Dimensions of the mounting cutout



3.1 Preparing for mounting

| Mounting cutout | 15" ² | 15" ³ | 19" | 22" |
|-----------------------|------------------|------------------|--------|--------|
| Width w ¹ | 399 mm | 396 mm | 465 mm | 542 mm |
| Height h ¹ | 280 mm | 291 mm | 319 mm | 362 mm |

¹ Width and height must be interchanged for mounting in vertical format.

² Device with capacitive multi-touch screen

³ Device with resistive single-touch screen

Installation depth

Information on the overall depth is available in the section "Dimension drawings (Page 124)".

3.2 Mounting the device

3.2.1 Installation guidelines

Requirements for a fire protection enclosure according to EN 60950-1 only for standard mounting position

In the standard installation position and in the inclined position in horizontal format with vertical inclination of max. ±20°, the device meets the requirements for fire protection enclosures according to EN 60950-1 and can therefore be installed without an additional fire protection covering. For information on the mounting positions, refer to section "Permitted mounting positions (Page 31)".

NOTICE

Risk of fire

If you install the device in an unapproved mounting position or if you do not observe the ambient conditions, the device can overheat.

Overheating can cause a fire. Proper functioning of the device is no longer guaranteed.

Before you install the device, note the following general installation information.

- Install the device only in one of the permitted mounting positions.
- Note the climatic and mechanical ambient conditions (Page 135).
- The device was designed for use in a normal industrial environment. The SIMATIC PC cannot be operated in difficult operating environments which are subject to caustic vapors or gases without taking additional protective measures (such as the provision of clean air).
- For installation in control cabinets, note the SIMATIC setup guidelines as well as the relevant DIN/VDE requirements or the country-specific regulations.
- The ventilation slots of the device may not be covered or obstructed.
- Equip the control cabinet with struts for stabilizing the mounting cut-out. Install struts where necessary.
- The device with AC power supply meets the requirements for fire protection enclosures according to EN 60950-1 and can therefore be installed without an additional fire protection covering.

3.2 Mounting the device

• The device with DC power supply does not fulfill the requirements according to EN 60950-1 in the power supply unit area. The device must therefore be installed in such a way that it is part of an operating area with restricted access (for example, a lockable control cabinet, control panel or server room).

NOTICE

Voided approvals

If these conditions are not met when the system is mounted, the approvals according to UL 508 and EN 60950-1 are rendered void.

• Provide adequate volume in the control cabinet for air circulation and heat transport. Keep at least 10 cm distance between the device and control cabinet.

IP65 degree of protection

The installer of the plant is responsible for proper installation of the device.

Risk of electric shock

The degree of protection cannot be guaranteed if the device is not correctly installed. Moisture or water can penetrate and cause electric shock or plant damage.

The IP65 degree of protection is ensured for the front of the device only if you observe the following:

- Fixing with mounting brackets or mounting clips
- Make sure that the size of the mounting cut-out is correct; see section Preparing the mounting cutout (Page 33).

See also

Technical specifications (Page 131)

Dimension drawings (Page 124)

3.2.2 Mounting clips or mounting brackets, position for IP65

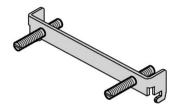
Types of mounting clips and mounting brackets

You can mount the device as follows:

• With 12 mounting clips, steel (included in the product package)



• With 6 mounting brackets (available as accessories)



Positions of the mounting clips or mounting brackets for IP65

To achieve the IP65 degree of protection for the device, the mounting clips or brackets must be affixed at the positions shown below.

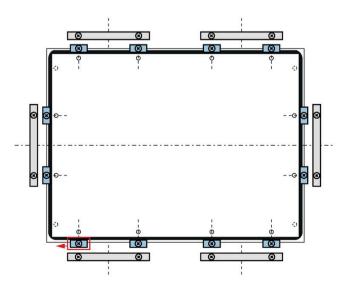
NOTICE

22" devices

The mounting clip marked in red must be shifted to the left on 22" devices to account for a cutout.

The degree of protection IP65 is not affected by the offset.

The position can be retained when using the mounting brackets.



3.2 Mounting the device

3.2.3 Mounting the device with mounting clips

Positions of the mounting clips

To achieve the degree of protection for the device, the positions for the mounting clips shown below must be adhered to.

The positions of the mounting clips are marked by stamps on the cutouts. Fit the mounting clips in all the stamped cutouts.

Requirements

- All packaging components and protective films have been removed from the device.
- To install the device, you need the mounting clips from the accessory kit.
- The mounting seal on the front of the device is not managed.

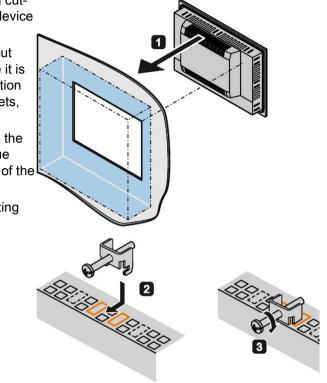
Procedure

Note

If the mounting seal is damaged or protrudes from the device, the guaranteed degree of protection is not ensured.

It is prohibited from mounting the device if the mounting seal is damaged. Order a replacement seal.

- Insert the device into the mounting cutout from the front and secure the device to prevent it falling out.
- Insert a mounting clip into the cutout provided on the device. Make sure it is in the correct position, see the section "Mounting clips or mounting brackets, position for IP65 (Page 37)".
- Tighten the threaded pin to secure the mounting clip. The maximum torque when tightening the threaded pins of the mounting clips is 0.5 Nm.
- 4. Repeat steps 2 and 3 for all mounting clips.
- 5. Check the fit of the mounting seal.



3.2 Mounting the device

3.2.4 Mounting the device with mounting brackets

If there are strict requirements for the front seal, it may be necessary to fasten the device with mounting brackets in a cabinet.

You can secure the device with 6 mounting brackets.

The mounting brackets are not supplied with the device and can be ordered separately; see section Accessories (Page 20).

Requirements

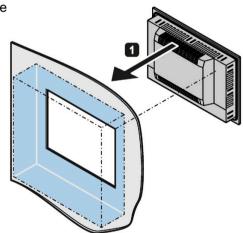
- All packaging components and protective films have been removed from the device.
- You have mounting brackets to hand
- 2.5 mm hexagonal spanner

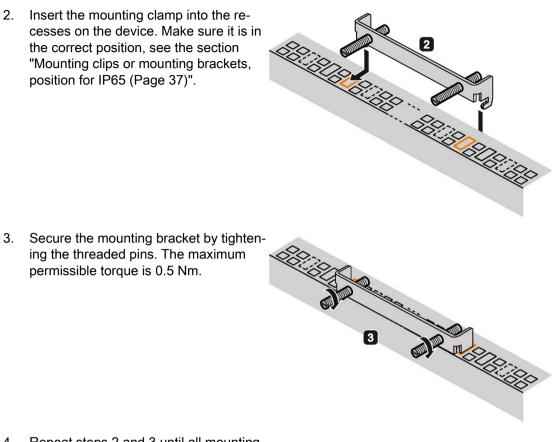
Procedure

Note

If the mounting seal is damaged or protrudes over the device, the degree of protection is not guaranteed.

1. Working from the front, insert the device into the mounting cut-out.





- 4. Repeat steps 2 and 3 until all mounting brackets are attached.
- 5. Check the fit of the mounting seal.

See also

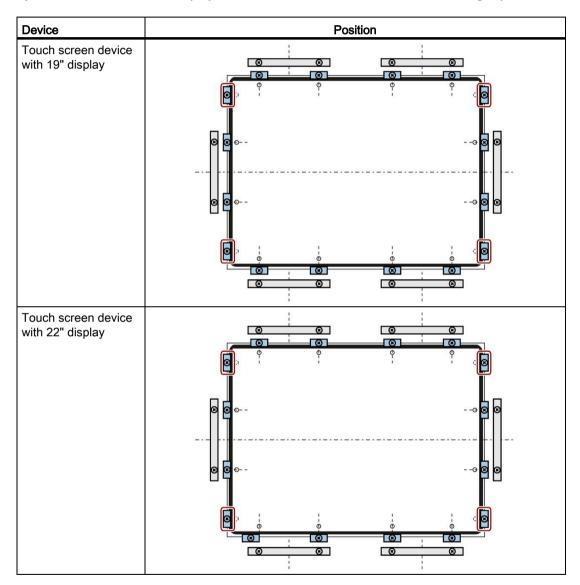
Preparing the mounting cutout (Page 33)

3.2 Mounting the device

3.2.5 Position of the mounting clips for IP66-complaint installation

Positions of the mounting clips

To achieve IP66 degree of protection instead of IP65 for a device with capacitive multi-touch screen, fasten 4 additional mounting clips (available as accessories) at the positions marked by the red boxes. The 15" display meets IP66 even without additional mounting clips.



3.3.1 Wiring information

WARNING

Risk of fire and electric shock

The on/off switch does not isolate the device from the power supply. Risk of electric shock if the device is opened incorrectly or defective. There is also a risk of fire if the device or connecting lines are damaged.

You should therefore protect the device as follows:

- Always pull out the power plug when you are not using the device or if the device is defective. The power plug must be freely accessible.
- Properly connect the device to a protective conductor.
- Use a central isolating switch in the case of cabinet installation.

Risk of lightning strikes

A lightning flash may enter the mains cables and data transmission cables and jump to a person.

Death, serious injury and burns can be caused by lightning.

Take the following precautions:

- If there is no additional lightning protection equipment: Disconnect the device from the power supply in good time when a thunderstorm is approaching.
- Do not touch mains cables and data transmission cables during a thunderstorm.
- Keep a sufficient distance from electric cables, distributors, systems, etc.

NOTICE

Fault caused by I/O devices

The connection of I/O devices can cause faults in the device.

The result may be personal injury and damage to the machine or plant.

Note the following when connecting I/O devices:

- Read the documentation of the I/O devices. Follow all instructions in the documentation.
- Only connect I/O devices which are approved for industrial applications in accordance with EN 61000-6-2 and IEC 61000-6-2.
- I/O devices that are not hotplug-capable may only be connected after the device has been disconnected from the power supply.

NOTICE

Damage through regenerative feedback

Regenerative feedback of voltage to ground by a connected or installed component can damage the device.

Connected or built-in I/Os, for example, a USB drive, are not permitted to supply any voltage to the device. Regenerative feedback is generally not permitted.

3.3.2 Connecting the Equipotential Bonding Circuit

A low-resistance ground connection ensures that interference signals generated by external power supply cables, signal cables or cables to the I/O modules are safely discharged to ground.

The equipotential bonding connection of the device is located on the side of the device and is identified by the following symbol:

Requirement

For the equipotential bonding connection, you need:

- One TORX T20 screwdriver
- One equipotential bonding cable with minimum cross-section of 2.5 mm²

Procedure

1. Connect the marked equipotentialbonding connection (thread M4) of the device with the equipotential-bonding cable.

Ensure that the equipotential-bonding cable has a large-area contact with the housing.

2. Connect the equipotential-bonding cable with the central grounding point of the cabinet.

Ensure that the equipotential-bonding cable has a large-area contact with the central grounding point.



3.3.3 Connecting 100-240 VAC power supply

Note before connecting the device

Note

The varying voltage power supply module is designed for operation on 120/230/240 V AC networks. The setting of the voltage range takes place automatically.

Thunderstorms

Do not connect or disconnect power and data cables during thunderstorms.

Operation only in TN networks

The device is designed for operation in grounded power supply networks (TN networks according to VDE 0100 Part 100, or IEC 60364-1).

Operation on ungrounded or impedance-grounded power networks (IT networks) is prohibited.

Rated voltage

The permitted nominal voltage of the device must conform with local mains voltage.

NOTICE

Notes on the power supply network

The mains connector must be disconnected to fully isolate the device from mains. Ensure easy access to this area.

A master mains disconnect switch must be installed if the device is mounted in a switch cabinet.

Make sure that the safety power outlet of the building installation is freely accessible and located as close as possible to the device.

Note

The power supply contains an active PFC (Power Factor Correction) circuit to conform to the EMC guidelines.

Uninterruptible AC power systems (UPS) must supply a sinusoidal output voltage in the normal and buffered mode when used with SIMATIC PCs with an active PFC.

UPS characteristics are described and classified in the standards EN 50091-3 and IEC 62040-3. Devices with sinusoidal output voltage in the normal and buffered mode are identified with the classification "VFI-SS-...." or "VI-SS-....".

Localized information

For countries other than the USA and Canada:

230 V supply voltage

This device is equipped with a safety-tested power supply cord which may only be connected to a grounded safety power outlet. If you choose not to use this cable, you must use a flexible cable of the following type: Cable cross-section at least 0.82 mm² and 15 A / 250 V ground contact connector. The cable set must be compliant with the safety regulations of the country where the device is to be installed and carry the identification labels required by law.

For the USA and Canada:

For the United States and Canada, a CSA or UL-listed power supply cord must be used.

The connector must be compliant with NEMA 5-15.

120 V supply voltage

A flexible cable with UL approval and with CSA label which has the following features is to be used: Type SJT with three leads, min. 18 AWG conductor cross-section, max. 4.5 m in length and parallel ground contact connector 15 A, min. 125 V.

240 V supply voltage

A flexible cable with UL approval and with CSA label which has the following features is to be used: Type SJT with three conductors, min. 18 AWG conductor cross-section, max. length 4.5 m, and tandem grounded connector 15 A, min. 250 V.

Procedure

 Make sure that the ON/OFF switch is in position '-' (Off) to avoid unintentional startup of the device when you plug in the power cord.

- 2. Connect the appliance connector to the device.
- 3. Connect the power cable with the safety power outlet.
- 4. If necessary, install the enclosed cable grip.





3.3.4 Connecting the 24 VDC power supply

Note before connecting the device

Safety extra-low voltage (SELV)

The device should only be connected to a 24 V DC power supply which meets the requirements of safe extra low voltage (SELV) according to IEC/EN/DIN EN 60950-1. A protective conductor must also be used. The conductors must withstand the short-circuit current of the 24 V DC power source, so that a short-circuit will not damage the cable. Only connect cables with a minimum cross-section of 1.3 mm² (AWG16) and a maximum cross-section of 3.3 mm² (AWG12).

Note

The 24 V DC power source must be adapted to the input data of the device (see specifications).

Procedure

- Make sure that the ON/OFF switch is in the position "0" (OFF) to prevent unintentional startup of the device when it is connected to the 24 V power supply.
- 2. Switch off the external 24 V DC power supply.
- Connect the 24 VDC plug connector to the device. Observe the correct polarity of the contacts:
 - ① DC 24 V
 - 2 ground
 - ③ protective conductor



- 4. If necessary, install the enclosed cable grip.
- 5. Secure the 24 VDC cable to the cable grip using a cable tie.



Note

Reverse-polarity protection

The DC power supply (24V) has a mechanism to protect against reverse polarity. In the event that the 24 VDC lines are reversed (24 VDC nominal (-20% / +20%) and connected to ground, the device will not be damaged. The device will simply fail to turn on. After the power supply has been connected correctly, the device will again be ready to operate.

See also

General technical specifications (Page 131)

3.3.5 Connecting peripheral equipment

Note

Ensure suitability for industrial applications

Connect only I/O devices approved for industrial applications according to EN IEC 61000-6-2.

Note

Peripheral devices capable of hot-plugging (USB)

Hot-plug I/O modules (USB) may be connected while the PC is in operation.

NOTICE

Peripheral devices incapable of hot-plugging

Peripheral devices that are incapable of hot-plugging may only be connected after the device has been disconnected from the power supply. Strictly adhere to the specifications for peripheral equipment.

Note

Wait at least ten seconds between removing and reinserting USB devices.

When using standard USB devices, bear in mind that their EMC immunity level is frequently designed only for office environments. These USB devices are adequate for commissioning and servicing purposes. Only industrial grade USB devices are permitted for use in industrial environments. The USB devices are developed and marketed by the respective provider. The product supplier in each case provides support for the USB devices. Moreover, the terms of liability of the individual vendors or suppliers apply here.

Note

The connected or built-in I/Os, such as USB drives, should not introduce a reverse voltage into the device.

Reverse voltages exceeding 0.5 V to ground that are generated by connected or installed components can prevent proper operation of the device or lead to its destruction.

3.3.6 Connecting the device to networks

The following options are available for the integration in existing or planned system environments or networks:

Ethernet

The integrated Ethernet port (10/100/1000 Mbps) can also be used for communication and data exchange with automation devices such as SIMATIC S7. This functionality requires the "SOFTNET S7" software package.

PROFIBUS/MPI

The optional electrically isolated PROFIBUS interface (12 Mbps) can be used to interconnect distributed field devices or for coupling to SIMATIC S7.

The "SOFTNET for PROFIBUS" software package is required for coupling to S7 automation systems.

PROFINET

PROFINET can be operated via

- CP1616 IRT (Isochronous Real Time)
- Standard Ethernet interfaces (RT)

CP 1616 on-board allows you to connect IPCs to Industrial Ethernet. Only one CP 1616 can be installed in a PG/PC. You will find detailed information in sections "PROFINET (Page 52)" and "CP 1616 onboard communications processor (Page 164)".

Device driver CP 16xx.sys

The device driver allow integration of the Windows network protocol in the optional "CP 1616 onboard" Ethernet PROFINET controller on SIMATIC PCs. The PROFINET interface will act like a regular 100 Mbit Ethernet interface with a MAC address when you use this driver. The three RJ45 sockets are connected with each other via switch.

PROFINET IO application

You can create, operate and configure PROFINET IO applications using the "Development Kit DK-16xx PN IO. It must be installed in addition to the CP 16xx.sys device driver. This kit and the documentation are available free of charge at the following Internet address: Development Kit DK-16xx PN IO

(http://www.automation.siemens.com/net/html_00/produkte/040_cp_1616_devlopkit.htm)

SIMATIC NET

Use this software package to configure network components and connections. You will find information on this on the SIMATIC NET DVD. This software package and the documentation are not part of the product package.

Additional information

Additional information is available in the catalog and the online ordering system Industry Mall (<u>https://mall.industry.siemens.com</u>).

3.3.7 PROFINET

CP 1616 onboard

The basic characteristics of the PCS 1616 onboard are:

- Optimized for PROFINET IO
- With Ethernet realtime ASIC ERTEC 400
- Three RJ45 sockets for connection terminal devices or addition network components
- Integrated 3-port real-time switch
- Automatic hardware detection

NOTICE

A maximum of one CP 1616/1604 is permitted

A maximum of one CP 1616/1604 module can be installed in one PG/PC. If you want to use an additional CP 1616/1604 card, the CP 1616 onboard option must be disabled using the "Profinet" entry in the BIOS setup.

Additional documentation on PROFINET

Get an overview of the information available for PROFINET (http://support.automation.siemens.com/WW/view/en/18880715/133300).

| Document name | What is contained in this document? | | |
|---|--|--|--|
| This documentation is not included in the product package: | | | |
| Getting Started PROFINET IO Getting Started: Manual Collection | The documents use concrete examples to provide step-by-step instructions on how to commission a fully functional application. | | |
| Manual PROFINET System Description | This gives you the basic knowledge about the PROFINET IO topics: | | |
| | Network components, data exchange and communica- tion, PROFINET IO, component-based automation, application example of PROFINET IO and component- based automation. | | |
| Manual From PROFIBUS DP to PROFINET IO | Read this document if you want to convert an installed PROFIBUS system to a PROFINET system. | | |
| Readme file for CP 1616/CP 1604 and DK- 16xx PN IO | This provides the latest information about the SIMATIC NET products CP 1616/CP 1604, CP 1616 onboard, the developer kit. | | |
| Configuration Manual Commissioning PC Stations | This provides you will all the information necessary for commissioning and configuring a PC as a PROFINET IO controller or IO device. | | |

| Document name | What is contained in this document? | | |
|--|--|--|--|
| Manual SIMATIC NET Industrial Communication with PG/PC: Volume 1 - Basics SIMATIC NET Industrial Communication with PG/PC: Volume 2 - Interfaces | This manual introduces you to industrial communica- tion and explains the available communication proto- cols. It also describes the OPC interface as an alternative to the IO-based user programming inter- face. | | |
| S7 CPs for Industrial Ethernet Configuring and Commissioning | This provides the following support: - For commissioning S7 stations - For establishing effective communication | | |
| Manual SIMATIC NET - Twisted Pair and Fiber- Optic Networks | d Pair and Fiber- | | |
| This documentation is part of the supplied Documentation and Drivers CD: | | | |
| Operating instructions CP 1616/CP 1604/CP 1616 onboard | This provides you with all information required for operation. | | |
| Installation guide Device Driver CP16xx.sys | Read this guide if you want to install the NDIS device driver, CP16xx.sys. | | |

Further information

You can find the information on specific products in the Internet at the address: Productrelated Information SIMATIC NET (<u>http://www.siemens.com/simatic-net</u>)

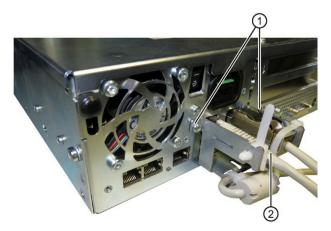
3.3.8 Connecting Ethernet/USB strain relief

The Ethernet/USB strain relief supplied in the product package is used to prevent accidental removal of the Ethernet cable and Industrial Ethernet FastConnect connector from the device. You need two cable ties to use the strain relief. In addition to the Ethernet cables, you can also use this strain relief to protect the four USB cables from inadvertent removal.

To secure the Ethernet strain relief, you will need a TORX T10 screwdriver.

Procedure

- Secure the Ethernet/USB strain relief with two oval-head screws M3 ① to the device housing.
- Connect the network and USB cables with the device and secure the connectors to the strain relief with cable ties ②.



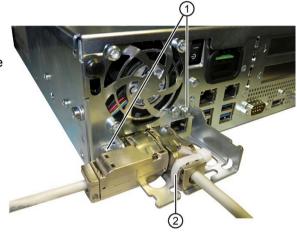
3.3.9 Connecting the PROFINET strain relief

The PROFINET strain relief supplied in the product package is used to prevent accidental removal of the Ethernet cable and Industrial Ethernet FastConnect connector from the device. You need two cable ties to use the strain relief.

To fix the PROFINET strain relief, you will need a TORX T10 screwdriver.

Procedure

- Secure the PROFINET strain relief with two oval-head screws M3 ① to the device housing.
- 2. Connect the PROFINET cables with the device and secure the PROFINET connector with straight cable outlet to the strain relief with cable ties ②.



Commissioning the device

4.1 Notes on commissioning and operation

Note

Windows Embedded Standard 7

Read the EWF and FBWF information

Two configurable write filters (Enhanced Write Filter and File Based Write Filter) are provided with Windows Embedded Standard. Read the EWF/FBWF information if you activate and use them, otherwise you can experience data loss.

Notes on operation

Note

During the startup procedure...

- Make sure that there are no conductive liquids on the touch screen during startup.
- Do **not** touch the touch screen during startup. The device automatically calibrates the touch screen during startup.

Requirement

- The device is connected to the power supply.
- The protective conductor is connected.
- The connection cables are plugged in correctly.
- The following hardware is available for initial commissioning:
 - One USB keyboard
 - One USB mouse

4.2 Switching on the device

4.2 Switching on the device

Following the initial startup, the operating system preinstalled on the drive is automatically configured on the device.

NOTICE

Faulty installation

If you change the default values in the BIOS Setup or if you turn off the device during installation, you disrupt the installation and the operating system is not installed correctly. The operating safety of the device and the plant is at risk.

Do not switch off the device during the entire installation process. Do not change the default values in the BIOS Setup.

Note

The power-up time depends on the device configuration and the BIOS settings. Changes to the device configuration and/or the BIOS settings can influence the power-up time.

Procedure

1. Set the On/Off switch to "ON" position.

The "PC ON/WD" LED lights up. The module carries out a self-test. During the self-test, the following message appears:

Press Esc for Boot Options

- 2. Wait for the message to disappear.
- 3. Follow the instructions on the screen.

The following steps are only to be performed for initial startup of the device with factory settings:

4. Make the region and language settings.

If you want your system language to be international, select English. Information about changing the region and language settings is available in the section "Servicing and maintaining the device", under "Installing software".

Note

Once the operating system has been set up, the device might restart.

5. Type in the product key as required.

You can find the product key among the identification data of the device on the "Certificate of Authenticity" COA label, in the "Product Key" line.

6. If the device is delivered with pre-installed software, the setup of the SIMATIC IPC Wizard is started automatically after operating system installation (see the following section).

The installation of the operating system is complete.

4.3 Automatic switching on of the device

4.3 Automatic switching on of the device

In the BIOS setup, you can specify the behavior of the device when it is disconnected from the mains voltage. The following property is set as default:

- BIOS setup, "Advanced" menu, "Chipset Configuration" submenu, setup parameter "After G3 On" to "S0".
- After a power loss during operation, the device will automatically restart when the power returns.

The mains voltage must have failed for at least 20 s for the power failure to be detected and for this defined action to be executed.

NOTICE

Unintentional reactions at power loss restart

Automatic startup, for example, after a power failure, can result in unintentional reactions of the machine or plant. This endangers the operation.

Take the BIOS setup entry "After G3 On" into consideration in the plant planning.

4.4 Windows Action Center

The Action Center checks the status of the device with regard to the important safety aspects listed below. If a problem is found, the Action Center provides recommendations on how you can better protect the device.

Functions

- Firewall: The Windows Firewall adds protection to the device by blocking network or Internet access to the device by unauthorized users. The firewall is enabled in the delivery state.
- Antivirus software: Antivirus programs add protection to the device by searching for and eliminating viruses and other security threats. No antivirus software is installed in the delivery state.
- Automatic updates: Using the Automatic Update feature allows Windows to regularly search for the latest critical updates for the device and to install them automatically.

This option is disabled in the delivery state for Windows Server 2008 R2 and Windows Server 2012 R2. You can enable or disable this option for Windows 7 and Windows 10 during commissioning of Windows.

 User Account Control: User Account Control issues a warning when programs attempt to modify important Windows settings. You can then either acknowledge this warning or prevent the program from changing the Windows settings.

This option is disabled in the delivery state for Windows Server 2008 R2 and Windows Server 2012 R2. This option is enabled in the delivery state for Windows 7 and Windows 10.

4.5 Notes on different device configurations

4.5 Notes on different device configurations

4.5.1 RAID1 system (optional)

This is a RAID1 system configuration (mirroring with two hard disks). This configuration enhances system availability as the system is able to continue operation if a hard drive fails, or if there is a cable problem at a channel.

The two hard disks are configured as follows in the factory state of the device:

| RAID1 system | |
|--|--|
| Partition C: System, NTFS, 50 GB | |
| Partition D: Data, NTFS, re- maining capacity | |

Note

You can find information regarding Intel RAID controllers in the RAID documentation on the included "Documentation and Drivers" DVD in the Drivers\RAID\Intel directory.

RAID system management functions

The pre-installed RAID system software offers enhanced functionality for RAID system operation and management. For more information, please refer to the chapter "Servicing and maintaining the device".

Note

The entries of the RAID status are made in the Windows Event Viewer by default.

If an error occurs, a hard disk can be synchronized at the operating system level. It may take up to several hours to synchronize a new disk in the background, depending on the size of the hard disk and on the system load.

The redundant system state RAID 1 is reached again only after synchronization is completed.

4.5 Notes on different device configurations

Comments about faults

Note

Input delay

System load may briefly increase due to synchronization when a hard disk has failed, depending on processor load and current hard disk activity.

In extreme cases, input from the keyboard and touch screen may be delayed for a brief period.

Before you replace the defective hard disk, create a backup copy of the system.

See also

Managing RAID systems (Page 91)

4.5 Notes on different device configurations

4.5.2 Notes on the DVD burner

Notes on the data backup on DVD

To achieve a reliable data backup on the DVD-R media with the burner (HLDS GTC0N, HLDS GUD0N), use the "SIMATIC IPC Image & Partition Creator" software Version V3.5.1 or higher.

Only HLDS drives for the use with DVD-R blanks are affected. There are no restrictions for DVD+R or DVD+RW blanks.

NOTICE

Data errors during burning:

- Burner operation is only permitted in an environment free of shock and vibration.
- It cannot be ruled out that vibrations in the environment and varying quality of raw discs could result in data errors when burning data media, even when no error message occurs.
- Data comparison is the only guarantee that data has been written correctly. Perform data comparison each time you burn a disc.

Requirement

- "SIMATIC IPC Image & Partition Creator" Version V3.5.1 or higher
- DVD+R or DVD+RW blank

Procedure

- 1. With the "SIMATIC IPC Image & Partition Creator" software create a backup of your data on a DVD.
- 2. Check your backups for integrity.

You can find information on this in the operating manual: "SIMATIC IPC Image & Partition Creator (https://support.industry.siemens.com/cs/de/en/view/21766418)".

4.6 Switching off the device

Procedure

Risk of electric shock

The on/off switch does not isolate the device from the mains. When the on/off switch is in the position 0 "Off", the device is still supplied with line voltage to generate the internal auxiliary voltage.

Always pull out the plug to isolate the device from the mains.

NOTICE

Risk of data loss

Microsoft operating systems and hardware components, such as hard drives, save your data in internal caches. Files may be open or data may be being written when the power supply is interrupted in the following ways:

- When you activate the on/off switch while the device is running (uncontrolled switch off)
- In the case of a hardware reset
- In the case of an unpredictable supply voltage failure

This results in data loss, which damages the device of plant. Follow these steps to prevent data loss:

- Shut down the operating system with "Start > Shut down" before you switch off the device.
- Protect the device and plant with a suitable uninterruptible power supply (UPS).
- 1. Open the function "Start > Shut down" in the Start menu.

The green LED "PC ON/WD" changes to yellow.

Operating the device and device functions

5.1 Operator input options

Depending on your device and the connected I/O devices, the following operator input options are available:

- Integrated keyboard on touch device (not for all IPC)
- Touch screen for touch device

Unintentional actions with touch screen operation

If you touch the touch screen while system-internal processes are running, unintended reactions of the device may be triggered.

Do not touch the screen in the following situations:

- During the boot process
- When plugging or unplugging USB components
- While Scandisk is running
- During a BIOS update

NOTICE

Damage to the touch screen

Hitting the touch screen with hard objects may damage it and can result in a total failure of the touch screen.

Only touch the touch screen with your fingers or a suitable touch stylus.

- Screen keyboard for touch device
- External keyboard, connected via USB
- External mouse, connected via USB

5.2 Operating a device with resistive single touch screen

5.2 Operating a device with resistive single touch screen

When you touch an object on the single touch screen, the corresponding function is performed.

Personal injury or property damage due to incorrect operation

Incorrect operation of devices with a touch screen can occur. This can result in personal injury or property damage.

Take the following precautions:

- Configure the plant so that safety-related functions are not operated with the touch screen.
- Always touch only a single point on the touch screen.
- Calibrate the touch screen, at the latest when the touch screen becomes inaccurate or does not respond despite repeated touches.
- Switch off the device for cleaning and maintenance.
- Make sure that the touch screen is kept free of dirt.

NOTICE

Damage to the touch screen

Touching the touch screen with pointed or sharp objects can damage it and lead to a significant reduction in service life or even total failure of the touch screen.

Do not touch the touch screen with pointed or hard objects. Only touch the touch screen with your fingers, a touch stylus or an approved touch glove.

Note

Appearance of blisters under extreme ambient conditions

Under extreme environmental conditions such as high atmospheric humidity and temperature, bubbles can form on the touch surface in rare cases. This only affects the appearance and does not represent any functional restriction.

5.3 Operating a device with capacitive multi-touch screen

5.3 Operating a device with capacitive multi-touch screen

You operate the multi-touch screen with one or multiple fingers. You can also operate it using gestures with up to five fingers at a time.

Personal injury or property damage due to no earth connection

An inadequate earth connection or the lack of one may cause malfunction of the capacitive touch screen. Functions may not work properly. This can result in personal injury or property damage.

- Always connect the device to an earth conductor.
- The earth conductor from the device must be connected directly to earth with low impedance (short connection, minimum cross-section 2.5 mm²).

You can find additional information on connecting the earth conductor in the section "Connecting the Equipotential Bonding Circuit (Page 44)".

Personal injury or property damage due to maloperation

Incorrect operation of devices with a touch screen can occur. This can result in personal injury or property damage.

Take the following precautions:

- Configure the plant so that safety-related functions are not operated with the touch screen.
- Switch off the device for cleaning and maintenance.

Danger of malfunction due to improper execution of gestures on the touch screen

If gestures are executed incorrectly on the touch screen with multi-touch function, these gestures may not be recognized or could be recognized incorrectly. The entries made are then not implemented by the device or are implemented incorrectly or in an unintended manner.

Incorrect execution of multi-touch functions can lead to errors in the operation of the plant and thus to physical injury.

Note the following when operating the touch screen with multi-touch function:

- The touch screen reacts to contact on its surface, not to pressure.
- When using a touch pen: Operate the touch screen only with a touch pen for capacitive touch.
- Avoid unintended multiple touches, for example, with your knuckles.

Before you start to operate the device, make sure you are familiar with the multi-touch functions of the Windows operating system, as well as with the application to be used and its functions. Ensure that the gestures which the user executes on the multi-touch display are recognized by the application. It is possible that certain gestures need to be trained beforehand.

Notes on operation

Note

Do not touch the touch screen during startup

The device automatically calibrates the capacitive multi-touch screen during startup. The touch screen is locked during calibration.

Do **not** touch the touch screen during startup. Make sure that you do **not** rest on the touch screen with the palm of your hand during startup.

Make sure that there are no conductive liquids on the touch screen during startup.

Note when operating the multi-touch screen:

- Surface contact with a diameter of about 5 to 20 mm is required for an operator action to be detected.
- An operation with gloves with a material thickness of <2 mm is detected in most cases. However, check the usefulness of the gloves you are using.
- To avoid incorrect operation, certain inputs are ignored and blocked from further entry:
 - Simultaneous operation with more than 5 fingers.
 - Surface contact with a diameter of > 3 cm, for example, resting the palm of the hand on the touch screen
 - As soon as the touch screen is no longer touched, input is possible again.

Functions of the multi-touch screen

General functions

- Detection of up to 5 finger touches at a time.
- Detection of gestures that are supported by the operating system or the software installed on the device.

Note

Multi-touch operation can provide advanced features or pose limitations depending on the operating system and the software installed on the device. Read the corresponding documentation.

• You do not need to calibrate the touch screen. Some operating systems do offer touch calibration. However, this calibration does not result in an improvement of the accuracy.

Security functions in an industrial environment

The touch screen is locked for security reasons when following happens:

- There is a conductive liquid on the touch screen with ground contact via the enclosure or the operator, for example.
- Electromagnetic interference is present that exceeds the specification according to EN 61000-4-2.

Once the interference is over, the touch screen is no longer locked.

See also

Chemical resistance of the HMI devices and industrial PCs (https://support.industry.siemens.com/cs/ww/en/view/39718396)

5.4 IPC Wizard functions

5.4 IPC Wizard functions

Software components

- General for all devices: Panel PC Tools
 - SetBrightness
 - IPCScreenSaver
- Special for devices with resistive single-touch screen: UPDD (Universal Pointing Device Driver) with the following features
 - Advanced touch features
 - Calibrating
- Calibration is not necessary for devices with capacitive multi-touch screen. Depending on your operating system, you may be able calibrate the touch screen through the operating system, although it will not improve the accuracy.

All other functions are described in the manual "SIMATIC IPC Wizard 2.1 and Panel Configuration Center":

- On the "Documentation and Drivers" CD/DVD included in the delivery
- In the IPC Wizard installation directory on the PC

5.5.1 Monitoring functions

5.5.1.1 Overview of the monitoring functions

The basic version of the device also provides monitoring functions. The following display, monitoring and control functions are available when the appropriate software is used:

- Temperature monitoring (over / under temperature)
- Battery monitoring: The charge level of the battery is monitored.
- Monitoring of hard disks, memory cards and SSD drives with S.M.A.R.T. functionality
- Watchdog (hardware or software reset of the computer)
- Operating hours meter (information on the cumulative run time)
- Hard disk status and status of the RAID system

SIMATIC IPC DiagBase software

Use the functions of the SIMATIC IPC DiagBase software included in the scope of delivery for local monitoring. Use the "DiagBase Management Explorer" application to obtain a clear overview for monitoring purposes. Use the DiagBase Alarm Manager to receive notifications about individual alarms.

Note

For more information on SIMATIC IPC DiagBase software functionality, please refer to the relevant online help.

SIMATIC IPC DiagMonitor software

SIMATIC IPC DiagMonitor is available on CD (not included in the scope of delivery). The CD contains both the monitoring software and the software for the stations to be monitored. The interface specifications and a library for creating your own applications are also provided.

5.5.1.2 Temperature monitoring/display

Four temperature sensors monitor the temperature of the device at several positions:

- Processor temperature
- Temperature close to the RAM ICs/chips
- Temperature of the basic module below the power supply
- Temperature in proximity of the air inlet

A temperature error is triggered under these circumstances:

- The configured low threshold for the temperature has been violated.
- The configured high threshold for the temperature has been violated.

A temperature error causes the following reaction:

| Reaction | Option |
|---|--------|
| The DiagBase or DiagMonitor software alerts the user. | None |

The temperature error is retained in memory until temperatures have fallen below the thresholds and it is reset by one of the following measures:

- Acknowledgment of the error message by the monitoring software
- Restart of the device

5.5.1.3 Watchdog (WD)

Configuration

You configure the watchdog with the DiagBase or DiagMonitor software.

Function

The watchdog is able to monitor system runtime and informs the user about the different reactions that are triggered if the system does not respond to the watchdog within the specified monitoring time.

A watchdog alarm is retained after a restart and is reset and logged by the DiagBase or DiagMonitor software. The watchdog configuration is retained in the process.

Watchdog reactions

The following reactions can occur if the watchdog is not addressed within the set time:

| Option | Reaction | |
|------------------------|---|--|
| Reset on | Executes a hardware reset when the watchdog expires | |
| Reset off ¹ | Executes no action when the watchdog expires | |
| Restart ¹ | Restarts the operating system when the watchdog expires | |
| Shutdown ¹ | Shuts down the operating system when the watchdog expires | |

¹ Option is device-specific.

NOTICE

"Reset on" option

The "Reset on" option immediately triggers a hardware reset that may result in loss of data under Windows and damage to the installation.

Watchdog monitoring times

The monitoring time can be configured with the DiagBase or DiagMonitor software.

Note

When you change the monitoring time, the change becomes effective immediately.

5.5.1.4 Battery monitoring

The installed buffer battery has a service life of at least 5 years. The status can be checked with two-tier battery monitoring. The information can be read from an I/O register and evaluated.

When the first warning level is reached, the remaining service life of the battery for buffering CMOS data and buffer memory is at least 1 month.

5.5.2 Enhanced Write Filter (EWF)

Purpose and function

The Enhanced Write Filter (EWF) is a function that is only available for Windows Embedded operating systems. EWF is a write filter that can be configured by the user.

You can use the Enhanced Write Filter to boot Windows Embedded Standard from read-only media, for example, memory cards or Solid State Drives (SSD), or provide individual partitions with write protection.

EWF can be used to minimize write access to storage media. This is important because the write cycles are limited due to technical reasons. We therefore recommend using EWF if you work with these storage media.

If you use HORM or compressed NTFS, EWF is indispensable.

Data loss with several write filters

Both EWF and FBWF are preinstalled in the SIMATIC IPC images. If several writer filters are active on one partition at the same time, you may experience data loss. This may damage the machine or plant.

Make sure that you only activate one write filter for each partition.

Note

Windows Embedded Standard

The Enhanced Write Filter is deactivated in the Windows Embedded Standard default state.

- Back up your data after installation of the operating system and programs.
- Activate the EWF.

Setting EWF

The following programs can be used to install, enable or disable the EWF:

- EWFMGR.EXE
- SIMATIC IPC EWF Manager.

The SIMATIC IPC EWF Manager is pre-installed and included on the supplied "Documentation and Drivers" DVD.

Start the SIMATIC IPC EWF Manager as follows:

 "Start > All Programs >Siemens Automation > SIMATIC > EWF Manager > EWF Manager"

Configure the SIMATIC IPC EWF Manager as follows:

 "Start > All Programs > Siemens Automation > SIMATIC > EWF Manager > EWF Settings"

or

• Click the "SIMATIC IPC EWF Manager" icon in the system tray.

The following functions are available:

| Function | Command |
|---|-----------------------------|
| Write-protect drive C: Power on | ewfmgr c: -enable |
| Write-protect drive C: disable: the modified data are applied | ewfmgr c: -commitanddisable |
| Modified data on drive C: apply | ewfmgr c: -commit |
| Display information about the EWF drive | ewfmgr c: |
| Display help | ewfmgr /h |

Note

The EWF commands affecting the write protection do not become active until after the next booting process.

Note

The EWF command ewfmgr c: -commitanddisable may not be used with the option -live: Not ewfmgr c: -commitanddisable -live.

Special notes for use

If EWF is enabled, when the PC shuts down all changes made on drive C: after the boot process are lost.

These changes are only retained on the PC in the following cases:

- EWF is disabled when you make changes.
- EWF is enabled and you save the changes before shutting down the device using the following command on C: drive :

ewfmgr c: -commit

Note

When the system is set to automatically adjust the clock for daylight saving time adjustment, systems without central time management and with activated EWF set the clock forward or backward by one hour in the daylight saving time or standard time period each time the system boots.

The reason for this behavior is that Windows Embedded Standard 7 makes a registry entry that the changeover to daylight saving time has occurred. Since this file is also protected against modification by the EWF, the marker is lost during the boot sequence and the adjustment is made again.

We therefore recommend that you deactivate the automatic adjustment and change the clock manually.

Follow these steps:

- 1. Deactivate automatic adjustment in the Control Panel: In the "Time Zone" tab opened with the menu command "Start > Control Panel > Date and Time", remove the check mark from the "Automatically adjust clock for daylight saving changes" check box.
- 2. Save the change you have made with ewfmgr c: -commit and then reboot the system.

5.5.3 File Based Write Filter (FBWF)

Purpose and function

With the Feature Pack 2007 for Windows XP Embedded and Windows Embedded Standard 7, Microsoft introduced a second write filter, File Based Write Filter (FBWF).

In contrast to EWF, which protects partitions based on sectors, FBWF works on the file level. When FBWF is enabled, all files and folders of a partition are protected unless they are included in an exception list.

FBWF is disabled by factory default in the operating system images for SIMATIC IPC and must be enabled and configured by the user.

When you enable FBWF, the folders C:\FBWF and D:\FBWF are authorized for writing by default.

Comparison between EWF and FBWF

- You should prefer FBWF, because it is more flexible in its configuration and allows immediate writing without rebooting.
- If you use HORM or compressed NTFS, EWF is indispensable.

Data loss with several write filters

Both EWF and FBWF are preinstalled in the SIMATIC IPC images. If several writer filters are active on one partition at the same time, you may experience data loss. This may damage the machine or plant.

Make sure that you only activate one write filter for each partition.

5.5 Extended device functions

Configuring FBWF

FBWF can be configured in command console using the program FBWFMGR.EXE.

Note

- Observe the following syntax: Enter a **space** after the drive designation colon.
- Changes for direct write access only take effect after rebooting.
- Only existing files and folders can be entered in the exception list.

| Function | Command | |
|---|---|--|
| Display the current FBWF status | fbwfmgr /displayconfig | |
| Enable FBWF after the next startup | fbwfmgr /enable | |
| Write to protected files | fbwfmgr /commit c: \Test.txt | |
| Adding/removing elements in the exception list: | | |
| Add file | fbwfmgr /addexclusion C: \Test.txt | |
| Add folder | fbwfmgr /addexclusion C: \Test fold- er | |
| Remove file | fbwfmgr /removeexclusion C: \Test.txt | |
| Remove folder | fbwfmgr /removeexclusion C: \Test folder | |
| Call up the help function | fbwfmgr /? | |

Detailed instructions on FBWF are available on the Internet (<u>http://msdn.microsoft.com/en-us/library/aa940926(WinEmbedded.5).aspx</u>).

5.5.4 Buffer memory SRAM (optional)

In order for applications to store data following a power failure, motherboards with fieldbus (PROFIBUS or PROFINET) feature battery-buffered SRAM. If the supply voltage fails for more than 20 ms for the AC power supply or more than 5 ms for the DC power supply, then you will be informed about this situation by the NAU signal.

At least 10 ms is available to copy the data to the buffered RAM. During this time, 128 Kb can be saved with a full load and even more with a smaller configuration, in other words, a lesser load. A maximum 2 MB memory window is displayed via a PCI address register. The base address is initialized by the BIOS.

A corresponding function is implemented there for using the SRAM under WinAC RTX.

Note

If replacement of the battery takes longer than 30 seconds, the data saved in the CMOS RAM and in the buffered SRAM is lost.

Note

The buffer memory SRAM is available only with devices with PROFIBUS or PROFINET interfaces.

5.5.5 Active Management Technology (AMT)

AMT (Active Management Technology) is technology for the remote maintenance of computers (simply called AMT-PC in the remainder of the document) and it includes the following functions:

- Keyboard Video Mouse(KVM) Redirection: Using KVM that is integrated in the AMT hardware you access the AMT PC remotely. With KVM, you can also control AMT PCs that have no operating system or a defective operating system. A KVM remote session is always possible with the KVM server integrated in the firmware. This means you can restart the PC and change the BIOS setup remotely.
- Remote power management: AMT PCs can be turned on and off and restarted from another PC.
- SOL (Serial over LAN): Redirection of the data of a serial interface to the network. The main use of the function is text-based remote control of an AMT PC using a console.
- IDE redirection: An ISO file on the help desk PC can be mounted on the AMT PC and used as a DVD drive.

An ISO file contains a memory image of the content of a CD or DVD structured in the ISO 9660 format.

• Remote reboot: An AMT PC can be booted from a bootable ISO file made available by another PC.

5.5 Extended device functions

SIMATIC IPC Remote Manager

The "SIMATIC IPC Remote Manager" software is available for utilization of the AMT functions with SIMATIC IPCs. The software can be ordered from the Siemens online ordering system. For detailed information about "SIMATIC IPC Remote Manager", refer to the corresponding product documentation: SIMATIC IPC Remote Manager (http://support.automation.siemens.com/WW/view/en/48707158)

Typical areas of application and functions of the SIMATIC IPC Remote Manager:

- Remote maintenance of SIMATIC IPC with AMT, for example for service purposes in the case of a defective operating system or for adapting BIOS settings.
- Diagnostics without on-site use
- Convenient service: Access to AMT clients, such as headless systems, without additional hardware
- Resource management

Requirement

- A device with Xeon processor
- A functioning and configured management engine
- A functioning and configured Ethernet connection
- A help desk PC with a functioning and configured Ethernet connection for the full AMT functionality

Configuration of the AMT PC

You configure AMT by means of the BIOS setup and MEBx (Management Engine BIOS Extension). MEBx is a BIOS extension for configuration of AMT (see BIOS description in chapter "Technical specifications").

5.5.6 Trusted Platform Modul (TPM)

Depending on the ordered configuration, the motherboard contains a Trusted Platform Module (TPM). A TPM is a chip that adds important security functions to your device, such as enhanced protection of the PC against unauthorized manipulation by third parties. The current operating systems, for example, Windows 7 and Windows 8, support these security functions.

NOTICE

Import restrictions

TPM technology is subject to legal restrictions in some regions and may not be used there. You could commit a crime by importing or exporting the device in certain countries.

Note the respective import provisions for the TPM module.

Activating the Trusted Platform Module

The TPM can be activated under "Security" in the BIOS setup. Please follow the instructions in the BIOS setup.

Using the Trusted Platform Module

The TPM can be used in Windows 7 with the "BitLocker" drive encrypter. Please follow the instructions for this in the operating system.

Note

Risk of data loss

If you lose the password for the drive encryption, you will not be able to restore the data. You will then lose accesss to the encrypted drive.

The warranty does not cover a reset of the hardware in the event of a loss of a password.

Please store the password carefully and make sure it is protected against unauthorized access.

Expanding the device and assigning device parameters

6.1 Opening the Device

The device contains electronic components which may be destroyed by electrostatic charge.

You therefore need to take precautionary measures before you open the device. Refer to the ESD guidelines on handling electrostatically sensitive components (Page 121).

Requirement

- The device is disconnect from the mains.
- All connecting cables are unplugged
- Screwdriver of type Torx T10

Limitation of liability

All technical data and approvals apply only to expansion units which are released by SIEMENS.

Siemens disclaims any liability for impairment of functions caused by the use of third-party devices or components.

Observe the installation instructions for the components. UL approval of the device only applies when the UL-approved components are used according to their "Conditions of Acceptability".

Procedure

- 1. Remove the four screws in the cover.
- 2. Lift up the cover.



6.2 Expanding memory

6.2 Expanding memory

Memory expansion options

The motherboard has 2 slots for memory modules. DIMM DDR3 1600 memory modules, type PC3-12800, unbuffered, with or without ECC can be used. This allows you to expand IPC memory capacity to up to 16 GB, of which you can use approx. 3.2 GB for the operating system and applications with 32-bit operating systems. You can install one or two modules.

| Combination | Slot x19 (outside) | Slot x20 (inside) | Maximum expansion |
|-------------|--------------------|-------------------|-------------------|
| 1 | 2 GB/4 GB/8 GB | | 8 GB |
| 2 | 2 GB/4 GB/8 GB | 2 GB/4 GB/8 GB | 16 GB |

Note

Dual-channel operation and available memory

- The modules can be inserted into any slot. Memory is operated in dual-channel mode if two modules are installed.
- Memory modules with ECC and without ECC may not be used in mixed operation.
- If expansion modules with their own memory, for example graphics cards, with 256 MB or more are used, the memory available for the 32-bit operating system or applications may also be less than 3.2 GB.

In order to avoid operating faults you may have to remove a module so that the real memory expansion on the motherboard and the reserved memory of the expansion module do not overlap.

Preparation

Disconnect the device from mains and unplug all cables.

NOTICE

Electrostatic discharge

The electronic components on the PCBs are highly sensitive to electrostatic discharge. Always take appropriate precautionary measures when handling these components. Refer to the ESD directives on handling electrostatic sensitive components.

Note

We strongly recommend using only memory modules approved by Siemens. Siemens disclaims any liability for impairment of functions caused by the use of third-party memory modules.

6.2 Expanding memory

Installing a memory module

- 1. Open the device (Page 78).
- Note where the (polarized) cutout
 is located on the pin side of the RAM module before inserting it.

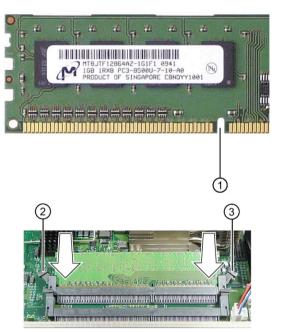
- Open the two locking mechanisms on the left ② and right ③ of the slot.
- Insert the module downwards, applying slight pressure and press it until the locking snaps into place.
- 5. Close the device.

Removing a memory module

- 1 Open the device (Page 78).
- 2 Release the locking mechanisms on the left and right of the slot.
- 3 Pull the memory module out of the slot.
- 4 Close the device.

Display of the current memory configuration

A new memory module is automatically detected. When switching on the device and starting the BIOS Setup using <F2>, the current memory size is displayed under "Total Memory".





6.3 Expansion cards

6.3 Expansion cards

6.3.1 Notes on the expansion cards

The device is designed for use with PCI expansion cards conforming to PCI specification V 2.2:

- 5 V 32 Bit PCI
- Universal 5 V & 3.3 V 32 Bit PCI

The following PCIe specifications apply to the use of PCIe cards:

- x16: V3.0
- x4: V2.0

Equipment options:

- 2 × PCI
- 1 × PCI, 1 × PCIe x16
- 1 × PCIe x4 Slot 1, 1 × PCIe x16 Slot 2

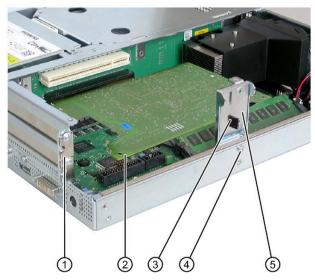
6.3.2 Removing and installing expansion cards

Requirement

• The device is opened.

Procedure

- Loosen the fastening screw (4) and remove the card retainer (5).
- 2. Remove the slot cover ① from the intended slot.
- 3. Insert the expansion card ② into the intended slot.
- 4. Mount the card bracket and insert the slider ③.
- 5. Screw in the slot cover ① of the expansion card.

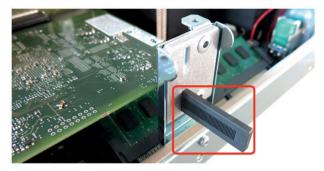


6. Insert the slider.

6.3 Expansion cards

Inserting the slider

1. Push the slider through the guide slot until it is firmly seated on the expansion card. The expansion card must now be inserted into the slot.



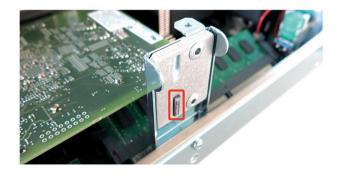
NOTICE

Damage to the expansion card.

The expansion card can break if excessive force is used.

- Do not apply any pressure.
- Do not apply excessive force on the slider when you push it onto the expansion card.
- 2. Cut off the protruding part of the slider element.

Use a knife to apply a cut on the slider at the upper edge of the bracket and then break this section off. Cut off the excess length with a diagonal cutter.



Notes on the allocation of resources

The slots for the expansion cards come with exclusive interrupts. The assignment of the PCI IRQ line to the PCI slot is explained in the chapter "Bus board (Page 145)".

6.4 Drives

6.4.1 Installation options for internal drives

One 3.5" hard disk



- Item Description
- ① Slot for one 3.5" drive
- ② Drive bay for one 3.5" drive

Two 2.5" hard disks



One SSD drive



Item Description

Item Description

2.5" hard disks

1

2

(1) SSD drive: Two slots for SSD drives

2.5" hard disk: Two slots for

Drive bay for 2.5" hard disks

② Drive bay for SSD drive

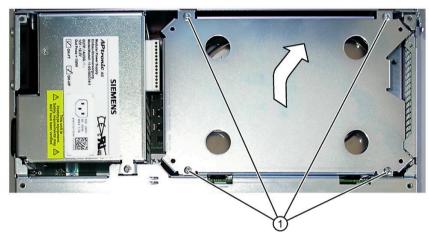
6.4.2 Removing and installing the drive bay module

Requirement

• The device is opened.

Procedure

1. Remove the four screws 1.



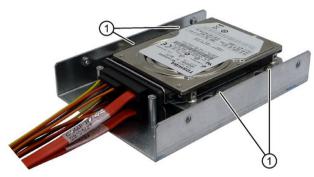
2. Lift out the drive bay module for hard disks and set it down carefully with the base facing downwards.

6.4.3 Removing and installing hard disks

Procedure

Removing 2.5" drive

- 1. Remove the drive bay module.
- Loosen the 4 screws ① on the holding plates.
 Do not remove the screws.



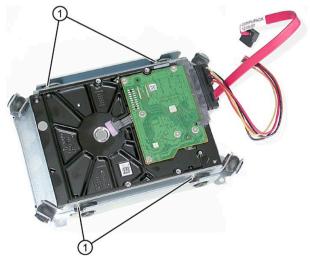
- 3. Remove the hard disk drive including the mounting plate from the bay.
- 4. Disconnect the power supply and the data cable from the drive.

Removing 3.5" drive

Note

Special screws with inch threads (screw designation 6-32x3/16"-St-G3E) are used with this drive.

- 1. Remove the drive bay module.
- 2. Disconnect the power supply and the data cable from the drive.
- 3. Remove the screws ① (Torx T15) of the drive.



4. Remove the hard disk drive from the bay.

Removing hard disk in removable drive bay

See chapter "Maintaining and repairing the device", "Removing and installing hardware", section "Removing and installing the hard disk in the removable drive bay (Page 105)".

Installation

Proceed in reverse order in each case.

6.4.4 Removing and installing an SSD drive

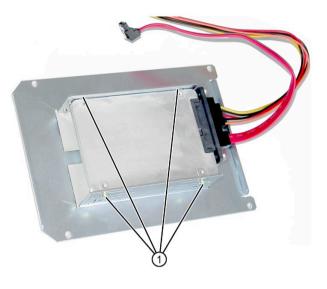
Requirement

• The device is opened.

Procedure

Removal

- 1. Remove the drive bay module.
- 2. Disconnect the power supply and the data cable from the drive.
- 3. Loosen the screws 1 of the drive.



4. Remove the drive from the bay.

Installation

Proceed in reverse order.

6.4.5 Installation options for external drives

Some devices are equipped with external drives according to their configuration; these are mounted on the outside of the device, for example, a DVD drive.



A DVD drive

The figure shows a mounted DVD drive.



Two 2.5" hard disks in removable drive bay

Item Description

- 1 2.5" hard disk
- (2) Tray for one 2.5" hard disk

6.4.6 Removing and installing a DVD drive

Requirement

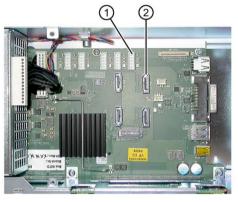
• The device is opened.

Procedure

Removing external drive

- 1. Remove the internal HDD/SSD drive bay module.
- Loosen the following connectors of the optical drive from the motherboard:
 - Power supply connector ①.
 - SATA connector ②

- Loosen the designated rivets on the left and right on the cover with a screwdriver and put the cover down with the optical drive facing downwards.
- 4. Loosen the designated screws on the inside of the cover.







- 5. Remove the cover of the external drive and the drive bay from the device.
- 6. Pull the connector of the SATA cable from the drive.

7. Loosen the four screws that connect the optical drive with the drive bay and pull out the optical drive to the front from the drive bay.



Installing external drive

Proceed in reverse order.

Maintaining and servicing your device

7.1 Maintenance

To maintain high system availability, we recommend the preventative replacement of those PC components that are subject to wear. The table below indicates the intervals for this replacement.

| Component | Replacement interval: |
|---------------------|---|
| Hard disk drive | 3 years |
| Fan | 3 years |
| CMOS backup battery | 5 years |
| SSD | Depends on the type of use ¹ |

¹ The interval for replacement depends greatly on the type of use. A specific interval cannot be given.

All drives are monitored with the software tools DiagBase or DiagMonitor on the basis of their SMART status. As soon the SMART status of the HDD or SSD switches to "Not OK", a message is sent in DiagBase or DiagMonitor, or when you start up the PC. You should then back up your data and replace the drive.

7.2 Managing RAID systems

7.2.1 Example for a RAID1 system during the boot phase of the system

| Intel(R) Rapid Storage Technology - Option ROM - Copyright(C) 2003-13 Intel Corporation. All Rights Reserved. | | | | | |
|--|---------------------------------------|-------------------------------|--------------|-------------------------------|-----------------|
| RAID ID 0 | Volumes: Name Volume0 | Level RAID1(Mirror) | Strip N∕A | Size Status 931.5GB Normal | Bootable Yes |
| | ical Devices: Device Model | Serial # | | Size Type/State Member Dis | sk(0) |
| | <pre><ctrl-i> to enter</ctrl-i></pre> | Configuration Util | ity | Member Di | SK(0) |

You can configure RAID hardware with <CTRL-I> in the boot phase. The associated description is available on the "Documentation and Drivers" DVD.

7.2 Managing RAID systems

7.2.2 RAID software

The RAID software "Intel Rapid Storage Technology" offers advanced functions to use and manage the RAID system.

1. Select the RAID software via "Start > Programs > Intel Rapid Storage Technology".

| 🔁 Intel® Rapid Storage Technology | |
|--|---|
| Status Manage Performance Preferences | intel |
| Current Status Your system is functioning normally. Manage Click on any element in the storage system view to manage its properties. O The Windows' write-cache buffer flushing policy can be enabled for all RAID array drives to ensure data integrity or disabled to improve data performance. Click the Help icon for more information on setting the write-cache buffer flushing policy based on your needs. | Storage System View (C) SATA_Array_0000 466 G8 466 G8 466 G8 ATAPI Device ATAPI Device Internal empty port 2 Internal empty port 3 Internal empty port 4 |
| | More help on this page |
| | |

- 2. Select "Manage" > "Advanced" to display details of the RAID system.
- Select "Help" > "System Report" > "Save" to create a report with the details of the RAID system.

7.2.3 Checking the status of the RAID system

By default, the status of the RAID system is displayed in the Windows Event Viewer and in a log file of the program. If an error occurs, a hard disk can be synchronized at the operating system level.

Note

It may take a very long time (hours or even days in the case of a high drive load) to synchronize a new hard disk in the background, depending on its size and on the system load.

The redundant system state is reached again only after synchronization is completed.

NOTICE

Operator errors on the machine or plant

Data is synchronized if a hard disk fails. Depending on the work load of the processor and hard disks, the system may react with some delay. Execution of keyboard, mouse or touch screen commands may be briefly delayed in extreme situations. This could result in operator errors on the machine or plant.

Do not operate safety-critical functions when a hard disk has failed.

7.2 Managing RAID systems

7.2.4 Displaying a defective hard disk of a RAID system in the RAID software

Note

Always replace the defective hard disk with a new hard disk of the same type and capacity.

If an error is detected the defective hard disk must be replaced with a new hard disk to return to a secure RAID status after an error.

The RAID software indicates the following:

- A defective hard disk
- Details of the functioning hard disk:

The functioning hard disk is indicated by BIOS with its port number or by the RAID software with its device port number.

The following figure shows the corresponding window in the RAID software with a RAID1 system.

| 🔁 Intel® Rapid Storage Technology | | – 🗆 X |
|---|-----------------------|---------------------|
| Status Manage Performance Preferences | | (intel) |
| Current Status Your system is reporting one or more events, and data may be at risk. | Storage System View | G |
| Refer to the details below for more information. | 466 GB Typ | lume1 be: RAID 1 |
| Click on any element in the storage system view to manage its properties. The Windows' write-cache buffer flushing policy can be enabled for all RAID array drives to ensure data integrity or disabled to improve data performance. Click the Help icon for more information on setting the write-cache buffer flushing policy based on your needs. | 0 GB 460 | 5 GB |
| SATA_Array_0000 💯 Volume1: Degraded | Internal empty port 2 | ļ |
| Details: Fix any problems reported on the array disks, or rebuild the volume to a new disk. Unknown disk on Controller 0, Port Unknown: Missing 👰 | Internal empty port 3 | |
| | Internal empty port 1 | |
| | More h | nelp on this page |
| | | |

You can find information on how to detect and replace a defective hard disk in the RAID system in the section "Removing and installing hardware (Page 104)".

7.2.5 Special feature: Replacing hard disk in the RAID system when switched off

The RAID system does not automatically boot up when restarted if a defective hard disk was replaced while the RAID system is switched off. Therefore, place the RAID system in the first place of the bootable sources in the BIOS setup menu "Boot". Otherwise, the system will boot from the hard disk you have just installed and the message "Operating system not found" will be displayed.

7.2.6 Integrating a new hard disk drive in the RAID system

The RAID system is configured in the delivery state so that a new hard disk must be integrated manually in case of an error. To integrate the hard disk automatically, activate "Automatic rebuild" in the "Preferences" menu of the RAID software.

Automatic integration of a hard disk

| NOTICE | |
|---------------------------|---|
| Data loss | |
| | k to be integrated is not checked for partition information or existing data natic integration. |
| All partitions hard disk. | and data on the hard disk are deleted without warning. Insert only a brand-new |

Requirement:

- "Automatic rebuild" is selected in the "Preferences" menu of the RAID software.
- The hard disk must be completely new or set up as spare drive for this purpose. Notes on creating spare drives are available in the controller documentation.

Sequence

The following figure is an example for the automatic rebuilding process.

| A Intel® Rapid Storage Technology | |
|--|--|
| Status Manage Performance Preferences | (intel) |
| Current Status Your system is reporting one or more events, and data may be at risk. Refer to the details below for more information. Image Click on any element in the storage system view to manage its properties. The Windows* write-cache buffer flushing policy can be enabled for all RAID array drives to ensure data integrity or disabled to improve data performance. Click the Help icon for more information on setting the write-cache buffer flushing policy based on your needs. SATA_Array.0000 Volume1: Rebuilding 1% complete Unknown disk on Controller 0, Port Unknown: Missing | Storage System View SATA_Array_0000 Volume1 Type: RAID 1 466 GB Volume1 466 GB Volume1 466 GB Volume1 466 GB Volume1 466 GB Volume1 466 GB Volume1 Type: RAID 1 466 GB V |
| | More help on this page |

A defective hard disk is still displayed during the rebuilding process. This display disappears when the rebuilding process is completed.

7.2 Managing RAID systems

Procedure - integrating hard disk manually

When the "Automatic rebuild" option is deselected in the "Preferences" menu of the RAID software (default setting), you must integrate the hard disk manually:

- 1. Select "Start" > "Programs" > "Intel Rapid Storage Technology".
- 2. Click 😊 "Run Hardware Scan now".

The new hard disk is found and displayed.

Or:

1. Reboot the device.

The RAID software automatically integrates the hard disk.

2. Click the "Rebuild to another Disk" link.

The RAID system is synchronized.

The following figure shows the window when integrating a hard disk in a RAID1 system.

| 🔁 Intel® Rapid Storage Technology | | - X |
|--|--|-----------------------------------|
| Status Manage Performance Preferences | | intel |
| Current Status Your system is reporting one or more events, and data may be at risk. Refer to the details below for more information. | Storage System View SATA_Array_0000 | s I |
| Manage Click on any element in the storage system view to manage its properties. | 466 GB | Volume1 Type: RAID 1 466 GB |
| The Windows* write-cache buffer flushing policy can be enabled for all RAID array drives to ensure data integrity or disabled to improve data performance. Click the Help icon for more information on setting the write-cache buffer flushing policy based on your needs. | SATA disk (466 GB) 466 GB | |
| SATA_Array_0000 Volume1: Degraded <u>Rebuild to another disk</u> Details: Fix any problems reported on the array disks, or rebuild the volume to a new disk. | ATAPI Device | |
| Unknown disk on Controller 0, Port Unknown: Missing 💯 | Internal empty port 3 | |
| | Internal empty port 4 | ore help on this page |
| | | |

If you shut down and restart the system without installing a functioning new hard disk, "unused" is displayed for the corresponding SATA port. You can install the functioning hard disk while the system is running. The new hard disk is then assigned to a SATA port and is integrated into the RAID system.

A defective hard disk is still displayed during the rebuilding process. This display disappears when the rebuilding process is completed.

7.3 Service and spare parts

Making repairs

Opening the device

Unauthorized opening and improper repairs on the device may result in substantial damage to equipment or endanger the user. If you install or replace a system expansion and damage your device, the warranty will become void.

The device may only be repaired by qualified personnel.

Safety when working in and on electrical systems

Work in or on electrical systems may only be carried out by authorized persons. The following safety regulations apply in Germany for the prevention of electric shock and electrocution:

- 1. Switch off the system
- 2. Secure the system to prevent it switching back on
- 3. Check the system to ensure it is de-energized
- 4. Ground and short the system
- 5. Cover or shield adjacent live parts

These safety rules are based on the DIN VDE 0105 standard.

Note

These safety steps must always be taken in the above order before any work on electrical systems. Once work on an electrical system is finished, cancel the safety steps starting with the last and finishing with the first.

In accordance with the applicable safety regulations, clearly indicate on an electrical system that work on it is underway.

Observe the safety regulations applicable in the country of operation.

Electrostatic-sensitive components

The device contains electronic components which are destroyed by electrostatic charges. This can result in malfunctions and damage to the machine or plant.

Make sure you take precautionary measures even when you open the device, for example, when opening device doors, device covers or the housing cover. For more information, refer to the chapter "ESD Guideline (Page 121)"

7.3 Service and spare parts

Risk of explosion and release of harmful substances

Improper handling of lithium batteries can result in an explosion of the batteries. Explosion of the batteries and the released pollutants can cause severe physical injury.

Observe all safety and handling instructions for lithium batteries. Do not expose lithium batteries to flames and do not solder the battery cell. Do not recharge, open, or short lithium batteries. Do not reverse lithium battery polarity or heat the batteries to over 100°C. Keep lithium batteries out of direct sunlight and protect them from moisture and condensation.

Note the following when handling lithium batteries:

- An empty battery jeopardizes the function of the device. Charge the battery in good time.
- Replace lithium batteries only with batteries of the same type or a type recommended by the manufacturer.

The order number for the lithium battery is A5E00331143.

NOTICE

Batteries and rechargeables pollute the environment

Do not dispose of used batteries or rechargeables in household waste. Users are obliged by law to return used batteries and rechargeable batteries. You as the user are legally responsible disposing used batteries or rechargeables in a correct manner.

Observe the following rules for the disposal of batteries and rechargeables:

- Dispose of used batteries and rechargeable batteries separately as hazardous waste in accordance with local regulations.
- You can take used batteries and rechargeable batteries to public collection points and wherever batteries and rechargeable batteries of the type in question are sold.
- Mark used battery containers as "Used batteries".

Limitation of liability

All technical specifications and approvals for the device apply only if you use expansion components that have a valid CE approval (CE marking). The installation instructions for expansion components in the associated documentation must be observed.

UL approval of the device only applies when the UL-approved components are used according to their "Conditions of Acceptability".

We are not liable for functional limitations caused by the use of third-party devices or components.

See also

Spare parts and repairs (<u>http://support.automation.siemens.com/WW/view/en/16611927</u>)

7.4 Cleaning the Device Front

The device is designed for low-maintenance operation. You should still clean the device front regularly, however.

Unwanted reactions when cleaning the device

You risk unintentional actuation of control elements if you clean the device while it is switched on.

You may possibly trigger unwanted actions of the device or controller that are liable to cause personal injury or damage to the machinery.

Always switch off the device before you clean it.

Cleaning Agents

NOTICE

Damage to the HMI device caused by impermissible cleaning agents

Impermissible and unsuitable cleaning agents may cause damage to the HMI device.

Use dish soap or foaming screen cleaner only as cleaning agents. Do not use the following cleaning agents:

- Aggressive solvents or scouring powder
- Steam jets
- Compressed air

Cleaning the Device Front

- 1. Switch off the device.
- 2. Dampen the cleaning cloth.
- 3. Spray the cleaning agent on the cloth and not directly on the device.
- 4. Clean the device with the cleaning cloth.

7.5 Separating the control unit from the computer unit

7.5 Separating the control unit from the computer unit

Introduction

You separate the control unit from the computer unit in the removed state to carry out repairs or to replace the control unit, for example.

Requirement

- The device is disconnected from the mains.
- The device is fully removed.
- The device is lying on a soft cloth with the front side down.

Procedure

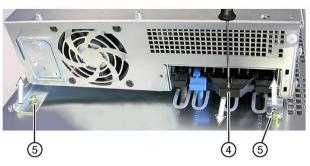
1. Loosen the 4 screws ① somewhat, but do not remove them.



 Loosen the captive knurled screw ② and remove the metal door from the slots ③.

7.5 Separating the control unit from the computer unit

- 3. Pry out the connector ④ using a screwdriver.
- Push the computer unit back slightly until the screw (5) lies exactly in its recess.
- 5. Pull the connector ④ fully out.
- 6. Lift up the computer unit and gently place it on a soft surface.



7.6 Connecting the control unit with the computer unit

7.6 Connecting the control unit with the computer unit

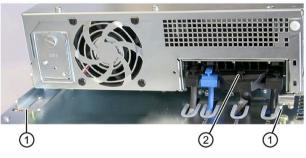
Requirement

- Computer unit and control unit are disconnected from the mains.
- Control unit and computer unit are fully removed.
- The control unit is lying on a soft cloth with the front side down.

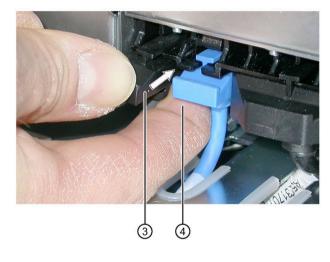
Procedure

 Set down the computer unit with its guide rail lightly on the screws ①.

> Make sure that the computer unit is not scratched and there is sufficient distance to the control unit for the connector (2) and its cable.

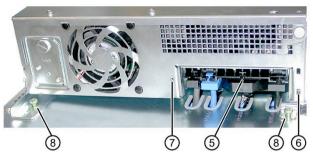


- Mount the connector ② on its corresponding guide rail (see figure) and push the connector all the way in until it is securely at the back of its socket.
- Push the left connector ③ to the back of its socket as depicted using the index finger ④ as support.



7.6 Connecting the control unit with the computer unit

- 4. Check once again that all the connectors (5) are fully plugged in and are the same height at the front.
- Insert the metal door in the rivers
 ets (6) and close the metal door with the knurled screw (7).
- 6. Slide the computer unit all the way forward to the stop screw(8) and screw in the 4 screws.



7.7 Removing and installing hardware

7.7 Removing and installing hardware

7.7.1 Replacing a defective hard disk drive in the RAID system

A hard disk can only be replaced during operation in the removable drive bay in connection with a configured RAID1 system. This functionality is referred to as "Hot Swap".

Note

If you have configured a non-RAID system with several hard disks, or in the case of an internally installed hard disk, you need to turn off the device before you replace a hard disk.

Observe the EGB guidelines. Always replace the drive with a new drive of the same type and capacity.

Mounting locations for hard disks in the RAID1 system

Hard disks for a RAID1 system can be installed permanently in the device or in a removable drive bay.

Note

The replacement of a RAID hard disk with removable drive bay can be performed without shutting down the device. An internal hard disk may only be replaced when the device is switched off.

The new hard disk can be integrated into the RAID system at operating system level with the RAID software. Synchronization may take several hours, depending on system load.

Status displays of the hard disks in a RAID1 system

The following table includes information on the alarms of the status displays. If the hard disk is defective and the SIMATIC DiagBase monitoring software is installed, the LEDs of the status display light up individually or simultaneously.

Internal hard disk or hard disk in removable drive bay

| Status display | RAID BIOS | RAID software | SATA connection of the motherboard | Drive |
|----------------|-----------|---------------|------------------------------------|-------|
| HDD0 alarm | Port 0 | Device port 0 | SATA 0 | 0 |
| HDD1 alarm | Port 1 | Device port 1 | SATA 1 | 1 |

Replacing a defective hard disk in the RAID system

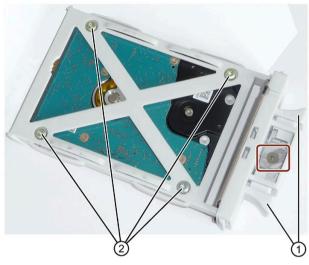
- 1. Determine which hard disk was reported by the RAID software as defective.
- 2. Remove the defective hard disk or replace the hard disk in the removable drive bay.
- 3. Replace the defective hard disk with a hard disk of the same type and capacity.
- 4. Integrate a new hard disk drive into the RAID system (Page 95).

7.7.2 Removing and installing the hard disk in the removable drive bay

Procedure

Removal

- 1. Open the lock identified in the figure with the appropriate key from the top.
- 2. Push in both sliders ① on the handle and remove the hard disk tray using its handle.
- 3. Place the hard disk bay top down on a soft surface.
- 4. Loosen the screws ② of the drive.



5. Remove the drive from the removable drive bay.

Installation

Proceed in reverse order.

7.7 Removing and installing hardware

7.7.3 Replacing the Backup Battery

Note

Batteries are wearing parts and should be replaced every 5 years to ensure proper functioning of the PC.

To be noted before you replace the battery

Risk of explosion and release of harmful substances!

For this reason, do not burn lithium batteries, do not solder on the cell body, do not open, do not short circuit, do not reverse polarity, do not heat above 100°C, dispose of correctly, and protect against direct sunlight, dampness and dew.

NOTICE

Risk of damage!

The lithium battery may only be replaced with an identical battery or with a type recommended by the manufacturer (Order No.: A5E00331143).

Disposal

Batteries must be disposed of in accordance with local regulations.

Requirement

Note

For the BIOS setting "Profile: Standard" the configuration data of the device is deleted when the battery replacement takes more than 30 seconds. You need to enter the configuration data again in the BIOS setup.

For the BIOS setting "Profile: User" the configuration data of the device is retained; only the date and time has to be reconfigured.

The content of the SRAM is lost if the battery replacement takes more than 30 seconds.

- You have written down the current settings of the BIOS setup. A list in which you can note down this information is found in the BIOS description.
- The device is disconnected from the mains and all connecting cables have been removed.

Note

You can also replace the battery while the device is running; do not touch anything with the device in this case. We recommend switching off the device beforehand.

Procedure

1. Open the battery compartment with a screwdriver at the indicated location.

2. Remove the battery holder.

3. Detach the cable.



- 4. Remove the old battery.
- 5. Fasten the new battery and reinsert the battery holder.
- 6. Close the battery compartment.

Maintaining and servicing your device

7.7 Removing and installing hardware

7.7.4 Removing and installing the power supply

Requirement

• The device is opened.

Procedure

Removal

- 1. Remove the screw at the indicated location below the on/off switch on the back of the device.
- 2. Remove the identified screws (Torx T10) on the side.

- 3. Remove the drive bay module. (Page 84)
- Remove the labeled power supply connector of the power supply.
- Lift up the power supply unit slightly and remove it to the rear top

Installation

Proceed in reverse order.







7.7.5 Removing and installing the bus board

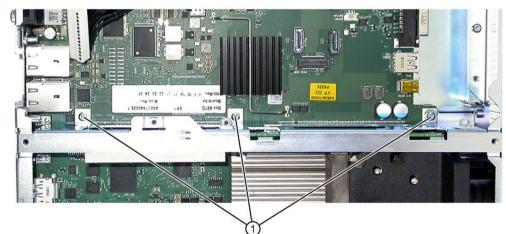
Requirement

• The device is opened.

Procedure

Removal

- 1. Remove all modules from the slots.
- 2. Remove the drive bay module for hard disks.
- 3. Remove the power supply.
- 4. Remove the screws 1 on the bus board.



5. Pull the bus board from the motherboard.

Installation

Proceed in reverse order.

Maintaining and servicing your device

7.7 Removing and installing hardware

7.7.6 Removing and installing the power supply fan

Requirement

- The device is opened.
- The power supply has been removed.

Procedure

Removal

1. Pull out the plug of the power supply fan ①.



- 2. Loosen the four screws ② on the enclosure.
- 3. Take the power supply fan out of the enclosure.

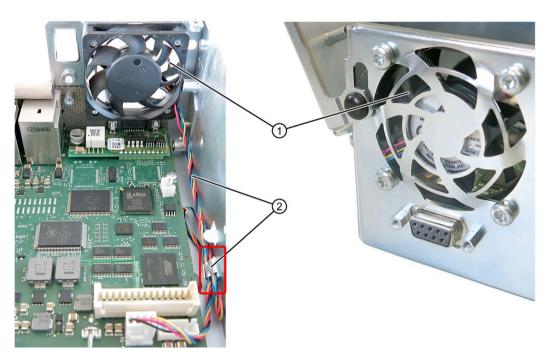
Installation

Note

Install only a fan of the same type. Note the correct mounting position of the fan.

The figure shows the correct mounting position.

- Direction of flow: Make sure that the blades ① of the power supply fan are on the outside of the housing.
- Run the power supply cable ② along the housing edge and fasten any excess cable as loop as shown in the illustration.



Maintaining and servicing your device

7.7 Removing and installing hardware

7.7.7 Removing and installing the device fan

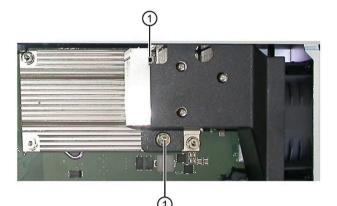
Requirement

• The device is opened.

Procedure

Removal

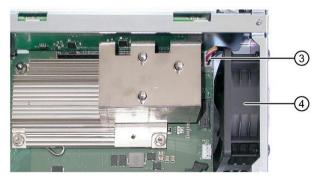
1. Remove the two screws ① and remove the air guide pulling it up vertically.



2. Loosen the four plastic rivets ② on the enclosure.



- 3. Pull out the fan plug ③.
- 4. Take the fan ④ out of the enclosure.



Installation

Note

Install only a fan of the same type. Note the correct fan mounting position: Make sure that the blades of the fan are on the outside of the housing.

Proceed in reverse order.

7.7.8 Replacing the processor

Requirement

- The device is opened.
- The memory modules have been removed.
- The air guide has been removed (see chapter "Removing and installing the device fan (Page 112)")
- A suitable processor

Only an approved processor is permitted to be installed on the motherboard of the device. If the processor type is changed, the BIOS must be updated so that the suitable microcode is loaded. Information about original spare parts for SIMATIC IPCs is available on the Internet at:

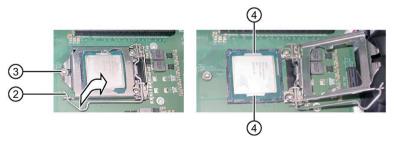
- Contacts (http://www.siemens.com/automation/partner)
- SIMATIC IPC after-sales information system (http://www.siemens.com/asis)

Procedure

1. Loosen the screws ().

The fourth screw is hidden by the air guide in the figure.

- 2. Remove the heat sink.
- 3. Release the lever ② of the processor bay and tilt it all the way back. The bay releases the processor.



- Remove the processor by grabbing the rails on the side ④. Do not touch the processor and its connections in the process (see Technical Specifications, chapter "ESD guidelines").
- 5. Install the new processor on the socket, as shown in the figure.

During positioning, make sure to take the highlighted arrow on the processor into consideration.

- 6. Tilt the lever to the front again. Make sure that the bay covers the screw ③.
- 7. Press the lever all the way down and lock it again.

NOTICE

Damage to the processor

The locking mechanism may be stuck. The locking mechanism is damaged while being pressed down. The processor is not correctly locked in place by the bay. The result may be malfunctions.

- Do not use excessive force.
- Tilt the lever back again and try again.

The next steps are available in the "Technical manual of the motherboard" on the "Documentation and Drivers" DVD shipped with the product.

Processor type and clock frequency

When a processor is replaced, perform a BIOS update. The microcode matching the processor is loaded in the process.

Note

Damage to the processor due to high clock frequency

If the installed processor is operated with a higher clock frequency than permitted, it can be destroyed or cause loss of data.

Operate the processor only at a clock frequency that is equal to or less than the permitted clock frequency.

7.8 Recycling and disposal

7.8 Recycling and disposal

Due to the low levels of pollutants in the HMI devices described in these operating instructions, they can be recycled.

Contact a certified disposal service company for electronic scrap for environmentally sound recycling and disposal of your old devices, and dispose of the device according to the relevant regulations in your country.

7.9 Installing operating system, software and drivers

7.9.1 Installing the operating system

Information on commissioning, restoring or reinstalling the operating system you ordered with the device can be found in the detailed operating system description on the delivered data carrier or online under:

- Microsoft® Windows® 7 (https://support.industry.siemens.com/cs/ww/en/view/109749497)
- Microsoft® Windows® 10 (https://support.industry.siemens.com/cs/ww/en/view/109749498)
- Microsoft® Windows Embedded Standard® 7 (https://support.industry.siemens.com/cs/ww/en/view/109749499)

7.9.2 Installing software and drivers

The supplied USB stick (read only), contains the "Documentation and Drivers" suite, which you use to install all supplied software and drivers.

Procedure

- 1. Insert the provided USB stick into the device.
- 2. Start the "Documentation and Drivers" suite from the USB flash drive by executing the "START_DocuAndDrivers.CMD" file.
- 3. Install the desired software and drivers.

Technical information

8.1 Certificates and approvals

ISO 9001 certificate

The Siemens quality management system for our entire product creation process (development, production and sales) meets the requirements of ISO 9001:2008.

This has been certified by DQS (the German society for the certification of quality management systems).

Certificate no.: 001323 QM08

Software license agreements

If the device is supplied with preinstalled software, you must observe the corresponding license agreements.

UL approval



- UL 508 (Industrial Control Equipment)
- CSA C22.2 No. 142 (Process Control Equipment)
- ANSI/ISA 12.12.01 (Hazardous Location)
- CSA-213 (Hazardous Location) Approved for use in
- Cl. I Div. 2, GP. A, B, C, D T4
- Cl. I, Zone 2, GP. IIC T4

ATEX/IECEx approval



Additionally to the installation instructions in the user manual of IPC477D the following specifications must be observed for installation in hazardous locations.

The device has to be used in pollution degree 2 environment only.

Use copper supply wires of at least 0.75 mm². EN60079-0 (ATEX) EN60079-15 (ATEX) EN60079-31 (ATEX) IEC60079-0 (IECEx) IEC60079-15 (IECEx)

8.1 Certificates and approvals

IEC60079-31 (IECEx)

| | II 3 G | Ex nA IIC Tx Gc |
|----------------------|--------|------------------|
| $\langle Ex \rangle$ | II 3 D | Ex tc T 70 °C Dc |

Approval Mark ATEX 15ATEX0119X and/or IECEx DEK 15.0080X

Note

Installation

You have to install the device so that the complete device conforms to IP65.

The front panel of the mounted device confirms to IP65.

DC-Version

If a main circuit breaker for DC-supply should be installed in hazardous locations as described above it has to be intended for use in that area. Otherwise it must be installed in an area which is known to be non-hazardous.

Risk of explosion when connecting or disconnecting the device

EXPLOSION HAZARD

WARNING - EXPLOSION HAZARD - Do not connect or disconnect while circuit is live unless area is known to be non-hazardous.

This equipment is suitable for use in Class I, Division 2, Groups A, B, C and D or non-hazardous locations only.

Warning - Explosion Hazard - Batteries Must Only Be Changed In An Area Known To Be Non-Hazardous.

The lithium battery shall only be replaced by a trained technician.

WARNING

Replacing components

EXPLOSION HAZARD

WARNING - SUBSTITUTION OF COMPONENTS MAY IMPAIR SUITABILITY FOR CLASS I, DIVISION 2 OR ZONE 2.

8.1 Certificates and approvals

| Reference designation | Description | Type of Protection |
|--------------------------------|-------------|--------------------|
| Hard Disk Drive on Motherboard | HDD | Brushless Motor |

| Federal Commu- nications Commis- sion Radio Frequency Interference Statement | This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to Part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense. |
|---|---|
| Shielded Cables | Shielded cables must be used with this equipment to maintain compliance with FCC regulations. |
| Modifications | Changes or modifications not expressly approved by the manufacturer could void the user's authority to operate the equipment. |
| Conditions of Operations | This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation. |

| CANADA | | |
|-----------------|--|--|
| Canadian Notice | This Class A digital apparatus complies with Canadian ICES-003. | |
| Avis Canadien | Cet appareil numérique de la classe A est conforme à la norme NMB- 003 du Canada. | |

RCM AUSTRALIA/NEW ZEALAND



C

This product meets the requirements of EN 61000-6-4 Generic standards – Emission standard for industrial environments.

This product meets the requirements of the standard EN 61000-6-4 Generic standards – Emission standard for industrial environments.

8.1.1 KC Mark (Korea)

This product meets the requirements of Korean certification.

This product satisfies the requirement of the Korean Certification (KC Mark).

이 기기는 업무용(A급) 전자파 적합기기로서 판매자 또는 사용자는 이 점을 주의하시기 바라며 가정 외의 지역에서 사용하는 것을 목적으로 합니다. 8.2 Directives and declarations

8.2 Directives and declarations

8.2.1 CE marking

((

The device meets the guidelines listed in the following sections.

EU Declaration of Conformity

The associated declaration of conformity is available on the Internet at the following address: Panel PC certificates (http://support.automation.siemens.com/WW/view/en/10805572/134200).

Electromagnetic compatibility

This product meets the requirements of EC Directive 2004/108/EC "Electromagnetic Compatibility".

The device is designed for the following areas of application corresponding to the CE marking:

| Scope of application | Requirements for | |
|----------------------|-----------------------|--------------------------|
| | Interference emission | Immunity to interference |
| Industrial area | EN 61000-6-4 +A1 | EN 61000-6-2 |

The devices with AC power supply comply with the standards EN 61000-3-2 +A1 +A2 (harmonic currents) and EN 61000-3-3 (voltage fluctuations and flicker).

Low-voltage directive

The device with AC power supply complies with the requirements of the EU Directive 2014/35/EU "Low Voltage Directive". Compliance with this standard has been verified according to EN 60950-1 +A11 +A1 +A12 +A2.

8.2.2 ESD guideline

What does ESD mean?

An electronic module is equipped with highly integrated components. Due to their design, electronic components are highly sensitive to overvoltage and thus to the discharge of static electricity. Such electronic components or modules are labeled as electrostatic sensitive devices.

The following abbreviations are commonly used for electrostatic sensitive devices:

- ESD Electrostatic sensitive device
- ESD Electrostatic Sensitive Device as a common international designation

Electrostatic sensitive devices can be labeled with an appropriate symbol.



NOTICE

Damage to ESD from touch

Electrostatic sensitive devices, ESD, can be destroyed by voltages which are far below the human perception limit. If you touch a component or electrical connections of a module without discharging any electrostatic energy, these voltages may arise.

The damage to a module by an overvoltage can often not be immediately detected and only becomes evident after an extended period of operation. The consequences are incalculable and range from unforeseeable malfunctions to a total failure of the machine or system.

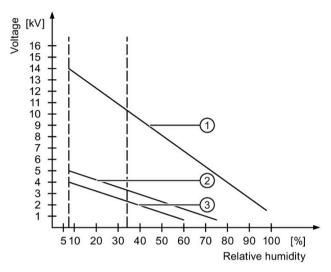
Avoid touching components directly. Make sure that persons, the workstation and the packaging are properly grounded.

8.2 Directives and declarations

Charge

Every person without a conductive connection to the electrical potential of his/her surroundings can be electrostatically charged.

The material with which this person comes into contact is of particular significance. The figure shows the maximum electrostatic voltages with which a person is charged, depending on humidity and material. These values conform to the specifications of IEC 61000-4-2.



- ① Synthetic materials
- 2 Wool
- ③ Antistatic materials such as wood or concrete

NOTICE

Grounding measures

There is no equipotential bonding without grounding. An electrostatic charge is not discharged and may damage the ESD.

Protect yourself against discharge of static electricity. When working with electrostatic sensitive devices, make sure that the person and the workplace are properly grounded.

8.2 Directives and declarations

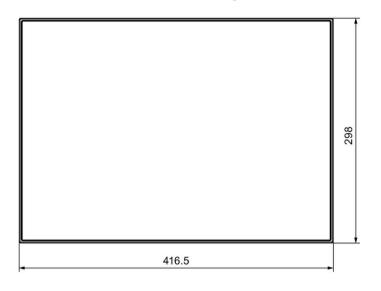
Protective measures against discharge of static electricity

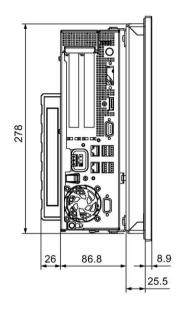
- Disconnect the power supply before you install or remove modules which are sensitive to ESD.
- Pay attention to good grounding:
 - When handling electrostatical sensitive devices, make sure that persons, the workstation and devices, tools and packaging used are properly grounded. This way you avoid static discharge.
- Avoid direct contact:
 - As a general rule, do not touch electrostatic sensitive devices, except in the case of unavoidable maintenance work.
 - Hold the modules at their edge so that you do not touch the connector pins or conductor paths. This way, the discharge energy does not reach and damage the sensitive components.
 - Discharge your body electrostatically before you take a measurement at a module. Do so by touching grounded metallic parts. Always use grounded measuring instruments.

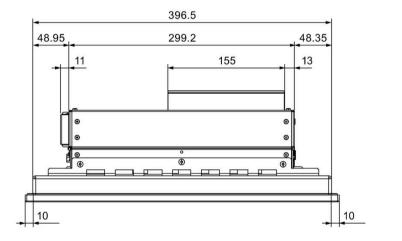
8.3 Dimension drawings

8.3 Dimension drawings

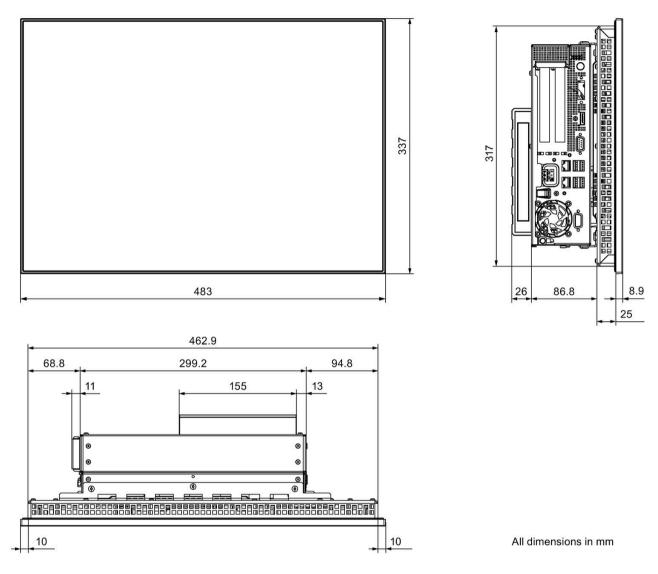
8.3.1 Dimension drawing of 15" device with capacitive multi-touch screen







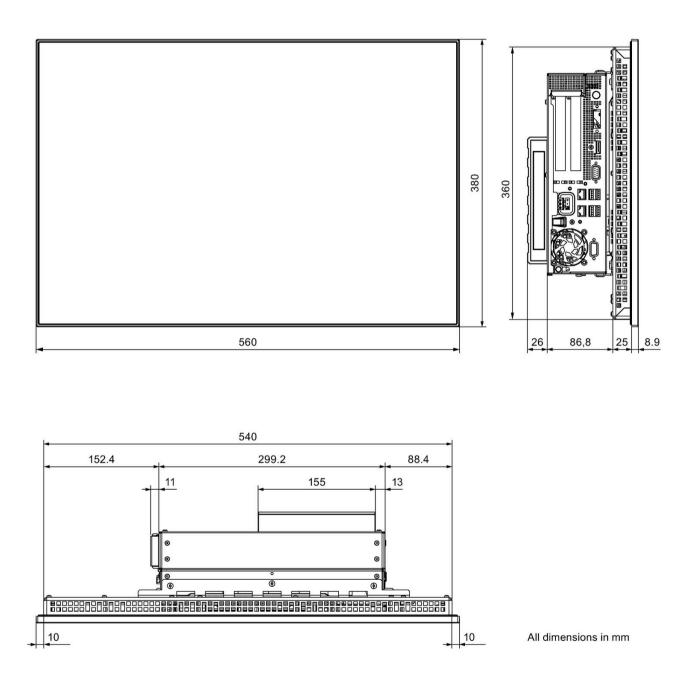
All dimensions in mm



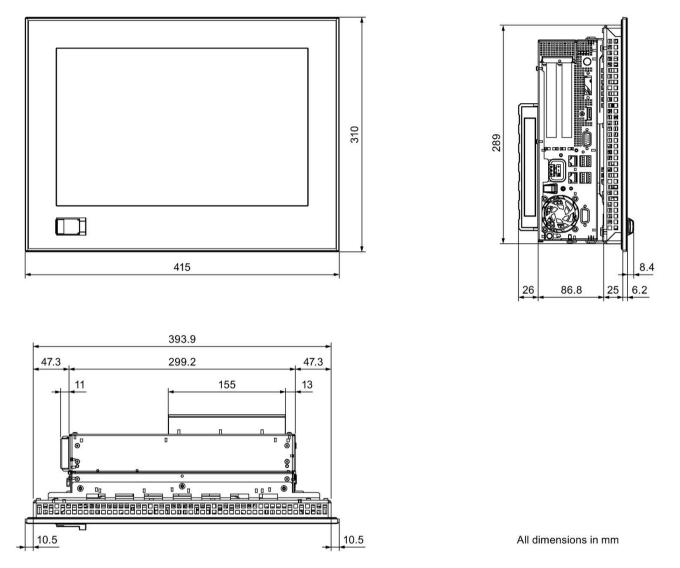
8.3.2 Dimension drawing of 19" device with capacitive multi-touch screen

8.3 Dimension drawings

8.3.3 Dimension drawing of 22" device with capacitive multi-touch screen

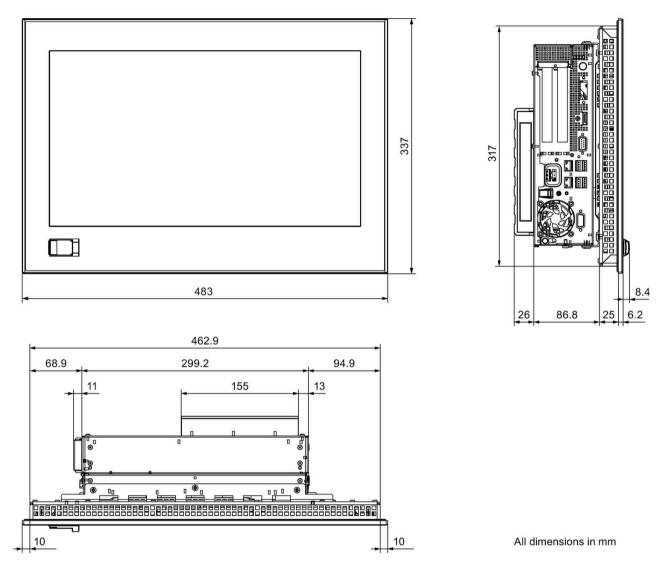


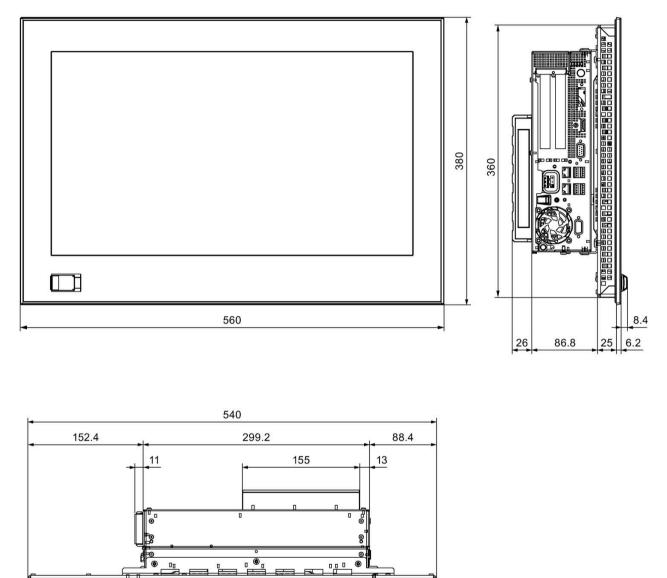
8.3.4 Dimension drawing of 15" device with resistive single touch screen



8.3 Dimension drawings

8.3.5 Dimension drawing of 19" device with resistive single touch screen





8.3.6 Dimension drawing of 22" device with resistive single touch screen

All dimensions in mm

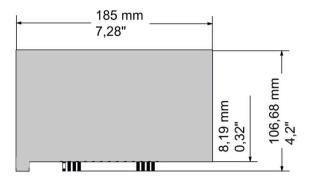
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8.3 Dimension drawings

8.3.7 Dimensional drawing for the installation of expansion cards

Short PCI or PCIe expansion card



8.4.1 General technical specifications

| Order numbers | See order documents | | |
|--|--|-------------------------------|----------------------|
| Weight | 15" | 19" | 22" |
| | 12 kg | 14 kg | 16 kg |
| Supply voltage AC | Nominal 100-240 V AC (-15% / +10%) (autorange) | | torange) |
| Supply voltage DC ¹ | Nominal 24 V DC (-20 | % / + 20%), SELV ¹ | |
| Input current AC | Continuous current up | to 2.5 A (up to 50 A | for 1 ms at startup) |
| Input current DC | Continuous current up | to 8 A (up to 14 A fo | or 20 ms at startup) |
| Line voltage frequency | 50-60 Hz (47 to 63 Hz | .) | |
| Short-term voltage interruption in accordance with Namur | max. 20 ms (at 93 to 264 V) (max. 10 events per hour; recovery time at least 1 s) | | t least 1 s) |
| Power consumption | • AC: 190 W | | |
| | • DC: 210 W | | |
| Degree of protection | On the front: IP 65 | | |
| | At the rear: IP 20 acco | ording to IEC 60529 | |
| Protection class | Protection class I to IEC 61140 | | |
| Safety specifications | EN 60950-1; UL508; CSA C22.2 No 142 | | |
| Noise emission | < 55 dB(A) according to EN ISO 7779 | | |
| Quality assurance | In accordance with IS | O 9001 | |

¹ The device should only be connected to a 24 V DC power supply which meets the requirements of safe extra low voltage (SELV) according to IEC/EN/DIN EN 60950-1. A protective conductor must also be used (see section "Connecting the 24 VDC power supply (Page 48)").

Electromagnetic compatibility

| Interference emission | EN 61000-6-3, EN 61000-6-4, CISPR22 class A; FCC class A |
|---|---|
| Immunity with regard to conduct- ed interference on the supply lines | ± 2 kV according to IEC 61000-4-4; burst ± 1 kV according to IEC 61000-4-5; symmetrical surge ± 2 kV according to IEC 61000-4-5; asymmetrical surge |
| Noise immunity on signal lines | ± 1 kV to IEC 61000-4-4; Burst; Length < 3 m ± 2 kV in accordance with IEC 61000-4-4; Burst; length > 3 m ± 2 kV in accordance with IEC 61000-4-5; Surge; length > 30 m |
| Immunity to electrostatic dis- charge | ± 6 kV contact discharge in accordance with IEC 61000-4-2 ± 8 kV air discharge in accordance with IEC 61000-4-2 |
| Immunity to RF interference | 10 V/m 80 MHz - 2.7 GHz, 80% AM according to IEC 61000-4-3 3 V/m 2.7–6 GHz, 80% AM according to IEC 61000-4-3 10 V 10 KHz–80 MHz, 80% AM according to IEC 61000-4-6 |
| Immunity to magnetic fields | 100 A/m, 50/60 Hz according to IEC 61000-4-8 |

Motherboard

| Chipset | Intel DH82C226 PCH | |
|----------------------|---|--|
| Processor | Intel Xeon E3-1268L v3 2.3 (3.3) GHz, 4 cores, 8 threads, GT2, 8 MB second level cache, HT, AMT | |
| | Intel Core i3-4330TE 2.4 GHz, 2 cores, 4 threads, GT2, 3 MB second level cache | |
| | Intel Celeron G1820TE 2.2 GHz, 2 cores, 2 threads, GT1, 2 MB second level cache | |
| Main memory | Expansion options | |
| | • 2 GB, 4 GB, 8 GB, 16 GB without ECC | |
| | • 4 GB, 8 GB, 16 GB with ECC | |
| Buffer memory | 2 MB SRAM | |
| Expansion card slots | 1 × PCI 185 mm long and 1 × PCI 185 mm long 1 × PCI 185 mm long and 1 × PCIe x16 185 mm long 1 × PCIe x16 185 mm long and 1 × PCIe x4 185 mm long | |

Drive and memory media

| Hard disk drive | 1 × 3.5" SATA HD |
|------------------|--|
| | 2 × 2.5" SATA HD |
| Solid State Disk | 1 × 2.5" SATA SSD, ≥ 240 GB standard |
| DVD burner *2 | Serial ATA, See order documentation for features |

Display

| | 15" ¹ | 15" ² | 19" | 22" |
|--|---|--------------------|--------------------|---|
| Display type | LCD TFT with extended view- ing angle | LCD TFT | LCD TFT | LCD TFT with extended view- ing angle |
| Degree of protection on the front | IP 65 | IP 65 | IP 65 | IP 66 |
| Active display area | 331 x 207 mm | 364 mm x 216 mm | 410 mm x 230 mm | 475 mm x 267 mm |
| Resolution | 1280 x 800 | 1366 x 768 | 1366 x 768 | 1920 x 1080 |
| | Pixels | Pixels | Pixels | Pixels |
| Displayable colors | Up to 16.7 million | | | |
| Brightness control | Yes, value range 0 to 99 ³ 0 = backlighting off | | | |
| Backlighting | LED | LED | LED | LED |
| Half Brightness Life Time (MTBF ⁴³) | 80000 h | 70000 h | 50000 h | 30000 h |
| Pixel error class in accord- ance with ISO 9241-307 | II | | | |
| Contact force resistive touch screen | With test stylus, 2 mm diameter: 5 N | | | |
| Power consumption | 25 W | 25 W | 25 W | 32 W |

¹ resistive touch screen only

- ² capacitive touch screen only
- ³ Via SetBrightness dialog: 9 to 99 (≙ 10% to 100%), via SetBrightness command line call: 0 to 99
- ⁴ MTBF: Operating hours after which the maximum brightness is reduced by half compared to the original value. MTBF is increased by using the integrated dimming function, for example, timecontrolled via screen saver or centrally via PROFlenergy.

Graphics

| Graphic controller | Xeon: Intel® HD Graphics Controller P4600 GT2 Core i3: Intel® HD Graphics Controller P4600 GT2 Celeron: Intel® HD Graphics Controller (GT1) |
|--------------------------------------|---|
| Graphics memory | 32 - 512 MB Shared Memory |
| Resolution / frequency / col- ors | Display Port (Spec. V1.2) : max. 3840 x 2160 / 60 Hz / 32-bit DVI-D : max. 1920 x 1200 / 60 Hz / 32 Bi VGA: max. 1920 x 1200 / 60 Hz / 32-bit |

Interfaces

| DVI-I | Connection of DVI display devices | | |
|--------------------------------|--|--|--|
| DisplayPort | Connection of DisplayPort display devices | | |
| Keyboard | USB support | | |
| Mouse | USB support | | |
| USB | 4 × USB 3.0, max. 2 can be simultaneously operated as high current | | |
| | Front USB 3.0 for device with resistive single touch | | |
| PROFIBUS / MPI interface, | 9-pin Cannon socket, 2-row | | |
| isolated | Transmission speed: | | |
| | 9.6 kbps to 12 Mbps | | |
| | Operating modes: | | |
| | DP master: DP-V0, DP-V1 with SOFTNET DP | | |
| | DP slave: DP-V0, DP-V1 with SOFTNET-DP slave | | |
| PROFINET ³ | RJ45 connection, CP1616 compatible, | | |
| | onboard interface based on ERTEC 400, | | |
| | 10/100 Mbps, electrically isolated | | |
| Ethernet ³ | 2 × Ethernet port (RJ45) Intel WGI217LM and Intel WGI210IT, | | |
| | 10/100/1000 Mbps, electrically isolated, | | |
| | Wake on LAN, remote boot, | | |
| | teaming and Jumbo frames up to 9014 bytes are supported 4.5 | | |
| COM1 | RS232, 115 kbps max., 9-pin SUB-D, male | | |
| Free slots for expansion cards | 2 PCI/PCIe cards | | |

³ For unique labeling, the Ethernet ports are numbered on the enclosure. The numbering by the operating system can differ.

⁴ No teaming with AMT.

⁵ When using AMT, the interface x1 p1 must be used for connection to remote maintenance.

8.4.2 Ambient conditions

Climatic ambient conditions

| Ambient temperature, tested according to IEC 60068-2-1, IEC 60068-2-2, IEC 60068-2-14 | | | | |
|---|--|--|--|--|
| In operation, horizontal format, vertical instal- lation ¹² | + 5 °C to + 45 °C | | | |
| In operation, horizontal format, inclined instal- lation ² | + 5 °C to + 40 °C | | | |
| In operation, vertical format, vertical installa- tion ² | + 5 °C to + 45 °C | | | |
| Storage/transportation | – 20° C to +60° C | | | |
| Gradient | max. 10° C/h in operation, 20° C/h storage, no con- densation | | | |

¹ DVD burner operation is only permitted with ambient temperatures of +5°C to +40 °C

² The total power for USB and PCI/PCIe expansions cannot exceed 30 W, no DVD operation

| Relative humidity, tested in accordance with IEC 60068-2-78, IEC 60068-2-30 | | | |
|---|--|--|--|
| During operation 5 °C to 31 °C: 5% to 80% (no condensation): | | | |
| | linear decrease down to 5% to 25% at 45 °C (no condensation) | | |
| Storage/transportation | 5% to 95 % at 25° C (no condensation) | | |

| Atmospheric pressure | |
|------------------------|---|
| During operation | 1080 to 795 hPa (corresponds to an altitude of -1000 to 2000 m) |
| Storage/transportation | 1080 to 660 hPa (corresponds to an altitude of -1000 to 3500 m) |

Mechanical ambient conditions

| Vibration, tested according to DIN IEC 60068-2-6 | | |
|---|---|--|
| During operation | 10 to 58 Hz: 0.075 mm, 58 to 500 Hz: 9.8 m/s ² | |
| Storage/transportation 5 to 9 Hz: 3.5 mm, 9 to 500 Hz: 9.8 m/s ² | | |

| Shock resistance, tested in accordance with IEC 60068-2-27, IEC 60068-2-29 | | | |
|--|----------------|--|--|
| During operation ¹ | 50 m/s², 30 ms | | |
| Storage/transport 1 | 250 m/s², 6 ms | | |

Restriction for DVD burners: Read, write and burner operation only permitted in an interferencefree environment.

8.4.3 Current and power requirements

Maximum current values

| Component | Voltage | | | | | | | |
|--|---------|-------|------|------|--------|-------|-------|-------|
| | +5 | v | +3 | .3 V | +1 | 2 V | -1: | 2 V |
| Base device ^{1, 2} | | | | | 7. | 5 A | | |
| Hard disk drive 1 × 3.5" ² | 0.6 A | | | | 0.5 A | | | |
| Hard disk drives 2 × 2.5" ² | 1.2 | 2 A | | | | | | |
| SSD drive (SATA) 1 x 2.5" ² | 0.8 | 0.8 A | | | | | | |
| DVD burner drive ² | 0.8 A | | | | | | | |
| USB ports ^{3 4} | 2 | A | | | | | | |
| PCI/PCIe slots ⁴ total | 4 A | | 6 A | | 2 A | | 0.1 A | |
| Maximum per PCI slot | | 4 A | | 6 A | | 0.5 A | | 0.1 A |
| Maximum per PCIe slot | | - | | 3 A | | 2 A | | - |
| Internal front interfaces for Panel PC | | | | | 2.41 A | | | |
| Individual currents (max. permissible) 5 | 14 A | | 14 A | | 12.5 A | | 0.3 A | |

¹ Base device includes motherboard, processor, memory, both fans, CF

² Depends on the selected device configuration

³ 2 × USB3.0 high current and 2 × USB2.0 low current.

⁴ The power for individual PCI/PCIe slots cannot exceed 25 W. The total power for USB and PCI/PCIe slots cannot exceed 30 W.

⁵ The max. permitted accumulated power of +5 V and +3.3 V is 60 W.

Typical power values

| Component | Current consump- tion 230 VAC | Current consump- tion 24 VDC | Power consumption 0.85 efficiency |
|---------------------------|-------------------------------------|------------------------------------|--------------------------------------|
| | | | |
| Base device | 0.3 A | 3.0 A | 70 W |
| Hard disk drive 1 × 3.5" | 0.04 A | 0.38 A | 9 W |
| Hard disk drives 2 × 2.5" | 0.03 A | 0.25 A | 6 W |
| SSD drive (SATA) 1 x 2.5" | 0.02 A | 0.17 A | 7 W |
| DVD burner drive | 0.02 A | 0.17 A | 4 W |
| USB ports | max. 0.06 A | max. 0.54 A | max. 13 W |
| PCI/PCIe slots | 0.16 A max. | 1.54 A max. | Max. 37 W |
| Operator panel | max 0.14 A | max. 1.33 A | max. 32 W |

8.4.4 AC voltage supply

Technical data

Note

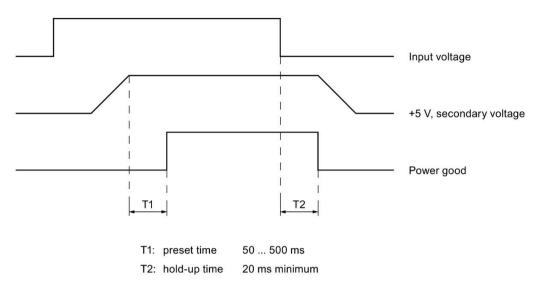
The power supply contains an active PFC (Power Factor Correction) circuit to conform to the EMC guidelines.

Uninterruptible AC power systems (UPS) must supply a sinusoidal output voltage in the normal and buffered mode when used with SIMATIC PCs with an active PFC.

UPS characteristics are described and classified in the standards EN 50091-3 and IEC 62040-3. Devices with sinusoidal output voltage in the normal and buffered mode are identified with the classification "VFI-SS-...." or "VI-SS-....".

| Power supply characteristics | AC power supply | | |
|-------------------------------------|---|--|--|
| Input data | | | |
| Voltage | Nominal 100 - 240 V AC (-15% / +10%), wide range | | |
| Continuous current | Max. 1.7 A for 20 ms | | |
| Starting current (load-independent) | Max. 132 A for a half-value time of 0.8 ms | | |
| l²t | Max. 9.5 A ² s | | |
| Active power | 176 W | | |
| Apparent power | 190 VA | | |
| Output data | | | |
| Voltages | +12 V / 12.5 A | | |
| Secondary power output | Max. 150 W | | |

Power Good signal of the AC power supply

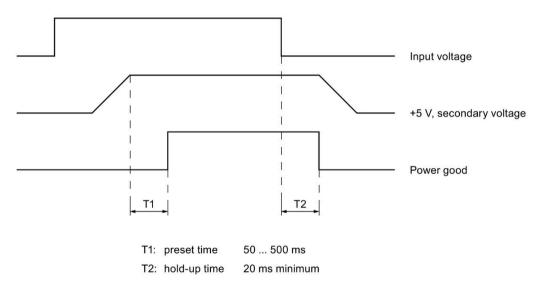


8.4.5 DC power supply

Technical data

| Power supply characteristics | DC power supply | | |
|--|---------------------------------|--|--|
| Input data | | | |
| Voltage Nominal 24 V DC (-20% / +20%), SELV, | | | |
| Continuous current | Max. 8 A | | |
| Starting current (load- independent) | Max. 13 A for a period of 50 ms | | |
| l²t | Max. 3.5 A²s | | |
| Active power | 176 W | | |
| Output data | | | |
| Voltages | +12 V / 12.5 A | | |
| Secondary power output | Max. 150 W | | |

Power Good signal of the DC power supply



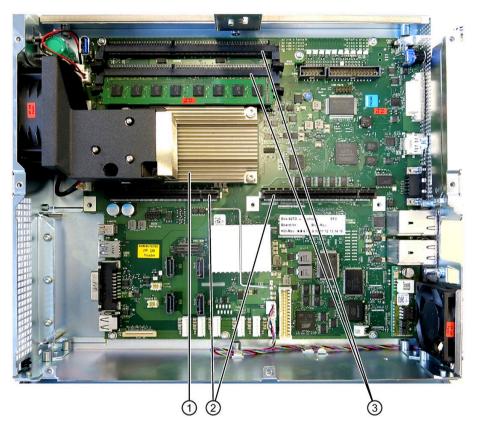
8.5 Hardware descriptions

8.5 Hardware descriptions

8.5.1 Motherboard

8.5.1.1 Structure and functions of the motherboard

The essential components of the motherboard are the processor and the chip set, two slots for memory modules, internal and external interfaces and the Flash BIOS.



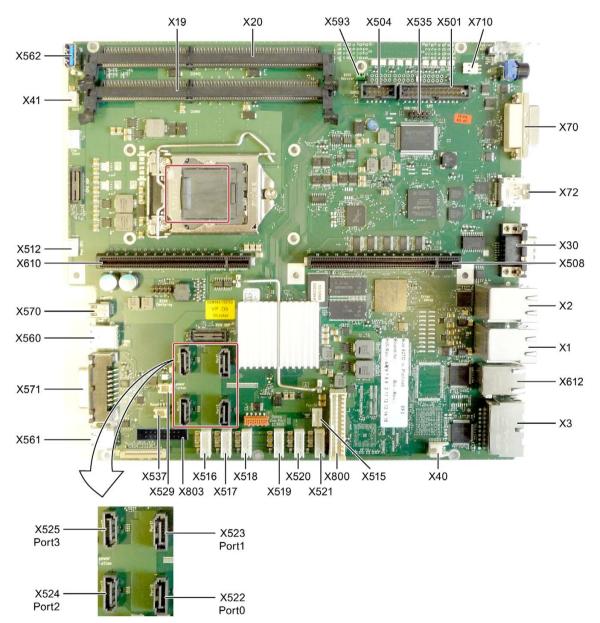
| 1 | Processor heat sink |
|---|-------------------------|
| 2 | Slot for the bus board |
| 3 | Two memory module slots |

8.5.1.2 Position of the interfaces on the motherboard

Interfaces

The motherboard of the device features the following interfaces:

- Interfaces for the connection of external devices
- Interfaces for internal components (drives, bus boards etc.)



8.5 Hardware descriptions

8.5.1.3 Internal interfaces

Pin assignment of the internal interfaces

| Interface | Posi- tion | Connector | Description |
|---------------------------------|---------------|---------------------------------------|---|
| Memory | Inter- nal | X19, X20 | 2 DIMM sockets, 64-bit |
| Bus expansion | Inter- nal | X508, X610 | Socket for bus expansion, assigned PCI bus sig- nals |
| Power supply | Inter- nal | X800 | 20-pin connector plug for power supply |
| BIOS Recovery | Inter- nal | X593 | Jumper: Jumper on pins 2-3: default Replug to pins 3-4 for BIOS Recovery* Replug to pins 1-2 for ME Update* * USB memory stick required |
| Serial ATA | Inter- nal | X522, X523, X524, X525 | Serial ATA, max. 3 drives operable |
| Connection for PS serial ATA | Inter- nal | X516, X517, X518, X519, X520, X521 | Voltage supply for serial ATA |
| Connection for PS fan | Inter- nal | X515 | Voltage supply for CPU fan, 4-pin male connector |
| Connection for equipment fan | Inter- nal | X512 | Voltage supply for equipment fan, 4-pin male connector |
| Backup battery | Inter- nal | X40, X41 | Voltage supply for backup battery, 2-pin male connector |
| USB port | Inter- nal | X535 | USB channel 6 and 7, 10-pole male connector On expansion card (optional) guided (see section "Operator controls and interfaces") |
| USB port | Inter- nal | X562 | USB channel 9, upright USB socket |
| Spare HDD | Inter- nal | X803 | LED display |

Pin assignment of the device fan supply, X512

| Pin no. | Short description | Meaning | Input/Output |
|---------|-------------------|-------------------------|--------------|
| 1 | GND | Ground | - |
| 2 | +12 V | Switched voltage supply | Output |
| 3 | CPU FAN_CLK | Clock signal | Input |
| 4 | PWM | PWM signal | Output |

| Pin no. | Short description | Meaning | Input/Output |
|---------|-------------------|-------------------------|--------------|
| 1 | GND | Ground | - |
| 2 | +12 V | Switched voltage supply | Output |
| 3 | PG1 FAN_CLK | Clock signal | Input |
| 4 | PWM | PWM signal | Output |

Pin assignment of the supply for the power supply fan, X515

Pin assignment of serial ATA voltage supply, X516 - X521

| Pin no. | Short description | Meaning | Input/Output | |
|---------|-------------------|-----------------------|--------------|--|
| 1 | +12 V | Voltage +12 V | Output | |
| 2 | GND | Ground - | | |
| 3 | GND | Ground - | | |
| 4 | +5 V | Voltage +5 V Output | | |
| 5 | +3.3 V | Voltage +3.3 V Output | | |

Connector for backup battery, X40, X41

A battery for buffering the CMOS RAM is connected to this connector. This is a 3 V Lithium battery with a capacity of 750 mAh.

| Pin no. | Short description | Meaning | Input/Output |
|---------|-------------------|------------|--------------|
| 1 | + | Plus pole | Input |
| 2 | - | Minus pole | - |

8.5 Hardware descriptions

8.5.1.4 Front ports

Overview

| Interface | Position | Connect- | Description |
|-----------|----------|----------|--|
| | | or | |
| Display | Internal | X570 | Connection of LC displays |
| I/O front | Internal | X571 | Interface for I/O front |
| USB 2.0 | Internal | X561 | Internal USB 2.0 interface (USB channel 6) |
| USB 3.0 | Internal | X560 | Internal USB 3.0 interface (USB channel 3) |

See also

Industry Automation and Drive Technologies - Homepage (http://www.siemens.com/automation/service&support)

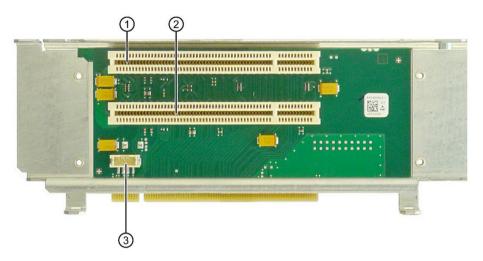
8.5.2 Bus board

8.5.2.1 Layout and principle of operation

The bus board is designed as a link between the motherboard and the expansion cards. It is secured with five screws.

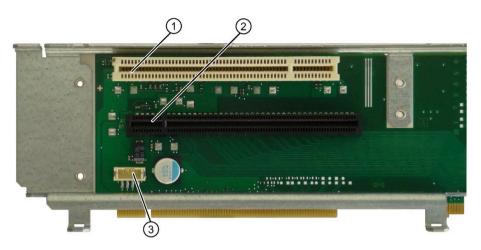
The following bus board models are available:

Variant 1 has two PCI slots. It can host expansion modules conforming to PCI specification (Rev. 2.2) for 5 V and 3.3 V modules. All PCI slots are master compatible. The expansion modules are supplied with power via the bus board to motherboard connection.



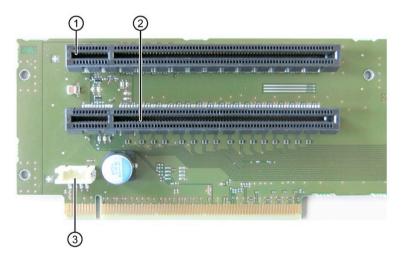
| 1 | Slot 1 PCI (TIA Portal: X100) |
|---|-------------------------------|
| 2 | Slot 2 PCI (TIA Portal: X101) |
| 3 | 12 V power supply connection |

Variant 2 has one PCI and one PCIe slot.



| 1 | Slot 1 PCI (TIA Portal: X100) |
|---|---|
| 2 | Slot 2 PCI Express x16 (TIA Portal: X101) |
| 3 | 12 V power supply connection |

Variant 3 has two PCIe slots.



| 1 | Slot 1 PCI Express x4, mechanical x16 (TIA Portal: X100) |
|---|--|
| 2 | Slot 2 PCI Express x16 (TIA Portal: X101) |
| 3 | 12 V power supply connection |

8.5.2.2 PCI slot pin assignment

| | 5V System Environme | 5V System Environment | |
|----|---------------------|-----------------------|--|
| | Side B | Side A | |
| 1 | -12V | TRST# | |
| 2 | тск | TCK +12V | |
| 3 | Ground | TMS | |
| 4 | TDO | TDI | |
| 5 | +5V | +5V | |
| 6 | +5V | INTA# | |
| 7 | INTB# | INTC# | |
| 8 | INTD# | +5V | |
| 9 | PRSNT1# | Reserved | |
| 10 | Reserved | +5 V (I/O) | |
| 11 | PRSNT2# | Reserved | |
| 12 | Ground | Ground | |
| 13 | Ground | Ground | |
| 14 | Reserved | Reserved | |
| 15 | Ground | RST# | |
| 16 | CLK | +5 V (I/O) | |
| 17 | Ground | GNT# | |
| 18 | REQ# | Ground | |
| 19 | +5 V (I/O) | Reserved | |
| 20 | AD[31] | AD[30] | |
| 21 | AD[29] | +3.3V | |
| 22 | Ground | AD[28] | |
| 23 | AD[27] | AD[26] | |
| 24 | AD[25] | Ground | |
| 25 | +3.3V | AD[24] | |
| 26 | C/BE[3]# | IDSEL | |
| 27 | AD[23] | +3.3V | |
| 28 | Ground | AD[22] | |
| 29 | AD[21] | AD[20] | |
| 30 | AD[19] | Ground | |
| 31 | +3.3V | AD[18] | |
| 32 | AD[17] | AD[16] | |
| 33 | C/BE[2]# | +3.3V | |
| 34 | Ground | FRAME# | |
| 35 | IRDY# | Ground | |
| 36 | +3.3V | TRDY# | |
| 37 | DEVSEL# | Ground | |
| 38 | Ground | STOP# | |
| 39 | LOCK# | +3.3V | |

| | 5V System Environme | 5V System Environment | |
|----|---------------------|-----------------------|--|
| | Side B | Side A | |
| 40 | PERR# | SDONE | |
| 41 | +3.3V | SBO# | |
| 42 | SERR# | Ground | |
| 43 | +3.3V | PAR | |
| 44 | C/BE[1]# | AD[15] | |
| 45 | AD[14] | +3.3V | |
| 46 | Ground | AD[13] | |
| 47 | AD[12] | AD[11] | |
| 48 | AD[10] | Ground | |
| 49 | Ground | AD[09] | |
| 50 | CONNECTOR KEY | CONNECTOR KEY | |
| 51 | CONNECTOR KEY | | |
| 52 | AD[08] | C/BE[0]# | |
| 53 | AD[07] | +3.3V | |
| 54 | +3.3V | AD[06] | |
| 55 | AD[05] | AD[04] | |
| 56 | AD[03] | Ground | |
| 57 | Ground | AD[02] | |
| 58 | AD[01] | AD[00] | |
| 59 | +5 V (I/O) | +5 V (I/O) | |
| 60 | ACK64# | REQ64# | |
| 61 | +5V | +5V | |
| 62 | +5V | +5V | |

8.5.2.3 Pin assignment 12 V power supply connection for expansion cards

| Pin | Short description | Meaning | Input/Output |
|-----|-------------------|--------------|--------------|
| 1 | +12 V 1 | 12 V voltage | Output |
| 2 | GND | Ground | - |
| 3 | GND | Ground | - |
| 4 | +5 V 1 | 5 V voltage | Output |

¹ max. permitted current: 1 A; with this power demand the total power demand for the PCI slots are not allowed to be exceeded.

8.5.2.4 PCI Express slot x16 pin assignment

| Signal | Pin no. | Pin no. | Signal |
|------------------|---------|---------|------------------|
| P12V | B1 | A1 | P12V |
| P12V | B2 | A2 | P12V |
| P12V | B3 | A3 | P12V |
| GND | B4 | A4 | GND |
| SMB_CLK2 | B5 | A5 | n.c. |
| SMB_DATA2 | B6 | A6 | n.c. |
| GND | B7 | A7 | n.c. |
| P3V3 | B8 | A8 | n.c. |
| n.c. | B9 | A9 | P3V3 |
| AUX_3V | B10 | A10 | P3V3 |
| WAKE2 | B11 | A11 | PCIE_RESET_L |
| n.c. | B12 | A12 | GND |
| GND | B13 | A13 | PCIE0_ECLK |
| PCIEX16_TX_P(15) | B14 | A14 | PCIE0_ECLK_N |
| PCIEX16_TX_N(15) | B15 | A15 | GND |
| GND | B16 | A16 | PCIEX16_RX_P(15) |
| SDVO_CTRLCLK | B17 | A17 | PCIEX16_RX_N(15) |
| GND | B18 | A18 | GND |
| PCIEX16_TX_P(14) | B19 | A19 | n.c. |
| PCIEX16_TX_N(14) | B20 | A20 | GND |
| GND | B21 | O21 | PCIEX16_RX_P(14) |
| GND | B22 | A22 | PCIEX16_RX_N(14) |
| PCIEX16_TX_P(13) | B23 | A23 | GND |
| PCIEX16_TX_N(13) | B24 | A24 | GND |
| GND | B25 | A25 | PCIEX16_RX_P(13) |
| GND | B26 | A26 | PCIEX16_RX_N(13) |
| PCIEX16_TX_P(12) | B27 | A27 | GND |
| PCIEX16_TX_N(12) | B28 | A28 | GND |
| GND | B29 | A29 | PCIEX16_RX_P(12) |
| n.c. | B30 | A30 | PCIEX16_RX_N(12) |
| SDVO_CTRLDATA | B31 | A31 | GND |
| GND | B32 | A32 | n.c. |
| PCIEX16_TX_P(11) | B33 | A33 | n.c. |
| PCIEX16_TX_N(11) | B34 | A34 | GND |
| GND | B35 | A35 | PCIEX16_RX_P(11) |
| GND | B36 | A36 | PCIEX16_RX_N(11) |
| PCIEX16_TX_P(10) | B37 | A37 | GND |
| PCIEX16_TX_N(10) | B38 | A38 | GND |
| GND | B39 | A39 | PCIEX16_RX_P(10) |
| GND | B40 | A40 | PCIEX16_RX_N(10) |
| PCIEX16_TX_P(9) | B 13 | A41 | GND |
| PCIEX16_TX_N(9) | B42 | A42 | GND |
| GND | B43 | A43 | PCIEX16_RX_P(9) |

| Signal | Pin no. | Pin no. | Signal |
|-----------------|---------|---------|-----------------|
| GND | B44 | A44 | PCIEX16_RX_N(9) |
| PCIEX16_TX_P(8) | B45 | A45 | GND |
| PCIEX16_TX_N(8) | B46 | A46 | GND |
| GND | B47 | A47 | PCIEX16_RX_P(8) |
| MCH_CFG_20 | B48 | A48 | PCIEX16_RX_N(8) |
| GND | B49 | A49 | GND |
| PCIEX16_TX_P(7) | B50 | A50 | n.c. |
| PCIEX16_TX_N(7) | B51 | A51 | GND |
| GND | B52 | A52 | PCIEX16_RX_P(7) |
| GND | B53 | A53 | PCIEX16_RX_N(7) |
| PCIEX16_TX_P(6) | B54 | A54 | GND |
| PCIEX16_TX_N(6) | B55 | A55 | GND |
| GND | B56 | A56 | PCIEX16_RX_P(6) |
| GND | B57 | A57 | PCIEX16_RX_N(6) |
| PCIEX16_TX_P(5) | B58 | A58 | GND |
| PCIEX16_TX_N(5) | B59 | A59 | GND |
| GND | B60 | A60 | PCIEX16_RX_P(5) |
| GND | B61 | A61 | PCIEX16_RX_N(5) |
| PCIEX16_TX_P(4) | B62 | A62 | GND |
| PCIEX16_TX_N(4) | B63 | A63 | GND |
| GND | B64 | A64 | PCIEX16_RX_P(4) |
| GND | B65 | A65 | PCIEX16_RX_N(4) |
| PCIEX16_TX_P(3) | B66 | A66 | GND |
| PCIEX16_TX_N(3) | B67 | A67 | GND |
| GND | B68 | A68 | PCIEX16_RX_P(3) |
| GND | B69 | A69 | PCIEX16_RX_N(3) |
| PCIEX16_TX_P(2) | B70 | A70 | GND |
| PCIEX16_TX_N(2) | B71 | A71 | GND |
| GND | B72 | A72 | PCIEX16_RX_P(2) |
| GND | B73 | A73 | PCIEX16_RX_N(2) |
| PCIEX16_TX_P(1) | B74 | A74 | GND |
| PCIEX16_TX_N(1) | B75 | A75 | GND |
| GND | B76 | A76 | PCIEX16_RX_P(1) |
| GND | B77 | A77 | PCIEX16_RX_N(1) |
| PCIEX16_TX_P(0) | B78 | A78 | GND |
| PCIEX16_TX_N(0) | B79 | A79 | GND |
| GND | B80 | A80 | PCIEX16_RX_P(0) |
| n.c. | B81 | A81 | PCIEX16_RX_N(0) |
| n.c. | B82 | A82 | GND |

Note

This slot can also be used for PCIe x8, x4 and x1 modules.

8.5.3 External ports

8.5.3.1 COM1/COM2

| Serial por | Serial port COM1, 9-pin (plug) or COM2 | | | | | |
|------------|--|---------------------|----------------|--|--|--|
| | | | | | | |
| Pin no. | Short description | Meaning | Input / output | | | |
| 1 | DCD | Data carrier detect | Input | | | |
| 2 | RxD | Received data | Input | | | |
| 3 | TxD | Transmit data | Output | | | |
| 4 | DTR | Data terminal ready | Output | | | |
| 5 | GND | Ground | - | | | |
| 6 | DSR | Ready for operation | Input | | | |
| 7 | RTS | Request to send | Output | | | |
| 8 | CTS | Clear to send | Input | | | |
| 9 | RI | Incoming call | Input | | | |

8.5.3.2 DisplayPort

DisplayPort port

| Pin no. | Short description | Meaning | Input / output | |
|---------|-------------------|----------------------|----------------|--|
| 1 | ML_Lane0+ | DP data 0+ | Output | |
| 2 | GND | Ground | - | |
| 3 | ML_Lane0- | DP data 0- | Output | |
| 4 | ML_Lane1+ | DP data 1+ | Output | |
| 5 | GND | Ground | - | |
| 6 | ML_Lane1- | DP data 1- | Output | |
| 7 | ML_Lane2+ | DP data 2+ | Output | |
| 8 | GND | Ground | - | |
| 9 | ML_Lane2- | DP data 2- | Output | |
| 10 | ML_Lane3+ | DP data 3+ | Output | |
| 11 | GND | Ground | - | |
| 12 | ML_Lane3- | DP data 3- | Output | |
| 13 | CONFIG1 CAD | Cable Adapter Detect | Input | |
| 14 | CONFIG2 | Ground (PullDown) | - | |
| 15 | AUX_CH+ | Auxiliary channel+ | Bidirectional | |
| 16 | GND | Ground | - | |
| 17 | AUX_CH- | Auxiliary channel- | Bidirectional | |
| 18 | HPD | Hot Plug Detect | Input | |
| 19 | GND | Ground | - | |
| 20 | DP_PWR | +3.3V (fused) | Output | |

8.5.3.3 DVI-I

DVI-I port (standard socket)

| 1 | | | |
|---------|---|-------------------------------|----------------|
| Pin no. | Short description | Meaning | Input / output |
| 1 | TMDS Data2- | DVI data channel | Output |
| 2 | TMDS Data2+ | DVI data channel | Output |
| 3 | TMDS Data2/4 shield | Cable shield | |
| 4 | NC | | |
| 5 | NC | | |
| 6 | DDC clock (SCL) | Display Data Channel – Clock | Input / output |
| 7 | DDC data (SDA) | Display Data Channel – Data | Input / output |
| 8 | Analog vertical sync (VSYNC) | Analog Vertical Sync Signal | Output |
| 9 | TMDS Data1- | DVI data channel | Output |
| 10 | TMDS Data1+ | DVI data channel | Output |
| 11 | TMDS Data1/3 shield | Cable shield | |
| 12 | NC | | |
| 13 | NC | | |
| 14 | +5V power (VCC) | +5V power for DCC | Output |
| 15 | Ground (return for +5V, Hsync and Vsync) (GND) | Analog ground | |
| 16 | Hot Plug Detect | | |
| 17 | TMDS data 0- | DVI data channel | Output |
| 18 | TMDS data 0+ | DVI data channel | Output |
| 19 | TMDS Data0/5 shield | Cable shield | |
| 20 | NC | | |
| 21 | NC | | |
| 22 | TMDS clock shield | Cable shield | |
| 23 | TMDS clock+ | DVI clock channel | Output |
| 24 | TMDS clock- | DVI clock channel | Output |
| C1 | Analog red (R) | Analog Red Signal | Output |
| C2 | Analog green (G) | Analog Green Signal | Output |
| C3 | Analog blue (B) | Analog Blue Signal | Output |
| C4 | Analog horizontal sync (HSYNC) | Analog Horizontal Sync Signal | Output |
| C5 | Analog ground (analog R, G, & return) (GND) | Analog ground | |

8.5.3.4 Ethernet

| Ethernet | Ethernet RJ45 interface | | | | |
|----------|-------------------------|--|----------------|--|--|
| | | | | | |
| Pin no. | Short description | Meaning | Input / output | | |
| 1 | BI_DA+ | Bi-directional data A+ | Input/output | | |
| 2 | BI_DA- | Bi-directional data A- | Input/output | | |
| 3 | BI_DB+ | Bi-directional data B+ | Input/output | | |
| 4 | BI_DC+ | Bi-directional data C+ | Input/output | | |
| 5 | BI_DC- | Bi-directional data C- | Input/output | | |
| 6 | BI_DB- | Bi-directional data B- | Input/output | | |
| 7 | BI_DD+ | Bi-directional data D+ | Input/output | | |
| 8 | BI_DD- | Bi-directional data D- | Input/output | | |
| S | | Shield | - | | |
| | LED 1 | Off: 10 Mbps Green light: 100 Mbps Orange light: 1000 Mbps | - | | |
| | LED 2 | Lit: Active connection, e.g., to a hub Flashing: Activity | - | | |

8.5.3.5 USB 3.0

| USB 3.0 p | ort | | |
|-----------|-------------------|---------------|----------------|
| | | | |
| Pin no. | Short description | Meaning | Input / output |
| 1 | VBUS | + 5 V (fused) | Output |
| 2 | D- | Data line | Input / output |
| 3 | D+ | Data line | Input / output |
| 4 | GND | Ground | _ |
| 5 | RX- | Data line | Input |
| 6 | RX+ | Data line | Input |
| 7 | GND | Ground | _ |
| 8 | TX- | Data line | Output |
| 9 | TX+ | Data line | Output |

8.5.3.6 PROFIBUS

| PROFIBU | S interface, 9-pin (socket) | |
|---------|-----------------------------|---|
| | | |
| Pin no. | Short description | Meaning |
| 1-2 | NC | Not connected |
| 3 | LTG_B | Data line (I/O) |
| 4 | RTS_AS | Turn on PLC transmitter (O) |
| 5 | GND | Ground isolated |
| 6 | P5V_dp_fused | +5 V / max. 90 mA (fused) electrically isolated |
| 7 | NC | Not connected |
| 8 | LTG_A | Data line (I/O) |
| 9 | RTS_PG | PG Request to send (O) |

8.5.3.7 PROFINET

PROFINET LAN X3 Port P1, P2, P3

| PROFIN | ET interface | | |
|-------------------|-------------------|--------------------------------------|----------------|
| LED 1 | | | |
| Pin no. | Short description | Meaning | Input / output |
| 1 | RD+ | Receive data ² | Input |
| 2 | RD- | Receive data ² | Input |
| 3 | TD+ | Send data ² | Output |
| 4, 5 ¹ | SYMR | Internal 75 Ohm terminating resistor | _ |
| 6 | TD- | Receive data ² | Output |
| 7, 8 ¹ | SYMT- | Internal 75 Ohm terminating resistor | _ |
| S | | Shield | |
| | LED 1 | Lights up green: link | |
| | LED 2 | Lights up yellow: Activity | |

¹ Optional product variant

² Auto Negotiation and auto crossover are supported

8.5.4 System resources

8.5.4.1 Currently allocated system resources

All system resources (hardware addresses, memory allocation, interrupt assignment, DMA channels) are assigned dynamically by the BIOS or the Windows operating system, depending on the hardware equipment, drivers, installed expansion cards and connected external devices. Assignment is automatic and depends on the demanded resources of the connected devices and the inserted modules. Due to this configuration dependency, clear statements can only be made by determining them in relation to the system in the final configuration.

Procedure

Resources may be viewed as follows under Windows:

1. Press the "Windows key" and "R" simultaneously.

The "Run" dialog box opens.

- 2. Enter "msinfo32" in the "Open" field.
- 3. Click "OK" to confirm.

8.5.4.2 System resources used by the BIOS/DOS

The following table describes the system resources for the factory state of the device.

I/O address allocation

The following tables describe the system resources in the factory state of the device.

Static area

| | ddress ex) | Size [byte] | Description of the basic function | Alternative function |
|------|---------------|----------------|-----------------------------------|----------------------|
| From | То | | | |
| 0000 | 001F | 32 | DMA controller | |
| 0020 | 0021 | 2 | Programmable interrupt controller | |
| 0022 | 0023 | 2 | <not used=""></not> | |
| 0024 | 0025 | 2 | Programmable interrupt controller | |
| 0026 | 0027 | 2 | <not used=""></not> | |
| 0028 | 0029 | 2 | Programmable interrupt controller | |
| 002A | 002B | 2 | <not used=""></not> | |
| 002C | 002D | 2 | Programmable interrupt controller | |
| 002E | 002F | 2 | Motherboard resources | |
| 0030 | 0031 | 2 | Programmable interrupt controller | |
| 0032 | 0033 | 2 | <not used=""></not> | |

| I/O address Size (hex) [byte] | | | Description of the basic function | Alternative function |
|----------------------------------|------|----|-----------------------------------|----------------------|
| From | То | | | |
| 0034 | 0035 | 2 | Programmable interrupt controller | |
| 0036 | 0037 | 2 | <not used=""></not> | |
| 0038 | 0039 | 2 | Programmable interrupt controller | |
| 003A | 003B | 2 | <not used=""></not> | |
| 003C | 003D | 2 | Programmable interrupt controller | |
| 003E | 003F | 2 | <not used=""></not> | |
| 0040 | 0043 | 4 | System timer | |
| 0044 | 004D | 10 | <not used=""></not> | |
| 004E | 004F | 2 | Motherboard resources | |
| 0050 | 0053 | 4 | System timer | |
| 0054 | 005F | 12 | <not used=""></not> | |
| 0060 | 0060 | 1 | Keyboard controller | |
| 0061 | 0061 | 1 | Motherboard resources | |
| 0062 | 0062 | 1 | <not used=""></not> | |
| 0063 | 0063 | 1 | Motherboard resources | |
| 0064 | 0064 | 1 | Keyboard controller | |
| 0065 | 0065 | 1 | Motherboard resources | |
| 0066 | 0066 | 1 | <not used=""></not> | |
| 0067 | 0067 | 1 | Motherboard resources | |
| 0068 | 006F | 8 | <not used=""></not> | |
| 0070 | 0070 | 1 | Motherboard resources | Cascaded |
| 0070 | 0077 | 8 | System CMOS/real-time clock | |
| 0078 | 007F | 8 | <not used=""></not> | |
| 0080 | 0080 | 1 | Motherboard resources | |
| 0081 | 0091 | 17 | DMA controller | |
| 0092 | 0092 | 1 | Motherboard resources | |
| 0093 | 009F | 13 | DMA controller | |
| 00A0 | 00A1 | 2 | Programmable interrupt controller | |
| 00A2 | 00A3 | 2 | <not used=""></not> | |
| 00A4 | 00A5 | 2 | Programmable interrupt controller | |
| 00A6 | 00A7 | 2 | <not used=""></not> | |
| 00A8 | 00A9 | 2 | Programmable interrupt controller | |
| 00AA | 00AB | 2 | <not used=""></not> | |
| 00AC | 00AD | 2 | Programmable interrupt controller | |
| 00AE | 00AF | 2 | <not used=""></not> | |
| 00B0 | 00B1 | 2 | Programmable interrupt controller | |
| 00B2 | 00B3 | 2 | Motherboard resources | |
| 00B4 | 00B5 | 2 | Programmable interrupt controller | |
| 00B6 | 00B7 | 2 | <not used=""></not> | |
| 00B8 | 00B9 | 2 | Programmable interrupt controller | |

| | ddress ex) | Size [byte] | Description of the basic function | Alternative function |
|------|---------------|----------------|-----------------------------------|--|
| From | То | | | |
| 00BA | 00BB | 2 | <not used=""></not> | |
| 00BC | 00BD | 2 | Programmable interrupt controller | |
| 00BE | 00BF | 2 | <not used=""></not> | |
| 00C0 | 00DF | 32 | DMA controller | |
| 00E0 | 00EF | 16 | <not used=""></not> | |
| 00F0 | 00F0 | 1 | Numeric data processor | |
| 00F1 | 0277 | 391 | <not used=""></not> | |
| 0278 | 027F | 8 | <reserved></reserved> | Reserved for LPT1 |
| 0280 | 02E7 | 104 | <not used=""></not> | |
| 02E8 | 02EF | 8 | <reserved></reserved> | Reserved for COM1 or COM2 |
| 02F0 | 02F7 | 8 | <not used=""></not> | |
| 02F8 | 02FF | 8 | COM2 | Can be deactivated in setup, then free Reserved for COM1 or COM2 |
| 0300 | 0377 | 120 | <not used=""></not> | |
| 0378 | 037F | 8 | LPT1 | Can be deactivated in setup, then free Reserved for LPT1 |
| 0380 | 03AF | 48 | <not used=""></not> | |
| 03B0 | 03BB | 12 | Graphics | |
| 03BC | 03BF | 4 | <reserved></reserved> | |
| 03C0 | 03DF | 32 | Graphics | |
| 03E0 | 03E7 | 8 | <not used=""></not> | |
| 03E8 | 03EF | 8 | <reserved></reserved> | Reserved for COM1 or COM2 |
| 03F0 | 03F7 | 8 | <not used=""></not> | |
| 03F8 | 03FF | 8 | COM1 | Can be deactivated in setup, then free Reserved for COM1 or COM2 |

| | ddress iex) | Size [byte] | Description of the basic function | Alternative function |
|------|----------------|----------------|-----------------------------------|----------------------|
| From | То | | | |
| 0400 | 0453 | 84 | Motherboard resources | |
| 04D0 | 04D1 | 2 | Programmable interrupt controller | |
| 0680 | 069F | 32 | Motherboard resources | |
| 0800 | 087F | 128 | Motherboard resources | |
| 164E | 164F | 2 | Motherboard resources | |
| 1800 | 18FE | 255 | Motherboard resources | |
| 1854 | 1857 | 4 | Motherboard resources | Cascaded |
| 2004 | 2007 | 4 | Motherboard resources | |
| FFFF | FFFF | 1 | Motherboard resources | |

Dynamic range - resources are managed by means of Plug and Play functionality

Interrupt Assignments

The functions are assigned different interrupts, depending on the operating system. A distinction is made between the PIC and APIC modes.

| Interrupt assignment in F | PIC mode |
|---------------------------|----------|
|---------------------------|----------|

| | R | IRQ number | h | Der | | | | | | | | | | | | | | | | | | | | | Comment |
|-----------------------|---|------------|-----|-----|----------|---|---|---|-----------|----------|------|---|----|-----------|----|----------|-----------|----|----------|----|----|----|----|----|-------------------------|
| IRQ (ACPI mode) 0 | 0 | 1 2 | 5 | с | 4 | 5 | 9 | 7 | 8 | , 6 | 10 1 | 1 | 12 | 13 | 4 | 15 1 | 16 1 | 17 | 18 | 19 | 20 | 21 | 22 | 23 | |
| IRQ (PIC mode) 0 | 0 | | 1 2 | ю | 4 | 5 | 9 | 7 | 8 | , б | 10 1 | 1 | 12 | 13 | 14 | 15 | | | | | | | | | |
| Host PCI IRQ Line | | | | | | | | | | | | | | | | | A | | 0 | | ш | ш | U | -1 | 1 |
| Function | | | | | | | | | \vdash | \vdash | | | | | | | \vdash | | \vdash | | | | | | |
| Timer output 0 | × | | | | | | | | | | | | | \vdash | | | \vdash | | | | | | | | Fixed |
| Keyboard | | × | | | | | | | \vdash | Η | | | | Η | | \vdash | \vdash | | \vdash | | | | | | Fixed |
| Cascaded (IRQ9) | | | × | | | | | | | _ | | | _ | | | | | | _ | | _ | | | | Fixed |
| Serial interface 2 | | | | × | | | | | | | | | | - | | | | | | | | | | | Can be disabled |
| Serial interface 1 | | | | | \times | | | | | \vdash | | | | | | | | | | | | | | | Can be disabled |
| FD controller | | | | | | | × | | \square | | | | | | | | \square | | | | | | | | Can be disabled |
| Parallel interface 1 | _ | | | | | | | × | | | | | | | | | _ | | _ | | | | | | Can be disabled |
| Real-time clock (RTC) | | | | | | | | | × | | | | | | | | | | | | | | | | |
| PS/2 mouse | | | | | | | | | | | | | × | - | | | | | | | | | | | Fixed, can be disabled |
| Numeric processor | | | | | | | | | | | | | | × | | | | | | | | | | | Fixed |
| SATA | | | | | | | | | | | | Z | | | | | | | | | | | | × | Can be disabled |
| USB Port 0/1 | | | | | | | | | | | | Z | | | | | | | | | | | | ۲ | Cannot be disabled |
| USB Port 2/3 | | | | | | | | | | \vdash | | Z | | \square | | | \square | | | | | | | Υ | Cannot be disabled |
| USB Port 4/5 | | | | | | | | | | | Z | | | | | | | | | | | | Υ | | Cannot be disabled |
| USB 2.0 controller | | | | | | | | | | | Z | | | | | | | | | | | | Υ | | Can be disabled |
| Ethernet 1 | | | | | | | | | | - | Z | | | | | ~ | Y | | | | | | | | Can be disabled |
| Ethernet 2 | _ | | | | | | | | | | Z | | _ | | | | ~^ | ۲ | _ | _ | - | | | | Can be disabled |
| VGA | | | | | | | | | | | Z | | | | | 1 | 7 | | | | | | | | Can be disabled |
| Profibus or Profinet | | | | | | Z | | | | | | | | | | | - | - | | 7 | | | | | Option, can be disabled |
| | | | | | | | | | | | | | | | | | | | | | | | | | |

Y Interrupt in APIC mode

^z BIOS Default Interrupt in PIC mode, e.g., DOS

¹ Host PCI-IRQ A to H is assigned to IRQ 16 to 23 permanently in APIC mode. Host PCI-IRQ A to H will be automatically assigned IRQ 0 to 15 by BIOS in PIC mode. A specific assignment can not be enforced.

| | IRC | Q Nu | umb | er | | | | | | | | | | | | | | | | | | | | | Comments |
|---------------------|-----|------|-----|----|---|---|---|---------------|--------------|---|----|----|----|----------------|--------------------------|----|-----|-----|-----|-----|-----|-----------|-----|-----|----------|
| ACPI IRQ | 0 | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 | 13 | 14 | 15 | 16 | 17 | 18 | 19 | 20 | 21 | 22 | 23 | |
| IRQ | 0 | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 | 13 | 14 | 15 | • | | | | | \square | - | H | |
| Host PCI IRQ Line | | | | | | | | | | | | | | | | | A | В | С | D | E | F | G | н | 1 |
| Function | | | | | | | | | | | | | | | | | (1) | (2) | (3) | (4) | (5) | (6) | (7) | (8) | |
| Slot 1 (PCI) | | | | | | | | | | | | | | | | | | | | | | | | | |
| PCI INT Pin A | - | - | | Z | - | - | - | 35 | 171 | - | - | - | - | - | - | | | - | 37 | - | Y | - | - | - | |
| PCI INT Pin B | - | 9 | - | - | - | - | Z | | - | Э | - | - | - | - | | | ÷ | ÷ | - | - | - | Y | 2 | - | |
| PCI INT Pin C | - | - | - | - | | - | Z | - | - | | - | - | - | - | Э. | - | - | - | - | - | - | - | Y | - | |
| PCI INT Pin D | - | - | - | - | - | - | - | Z | - | - | - | - | - | - | - | × | - | - | - | - | - | - | - | Y | |
| Slot 2 (PCI) | | | | | | | | | | | | | | | | | | | | | | | | | |
| PCI INT Pin A | - | - | - | - | - | - | Z | - | 3 4 0 | - | - | - | - | - | 5 | ŝ. | - | - | - | - | - | Y | - | - | |
| PCI INT Pin B | - | - | - | - | - | - | Z | - | - | - | - | - | - | - | - | i. | - | - | - | - | - | | Y | - | |
| PCI INT Pin C | - | ×. | - | | - | - | - | Z | | | - | - | - | | ~ | - | - | - | - | - | - | - | - | Y | |
| PCI INT Pin D | Ξ | ωĒ | ÷ | Z | - | Ξ | - | ι÷. | ÷. | æ | Ξ. | Ξ | | æ | $\overline{\mathcal{A}}$ | - | ē. | Ξ | - | ÷ | Y | Ē | Ξ | ÷ | |
| Slot 2 (PCIexpress) | | | | | | | | | | | | | | | | | | | | | | | | | |
| PCI INT Pin A | - | - | - | Z | - | - | - | | - | | | - | - | 3 - 2 | - | - | Y | - | - | 121 | - | - | - | | |
| PCI INT Pin B | - | - | - | - | - | - | - | - | - | - | | - | - | - | - | - | - | Y | - | - | - | - | - | - | |
| PCI INT Pin C | - | - | - | | - | - | - | | • | - | - | Z | - | - | - | • | - | - | Y | - | - | | - | - | |
| PCI INT Pin D | - | - | | | | - | - | . | 1.74 | - | - | - | - | a . | - | - | æ., | - | - | Y | - | | - | - | |

Interrupt assignment of the slot connectors on the bus board

¹ Host PCI-IRQ A to H will be assigned IRQ 16 to 23 permanently in ACPI mode. Host PCI-IRQ A to H will be automatically assigned IRQ 0 to 15 in PIC mode. A specific assignment can not be enforced.

Y Interrupt in APIC mode

^z BIOS Default Interrupt in PIC mode (e.g. DOS)

Exclusive PCI hardware interrupt

Applications demanding a high-performance interrupt require a high-speed hardware interrupt reaction. The PCI hardware interrupt should be used only by one resource in order to ensure high-speed reaction of the hardware.

Exclusive interrupt in APIC mode

| | IRQ assignments for Windows systems, (APIC mode) |
|------------------|--|
| Ethernet 1 | 16 ^{1, 2} |
| Ethernet 2 | 17 ¹ |
| Profibus/MPI | 19 ¹ |
| PCI slot 1 | 20 ¹ |
| PCI slot 2 | 21 ¹ |
| PCI Express slot | 16 ^{1, 3} |

¹⁾ Requirement: The modules in the PCI slots each require only one interrupt

²⁾ Requirement: VGA and PCIexpress do not require an interrupt

³⁾ Requirement: VGA does not require an interrupt and Ethernet1 is disabled

Exclusive interrupt in PIC mode

The interrupts are automatically assigned to the slots at system startup due to the default settings in system BIOS.

Several slots may share the same interrupt, depending on the system configuration. This functionality is known as interrupt sharing. Exclusive interrupts are not available in PIC mode. Disable specific system resources in order to obtain exclusive interrupts. BIOS assigns the PIC interrupts at random during restart of the system.

Memory address assignments

PCI VGA modules can be operated with expansion ROM up to 48 K.

| Add | ress | Size | Description of the basic function | Alternative function |
|-----------|-----------|-------|---|---------------------------------|
| From | То | | | |
| 0000 0000 | 0007 FFFF | 512 K | Conventional system memory | |
| 0008 0000 | 0009 F7FF | 126 K | Conventional system memory extended | |
| 0009 F800 | 0009 FFFF | 2 K | XBDA, extended Bios Data Area | |
| 000A 0000 | 000A FFFF | 64 K | VGA graphics refresh memory | Shared SMM for power management |
| 000B 0000 | 000B 7FFF | 32 K | Software graphics / text refresh memory | Not used |
| 000B 8000 | 000B FFFF | 32 K | VGA graphics/text refresh memory | |
| 000C 0000 | 000C BFFF | 48 K | VGA BIOS expansion | |
| 000C 0000 | 000C FFFF | 64 K | VGA BIOS | Always allocated or reserved |

| Address | | Size | Description of the basic function | Alternative function |
|-----------|-----------|---------|---|--|
| From | То | | | |
| 000E 0000 | 000F FFFF | 2 × 64K | DMI data, System BIOS, Op- tions ROMs: PXE, RAID | |
| 0010 0000 | CFFF FFFF | 3.2 GB | System memory 4 GB memory configuration | Depends on memory configuration |
| EFFF F000 | EFFF FFFF | 4 K | Motherboard resources | |
| F000 0000 | F3FF FFFF | 64 M | Motherboard resources | |
| FED0 0000 | FED0 03FF | 1 K | High Precision Event Timer | |
| FED1 0000 | FED1 7FFF | 32 K | Motherboard resources | |
| FED1 8000 | FED1 8FFF | 4 K | Motherboard resources | |
| FED1 9000 | FED1 9FFF | 4 K | Motherboard resources | |
| FED1 C000 | FED1 FFFF | 16 K | Motherboard resources | |
| FED2 0000 | FED3 FFFF | 128 K | Motherboard resources | |
| FED4 0000 | FED4 4FFF | 20 K | Trusted Platform Module 1.2 | |
| FED9 0000 | FED9 3FFF | 16 K | Motherboard resources | |
| FEE0 0000 | FEEF FFFF | 1 M | Motherboard resources | |
| FF00 0000 | FFFF FFFF | 16 M | Motherboard resources | Intel [®] 82802 firmware hub |

8.5.5 Assignment of expansion interfaces to the software in the TIA Portal (CP assignment)

The table below shows the correlation between enclosure labeling of the IPC expansion slots and the labeling that is used during assignment of interfaces to the software in TIA Portal.

| Enclosure labeling IPC677D | TIA Portal | |
|----------------------------|------------|--|
| 1 | X100 | |
| 2 | X101 | |

8.5.6 CP 1616 onboard communications processor

8.5.6.1 Properties

CP 1616 on-board allows you to connect IPCs to Industrial Ethernet.

The basic characteristics of the PCS 1616 onboard are:

- Optimized for PROFINET IO
- Enhanced Real Time Ethernet Controller 400 = ERTEC 400
- The connectors are designed for 10BaseT and 100BaseTX.
- Data transfer rates of 10 and 100 Mbps in full/half duplex mode are supported.
- The handshake is performed automatically (auto negotiation).
- Autocrossing
- Automatic hardware detection
- Integrated 3-port real-time switch

3-port real-time switch

The switch function of the 3-port real-time switch is maintained in the following cases:

- Restart (Windows Restart)
- Reset (using the shortcut <Ctrl-Alt-Del)

The switch function can be activated permanently in the BIOS setup, "Power" menu with the "PROFINET always On" parameter. When switched off (Disabled), the switch function is interrupted in the following cases:

- Shutting down with Windows command
- Activating the on/off switch
- Shutting down with power switch (on/off switch).

Three RJ45 connectors

Terminal devices or other network components can be connected to the three RJ45 sockets that lead to the integrated real-time switch. The CP 1616 is connected to the LAN (Local Area Network) via one of the three RJ45 sockets of the device.

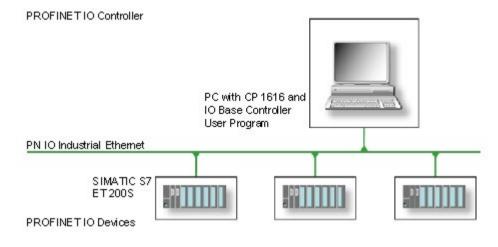
8.5.6.2 Typical Communication Partners

CP 1616 onboard as an IO controller

The following diagram shows a typical application: CP 1616 onboard as PROFINET IO controller on the IO controller layer.

The IO base controller user program runs on the PC. This program accesses the functions of the IO base user program interface.

Data traffic is routed via the communication processor to several SIMATIC S7 PROFINET IO devices, ET 200S over Industrial Ethernet.



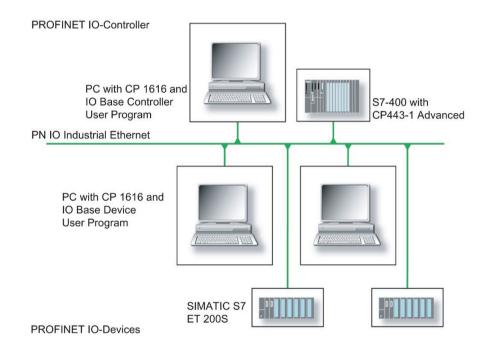
SIMATIC IPC677D Operating Instructions, 01/2020, A5E32995420-AE

CP 1616 onboard as IO device

The following diagram shows a typical application: Two PCs each with a CP as a PROFINET IO device on the IO device layer.

A PC with a CP as PROFINET IO controller, a SIMATIC S7-400 with a CP 443-1 as PROFINET IO controller and two SIMATIC S7 ET 200S PROFINET IO devices are also connected in the network.

The IO base device user program runs on the IO device PC. This program accesses the functions of the IO base user program interface. Data traffic is routed via the CP 1616 onboard communication processor to a PC as PROFINET IO controller, or to an S7-400 automation system with CP 443-1 over Industrial Ethernet.



8.5.6.3 Firmware Loader

Firmware loader

When to load firmware

The CP 1616 onboard is supplied with the latest version of the firmware. If new functions become available due to product development, you can make them available by performing a firmware download.

Description

This section will familiarize you with the application area and use of the firmware loader. You can find additional, detailed information about the individual loader variants in the integrated help of the program.

Firmware

This refers to the system program in the SIMATIC NET modules.

Application area for the firmware loader

The firmware loader enables you to reload new firmware releases to SIMATIC NET modules. It is used for:

- PROFIBUS modules
- Industrial Ethernet modules
- Modules for gateways, for example, IE/PB link

Installation

The firmware loader is available on your PG/PC under Windows following the installation of STEP 7/NCM PC.

Loader files

The firmware loader supports the following file types:

• <file>.FWL

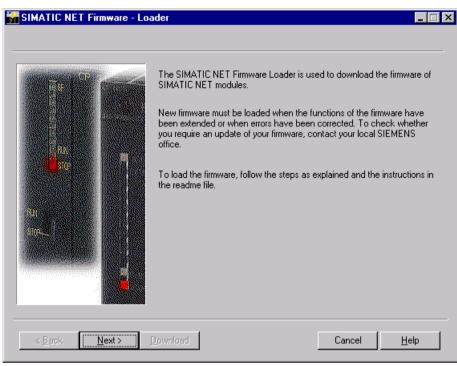
A file form that contains further information, which is displayed by the firmware loader. The firmware loader can use this information to check if the firmware is compatible to the device.

Read the information provided along with the loader file, for example, in the readme file. This information is also displayed in the firmware loader when the FWL file is loaded.

Loading firmware

Start downloading procedure

1. In the Windows Start menu, select the menu command SIMATIC > STEP 7 > NCM S7 > Firmware Loader.



2. Click "Next" and follow the instructions in the dialog fields that follow. A help function is integrated in the software as support.

Note

Ensure that the loader file you are using for the update is suitable for the version of firmware on your module. If you have any doubts, contact your local Siemens consultant.

Note

Be aware that aborting the loading process may result in an inconsistent state in your module.

You can find additional, detailed information about the individual loader variants in the integrated help.

Note

When loading the firmware or commissioning the module, be aware that the CP 1616 onboard takes five MAC addresses (always in direct sequence). The first two addresses are displayed in the BIOS, in the "Peripheral Configuration" submenu of the "Advanced" menu.

Example

The lower MAC address at "Profinet" is provided for Layer 2 communication, while the second one is used for Ethernet/PROFINET communication.

8.5.6.4 Further actions in STEP 7/NCM PC

Configuring

Your PC is now ready, although you still have to configure the SIMATIC NET communication software. The rest of the procedure is described in the "Commissioning PC Stations" manual (on the Windows PC that also contains STEP 7/NCM PC: Start > Simatic > Documentation > English > Commissioning PC Stations).

8.6.1 Overview

BIOS Setup program

The BIOS Setup program, or BIOS Setup for short, is located, together with the setup parameters, in a FLASH block on the motherboard.

You change the setup parameters of the device in the BIOS Setup. Examples: System time, hard disks or boot order.

Changing the device configuration

Your device configuration is preset for operating with the included software. You should only change the default setup parameters if you have made technical changes to your device, or if a fault occurs when the device is switched on.

NOTICE

Malfunctions can occur with running software CPU

If a BIOS update of the PC is performed while SIMATIC software controller, a SIMATIC WinAC for example, is running, the software CPU can malfunction, resulting in communication interruptions or failures, for example. Other actions that put a heavy load on the PC hardware, for example, running hardware tests such as benchmarks, can result in malfunctions of the software CPU.

Do not run a BIOS update or other actions that would put a heavy load on the hardware during operation of a software CPU.

Switch the software CPU to "STOP" before you run a BIOS update or perform other critical actions.

Note

Documentation

BIOS Setup is described for all devices and device configurations. Some BIOS submenus or Setup parameters may not be included, depending on your order. The interface of your BIOS Setup can deviate from the figures in this document.

You can find a detailed description of the BIOS on the Support website under Entry ID 92189185 (http://support.automation.siemens.com/WW/view/en/92189185).

8.6.2 Opening the BIOS selection menu

Procedure

1. Reset the device (warm or cold restart).

Depending on the device version, the default settings can differ from the figures shown. The following message appears briefly on the display at the end of the self-test: Press ESC for boot options

2. Press <ESC> to open the BIOS selection menu:



The following keys are available in the BIOS selection menu:

| Buttons | Function | |
|---------------------------------|--|--|
| Continue | Exit selection menu, continue start sequence | |
| Boot Manager | Specify the boot media from which to boot: | |
| | Hard disk drive | |
| | CD-ROM drive | |
| | USB drive | |
| Device Management | Start device manager for UEFI boot media | |
| Boot From File | Boot Maintenance Manager: | |
| | Boot Options: Set boot order | |
| | Driver Options: Configure drivers | |
| | Console Options: Configure connected input device | |
| | Boot from File: Start from an ".EFI" file | |
| | Reset System: Restore factory settings | |
| Secure Boot Option ¹ | Configuration settings to start the device in Secure Boot mode. The only software modules loaded are those that are known to be safe for the BIOS or the operating system. | |

| Buttons | Function |
|-------------|---|
| SCU | Start BIOS Setup via Setup Configuration Utility |
| BIOS Update | Update BIOS from USB memory stick |
| MEBx | Start Intel Management Engine BIOS Extension from Active Manage- ment Technology Support (AMT) |

¹ Available as of Windows 8 or later

8.6.3 Configuration

The individual setup parameters are distributed between different menus and submenus. The menus always have the same layout.

Menu layout

The following figure is an example for the main menu. Device-specific information is shown as blurred.

| 1 | Main Advanced Secur | ity Power Boot Exit | Rev. 5.0 |
|----------------|---|---|--|
| 0~ 3— 4— | Product Product BIOS Version BIOS Number Processor Type Cache RAM Total Memory CPU ID Hicrocode Revision Number Of Cores Number Of Threads Baseboard Revision MPI/DP Revision NVRAM Revision Intel ME Version / SKU Video Option ROM PXE Option ROM | ity Power Boot Exit 5.098/100 00002705 00002705 00002 6.108.00 000000 000000 000000 500.00 0000000 000000 000000 60000000 000000 000000 000000 60000000 000000 000000 000000 9000000 000000 000000 000000 90000000 000000 000000 000000 90000000 0000000 0000000 000000 900000000 0000000 0000000 0000000 900000000000 000000000 000000000000000000000000000000000000 | |
| 5— | System Time System Date El Help ESC Exit | 115:15:471 [10/31/2013] 14 Select Item ++ Select Henu F5/F6 Change Values ++ Select Henu Enter Select + Subflenu | F9 Setup Defaults F10 Save and Exit |
| | ① Header | ④ Help area | |

- (2) Menu bar(5) Key assignment
- ③ Settings, submenus and device-specific information

A menu is divided into four areas:

- In the menu bar 2 on top, you select from the different menus "Main", "Advanced", etc.
- The center left area ③ includes information on your device and you can edit settings that are partly available in submenus.
- The center right area ④ displays short help texts for the currently selected setup parameters.
- The key assignment (5) at the bottom shows the function keys and control keys available in BIOS Setup.

You can toggle between the menus with the " \leftarrow " left and " \rightarrow " right cursor keys.

The following table shows the standard menus. Not all menus are included in each supplied device configuration.

| Menu | Meaning |
|----------|---|
| Main | Display system information, for example, BIOS version, processor and memory |
| Advanced | Configure hardware using different submenus |
| Security | Security functions, e.g., setting a password |
| Power | Specify CPU settings and switch-on functions. |
| Boot | Determine boot options, e.g., boot order |
| Exit | Save and exit (see Exit menu) |

8.6.4 Exit menu

You always exit BIOS Setup in this menu.

| Main Advanced | Security Power | Boot Exit | InsydeH2O Setup Utility | | Rev. 5.0 |
|---|---|-----------|---|--|-----------|
| Hain Advanced Exit Saving Chan Save Change Uith Exit Discarding Load Qustom Defe Save Custom Defe Discard Changes | nges nout Exit Changes Faults nults | Boot jxit | | Exit system setup and save your | • changes |
| F1 Help Esc Exit | †∔ Select ↔ Select | | F5/F6 Change Values Enter Select ► SubMenu | F9 Setup Defaults F10 Save and Exit | |

| Exit Saving Changes | All changes are saved and the system is restarted with the new Setup parameters. |
|-----------------------------|--|
| Save Change Without Exit | All changes are saved |
| Exit Discarding Changes | All changes are discarded and the system is restarted with the old Setup parameters. |
| Load Optimal Defaults | All setup parameters are reset to the safe default values. |
| | Notice: The existing Setup parameters are overwritten by this. |
| Load Custom Defaults | The profile must be loaded with the custom Setup parameters. |
| | Requirement: The parameters are saved prior to this with "Save Custom Defaults". |
| Save Custom Defaults | The currently configured Setup parameters are saved as a custom profile (see also "Load Custom Defaults"). |
| Discard Changes | All changes are discarded. |

8.6.5 General BIOS Setup settings

If you have changed any default settings in Setup, you can enter them in the following table. You can then refer to these entries for any future hardware modifications.

Note

Print out the table below and keep the pages in a safe place once you made your entries.

The default setup settings vary depending on the ordered device configuration.

BIOS Setup settings

Main

| System parameters | Default settings | Local settings |
|-------------------|------------------|----------------|
| System Time | 00:00:00 | |
| System Date | MM/DD/YYYY | |

Advanced > Boot Configuration

| System parameters | Default settings | Local settings |
|-------------------|----------------------|----------------|
| Numlock | On | |
| POST errors | All without keyboard | |

Advanced > Peripheral Configuration

| System parameters | Default settings | Local settings |
|--------------------------------|-----------------------|----------------|
| Internal COM 1 ¹ | Auto | |
| Base I/O address ¹² | 3F8 | |
| Interrupt ¹² | IRQ4 | |
| Internal COM 2 ¹ | Auto | |
| Base I/O address ¹² | 2F8 | |
| Interrupt ¹² | IRQ3 | |
| Internal LPT ¹ | Auto | |
| Base I/O address ¹³ | 378 | |
| Interrupt ^{1 3} | IRQ7 | |
| Mode ¹³ | Bi-directional | |
| DMA Channel ¹³ | DMA 1 | |
| Onboard PROFINET 1 | Enabled | |
| PCI – MPI / DP 1 | Enabled | |
| Audio ⁴ | Auto | |

| System parameters | Default settings | Local settings |
|-----------------------------------|------------------|----------------|
| Onboard Ethernet 1 (LAN 1, X1 P1) | Enabled | |
| Onboard Ethernet 2 (LAN 2, X2 P1) | Enabled | |

¹ Visible depending on the ordered device configuration

- ² Only visible if the corresponding parameter "Internal COM #" is enabled.
- ³ Only visible if "Internal LPT" is enabled.
- ⁴ Only available if an Azalia HD audio controller is installed.

Advanced > SATA Configuration

| System parameters | Default settings | Local settings |
|-------------------|------------------|----------------|
| SATA Controller | Enabled | |
| HDC Configure As | AHCI | |

Advanced > Fan Control Configuration

| System parameters | Default settings | Local settings |
|-------------------|------------------|----------------|
| Fan Control Mode | Standard | |

Advanced > Video Configuration

| System parameters | Default settings | Local settings |
|---------------------|------------------|----------------|
| Primary Display | Auto | |
| IGD - Aperture Size | 128 MB | |
| IGD - DVMT Size | MAX | |
| IGD boot type | VBIOS default | |
| IGD boot type 2 | Disabled | |
| PEG0 - Gen X | Auto | |
| PEG1 - Gen X | Auto | |
| PEG2 - Gen X | Auto | |

Advanced > USB Configuration

| System parameters | Default settings | Local settings |
|---|----------------------------------|----------------|
| USB Precondition | Enabled | |
| XHCI | Auto | |
| Per-Port Control | Disabled | |
| The following parameters are only visible | e if "Per-Port Control" is enabl | ed (Enabled). |
| USB Port 0 (X61) | Enabled | |
| USB Port 1 (X60) | Enabled | |
| USB Port 2 (USB3 P2, internal) | Enabled | |
| USB Port 3 (USB3 P3, front) | Enabled | |
| USB Port 4 (X63) | Enabled | |
| USB Port 5 (X62) | Enabled | |

| System parameters | Default settings | Local settings |
|---|------------------|----------------|
| USB Port 6 (USB2 P6, front) ¹ | Enabled | |
| USB Port 6 (USB2 P6, touch) ² | Enabled | |
| USB Port 8 (USB2 P8, internal) | Enabled | |
| USB Port 9 (USB2 P9, internal) | Enabled | |
| USB Port 10 (USB2 P10, internal) ¹ | Enabled | |
| USB Port 11 (USB2 P11, internal) ¹ | Enabled | |

¹ Only with rack devices

² Only with box devices

Advanced > Chipset Configuration

| System parameters | Default settings | Local settings |
|------------------------------------|------------------|----------------|
| VT-d | Auto | |
| After G3 On | Last State | |
| DeepSx Power Policies ¹ | Disabled | |
| Max TOLUD | Dynamic | |
| HPET Support | Enabled | |

¹ Only with rack devices

Advanced > Active Management Technology Support

| System parameters | Default settings | Local settings |
|-----------------------------------|------------------|----------------|
| Intel AMT Support | Enabled | |
| Hide Un-Configure ME Confirmation | Disabled | |
| Un-Configure ME | Disabled | |
| Intel AMT Password Write | Enabled | |
| AMT CIRA Request Trig | Disabled | |
| USB Configure | Enabled | |
| AMT CIRA Timeout | 0 | |

Advanced > PCI Express Configuration

| System parameters | Default settings | Local settings |
|--------------------------------------|------------------|----------------|
| PCI Express Root Port 5 | Enabled | |
| PCIe Speed ² | Auto | |
| PCI Express Root Port 6 ¹ | Enabled | |
| PCIe Speed ¹² | Auto | |
| PCI Express Root Port 7 ¹ | Enabled | |
| PCIe Speed ¹² | Auto | |

| System parameters | Default settings | Local settings |
|--------------------------------------|------------------|----------------|
| PCI Express Root Port 8 ¹ | Enabled | |
| PCIe Speed ¹² | Auto | |

¹ Visible depending on the ordered device configuration

² Only visible if the associated parameter "PCI Express Root Port #" is enabled.

Security

| System parameters | Default settings | Local settings |
|------------------------------|---------------------------------|----------------|
| TPM Status ¹ | Depending on configura- tion | |
| TPM Operation ¹ | No Operation | |
| TPM Force Clear ¹ | Disabled | |
| Set Supervisor Password | | |
| Set User Password | | |
| Power-on Password | Disabled | |
| User Access Level | Full | |

¹ Visible depending on the ordered device configuration

Power

| System parameters | Default settings | Local settings |
|---|------------------|----------------|
| Wake on PME or LAN 2 (X2 P1) | Disabled | |
| Auto Wake on S5 | Disabled | |
| Wake on S5 Time ¹ | 00:00:00 | |
| Day of Month ¹ | 1 | |
| Wake on LAN 1 (X1 P1) | Enabled | |
| PROFINET always On ² | Disabled | |
| PROFINET Wake Capability ²³ | Disabled | |
| USB Ports 0/1 (X61/X60) powered | Enabled | |
| USB Ports 0/1 (X61/X60) Wake Capa- bility ⁴ | Disabled | |
| USB Ports 4/5 (X63/X62) powered | Enabled | |
| USB Ports 4/5 (X63/X62) Wake Capa- bility ⁴ | Disabled | |
| USB Ports 3/6/8/9 powered | Enabled | |
| USB Port 3/6/8/9 Wake Capability ⁴ | Disabled | |

¹ Only visible if the "Auto Wake on S5" is set accordingly.

² Visible depending on the ordered device configuration

³ Only visible if the parameter "PROFINET always On" is enabled.

⁴ Only visible if the associated parameter "USB Ports # powered" is enabled.

Power > Advanced CPU Control

| System parameters | Default settings | Local settings |
|---------------------------------------|------------------|----------------|
| P-States (ACTUAL) | Enabled | |
| Active Processor Cores | All Cores | |
| HT Support | Auto | |
| Execute Disable Bit | Enabled | |
| Intel (VMX) Virtualization Technology | Enabled | |
| C-States | Enabled | |
| Turbo Mode | Enabled | |

Boot

| System parameters | Default settings | Local settings |
|---------------------|------------------|----------------|
| Boot Type | Dual Boot Type | |
| Quick Boot | Enabled | |
| Quiet Boot | Enabled | |
| Network Stack | Disabled | |
| PXE Boot capability | Disabled | |
| Add Boot Options | Auto | |
| USB Boot | Enabled | |
| EFI Device First | Enabled | |
| Boot Delay Time | 3 | |

Boot > Legacy

| System parameters | Default settings | Local settings |
|-------------------|---|----------------|
| Normal Boot menu | Standard | |
| Boot Type Order | In the order of the following boot media: | |
| Floppy drive | Depending on configuration | |
| Hard Disk Drive | Depending on configuration | |
| CD/DVD ROM Drive | Depending on configuration | |
| USB | Depending on configuration | |
| Others | Depending on configuration | |

Exit

| System parameters | Default settings | Local settings |
|-------------------|------------------|----------------|
| Profile: | | |
| | | |
| | | |
| | | |
| | | |

8.6.6 BIOS update

Check regularly if updates are available for download to your device.

Additional information can be found on the Internet at the following address:After Sales Information system (http://www.siemens.com/asis).

Noting down and restoring BIOS Setup settings

NOTICE

Irretrievable loss of data

All BIOS Setup settings are deleted after the BIOS update. This can put the system in an undefined state. This may damage the device and the plant.

- 1. Print out the table in the next section "General BIOS Setup settings".
- 2. Enter your specific BIOS Setup setting in this table before you run a BIOS update.
- 3. Start BIOS Setup after the BIOS update.
- 4. Load the BIOS Setup default settings with <F9> "Setup Defaults". Or use the BIOS Setup command "Load Optimal Defaults" in the "Exit" menu.
- 5. Make your own Setup settings based on the table you have printed out.
- 6. Save the BIOS Setup settings with <F10> "Save and Exit".

Performing a BIOS update

NOTICE

Damage to the device

If you switch off the device during the update, the BIOS will be incomplete and corrupt. This may result in malfunctions.

Leave the device switched on during the update.

If you have purchased a new BIOS update for your device, follow these steps to install the update:

- 1. Copy the update to a USB memory stick.
- 2. Reset the device (warm or cold restart).

The following message appears briefly on the display at the end of the self-test:

Press ESC for boot options

- 3. Press <ESC> to open the BIOS selection menu.
- 4. Click the "BIOS Update" button.
- 5. Follow the instructions on the screen.

Reboots

There may be several reboots after a BIOS update. These reboots are initiated by the Management Engine (ME). The reboots are required by the ME to adapt itself to the changes of the BIOS update.

8.6.7 Alarm, error and system messages

During startup (the boot process), the BIOS first performs a **P**ower **O**n **S**elf **T**est (POST) and checks whether certain functional units of the PC are operating error-free. The boot sequence is immediately interrupted if critical errors occur.

BIOS initializes and tests further functional units if the POST does not return any errors. In this startup phase, the graphics controller is initialized and any error messages are output to the screen.

The error messages output by system BIOS are listed below. For information on error messages output by the operating system or application programs, refer to the corresponding manuals.

On-screen error messages

| On-screen error message | Meaning / tip | |
|--------------------------------|--|--|
| Operating system not found | Possible causes: | |
| | No operating system installed | |
| | Incorrect active boot partition | |
| | Wrong boot drive settings in SETUP | |
| Keyboard controller error | Controller error. Contact your technical support team. | |
| SMART failure detected on HDD | Hard disk reports pending failure through S.M.A.R.T. | |
| CMOS battery failed | CMOS battery is not connected. | |
| CMOS battery weak | CMOS battery is weak | |
| Real-time clock has lost power | The CMOS clock was operated without battery or with a battery that was too weak, during battery change, for example. Check the CMOS clock. | |
| Keyboard error | No keyboard inserted. | |
| PLD configuration failed | Programming of the PLC on the motherboard has failed. | |

8.7.1 Introduction

Intel® Active Management Technology (Intel® AMT) is an Intel technology for the remote maintenance of SIMATIC Industrial PCs (IPCs) with AMT technology using a management PC. It is not necessary to install an operating system on the SIMATIC IPC with Intel® AM. Intel® AMT provides numerous functions, e.g.:

• Keyboard Video Mouse (KVM) Redirection

KVM connections are always possible using the KVM server that is integrated in the firmware. KVM enables access to IPCs with a corrupted or no operating system as the KVM server is integrated in the AMT hardware. KVM enables you to reboot a remote computer and make changes to its BIOS settings.

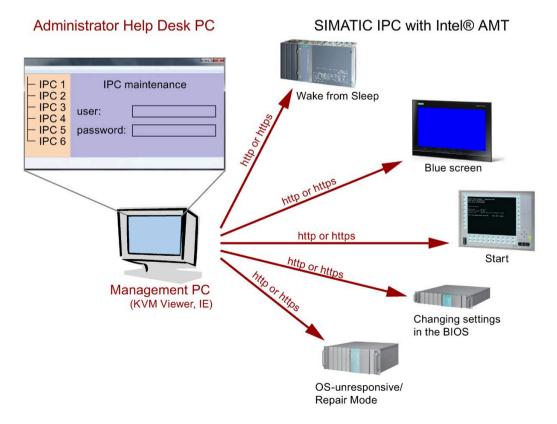
• Remote power management

SIMATIC IPC with Intel ® AMT can be switched on and off or restarted using another PC.

• IDE redirection

An image on the management PC can be integrated and used on the SIMATIC IPC with Intel® AMT both as a CD/DVD drive and as a floppy drive. If the image is bootable, you can also boot the SIMATIC IPC with Intel® AMT from it.

The following figure shows remote maintenance of SIMATIC IPCs with Intel® AMT, e.g. for troubleshooting a corrupt operating system or incorrect BIOS settings:



8.7.2 Overview of AMT

This section describes the required measures and settings on the local IPC so that the IPC can be controlled and maintained remotely from a management station known below as the help desk PC.

The local IPC is known below as the "AMT PC".

The sections contain the following information:

- AMT settings in the MEBx and in the BIOS setup
- Basic configuration of AMT
- Further useful notes

8.7.3 Enabling Intel® AMT / basic configuration

For security reasons, Intel® AMT is not enabled on new devices. The Management Engine (ME) is always active.

Procedure

For devices IPCxxxD, IPCxxxG, IPCxxxE, Field PG M4, Field PG M5, ITP:

- 1. If necessary, first reset Intel® AMT to the default status.
- 2. To open the BIOS selection menu, press the <ESC> key while the device is booting.
- 3. Open the BIOS Setup using the "Setup Configuration Utility (SCU)".
- 4. Select the "Active Management Technology Support" command in the Advanced menu. Only for the devices IPC547D, IPC547E and IPC547G: Select "AMT Configuration".
- 5. Activate the option "Intel AMT Support".
- Only for the devices IPC547D, IPC547E and IPC547G: Select the "Normal" setting for "MEBx Mode".
- 7. Exit the BIOS Setup with <F10> key (Save and Exit).

Only for the devices IPC547D, IPC547E and IPC547G: Exit the BIOS Setup with <F4> key.

Settings in the MEBx

- 1. To open the BIOS selection menu, press the <ESC> key while the device is booting.
- 2. Use the arrow keys to select "MEBx" and confirm with the <Enter> key.
- 3. Select "MEBx Login".
- 4. Enter the default password "admin".

Change the password. The new password must comprise:

- At least eight characters
- An upper case letter
- A lower case letter
- A number
- A special character (! @ # \$ % ^ & *)
- The underscore "_" and space characters are valid in the string but do not increase the complexity of the password.

Note

If the password is no longer available, you must reset the Intel® AMT to the default settings.

Backup the password to protect it against loss.

- 5. Switch to the "Intel (R) AMT Configuration" submenu and enable "Manageability Feature Selection".
- 6. Switch to the "Intel(R) ME General Settings" submenu and enable access via the network with "Activate Network Access".
- 7. Confirm the dialogs that appear with "Y".

Drivers are automatically installed once with the Windows system start in the subsequent restart.

See also

Resetting the Intel® AMT to the default settings and disabling AMT (Page 186)

8.7.4 Resetting the Intel® AMT to the default settings and disabling AMT

If Intel® AMT has already been configured, it is advisable to reset Intel® AMT to the default settings. One effect of resetting to the default settings is that Intel® AMT is disabled.

You can skip this point if you have a new IPC in the factory state.

Procedure

Proceed as follows to reset the Intel® AMT to the default values:

- 1. Press "F2" in the boot sequence to open the BIOS.
- 2. Select the "Active Management Technology Support" command in the Advanced menu; for an IPC547D/IPC547E/IPC547G select "AMT Configuration".
- 3. Set "Un-Configure ME" or "Un-Configure AMT/ME" to Enabled.
- 4. Exit the BIOS with "F10" (Save and Exit). You can exit the IPC547D/547E/IPC547G with "F4".

The following prompt will appear after an automatic restart:

Found unconfigure of Intel(R) ME Continue with unconfiguration (Y/N)

- 5. Confirm this prompt with "Y" to discard all settings in the Management Engine (ME).
- 6. For IPC427E/IPC477E/Field PG M4/Field PG M5, you now need to set the "Un-Configure ME" menu command in the BIOS back to Disabled.

8.7.5 Determining the network address

To connect the AMT PC with the AMT server, the network address that uniquely localizes the AMT server on the AMT PC must be entered.

If DHCP is set for the automatic assignment of the network address in "Network Setup" in the MEBx of the AMT PC, the network address is not fixed.

Procedure

If the AMT server uses the same network address as the operating system of the AMT PC (most common situation):

1. You can obtain the address of the AMT server in the command line in Windows using "ipconfig" and in UNIX using "ifconfig".

If the AMT server and operating system do not use the same network address, ask your network administrator for the address you have been assigned.

8.7.6 Forcing user consent

When a connection to the AMT PC is established, the KVM viewer may prompt the user to enter a six-figure code. This code is displayed on the screen of the AMT PC. The user of the AMT PC must inform the user of the KVM viewer of this code.

This code query needs to be set up on the KVM viewer.

Procedure

- 1. Select "Intel(R) AMT Configuration > User Consent" in the MEBx.
- 2. Select the value "KVM" for "User Consent".
- To allow a user with administrator privileges to avoid this code query, follow these steps:
- 1. Select "Intel(R) AMT Configuration > User Consent" in the MEBx.
- 2. Select "Opt-in Configurable from Remote IT".

8.8 Functional scope in Windows

8.8 Functional scope in Windows

8.8.1 Windows Embedded Standard 7 Professional

The overview shows the most important device functions under Windows Embedded Standard 7:

| Function | Availability |
|--|----------------------|
| .Net Framework | Available, V3.5 |
| Accessories | Available |
| Aero background | Available |
| Backup and Restore | Available |
| Bluetooth | Available |
| Dialog box filter | Available |
| DirectX and Windows Device Experience | Available, V11 |
| Domain services | Available |
| Driver database | Not available |
| Driver frameworks | Available |
| Encrypted File System (EFS) | Available |
| Enhanced Write Filter | Available |
| Fax and Scan | Available |
| File Based Write Filter (FBWF) | Available |
| Fonts | 48 |
| Help and Support Engine | Available |
| Hibernate Once Resume Many (HORM-EEF) | Available |
| Image Mastering API V2 | Available |
| IME Base Components | Available |
| Internet Explorer | Available, IE 8 |
| Internet Information Server (IIS) | Available, V7.0 |
| Language (Standard) | English ¹ |
| Mobility Center | Available |
| Network and Sharing Center | Available |
| Network Diagnostics | Available |
| Pagefile | Available |
| Printing Utilities and Management | Available |
| Registry Filter | Available |
| Remote Assistance | Available |
| Remote Client | Available |
| Remote Desktop | Available |
| SIMATIC IPC DiagBase | Available, V1.4 |
| Speech | Not available |
| System Management Administrative Tools | Available |

8.8 Functional scope in Windows

| Function | Availability |
|---------------------------------------|----------------|
| Telnet Server | Available |
| User Account Control | Available |
| Windows Explorer Shell | Available |
| Windows Firewall | Available |
| Windows Installer | Available |
| Windows Media Player | Available, V12 |
| Windows PowerShell 2.0 | Available |
| Windows Search and Natural Language 6 | Available |
| Windows Security Center | Available |
| Windows Update | Available |
| Wireless Networking | Available |

¹ Note the licensing agreements for Windows Embedded Standard 7 Professional.

Additional information on language selection is available in section "Setting up the language selection by means of the Multilanguage User Interface (MUI)".

Technical support

A.1 Service and support

You can find additional information and support for the products described on the Internet at the following addresses:

- Technical support (https://support.industry.siemens.com/cs/ww/en/)
- Support request form (<u>http://www.siemens.com/automation/support-request</u>)
- After-sales information system for SIMATIC PC / PG (<u>http://www.siemens.com/asis</u>)
- SIMATIC Documentation Collection (http://www.siemens.com/simatic-tech-doku-portal)
- Your local representative (<u>http://www.automation.siemens.com/mcms/aspadb/en/Pages/default.aspx</u>)
- Training center (http://sitrain.automation.siemens.com/sitrainworld/?AppLang=en)
- Industry Mall (<u>https://mall.industry.siemens.com</u>)

When contacting your local representative or Technical Support, please have the following information at hand:

- Order number of the device (MLFB)
- BIOS version (industry PC) or image version (HMI device)
- Installed additional hardware
- Installed additional software

Tools & downloads

Please check regularly if updates and hotfixes are available for download to your device. The downloads are available on the Internet under "After Sales Information System SIMATIC PC/PG" (see above).

A.2 Troubleshooting

This chapter provides you with tips on how to localize and troubleshoot frequently occurring problems.

| Problem | Possible cause | Remedy |
|-------------------------------|--|--|
| The device is not operational | There is no power supply to the device. | Check the power supply, the network cable and the power plug. Check if the On/Off switch is in the correct position. |
| | Device is being operated outside the specified ambient. conditions | Check the ambient conditions. After transport in cold weather, wait approximately 12 hours before switching on the device. |
| The PC crashes during startup | I/O addresses are assigned twice. Hardware interrupts and/or DMA channels are assigned twice Signal frequencies or signal levels are not adhered to Different connector pin assignments | Check your computer configuration: If the computer configuration corresponds with the factory state, please contact your technical support team. If the computer configuration has been changed, restore the original factory settings. Remove all third-party expansion cards, then restart the PC. If the error no longer occurs, the third-party expansion card was the cause of the fault. Replace this expansion card with a Siemens card or contact the card supplier. |
| | | If the PC still crashes, contact your technical support team. |
| Windows no longer boots | Settings in the BIOS Setup are incorrect | Check the settings in the BIOS Setup "SATA Configuration" submenuCheck the setting in the BIOS Setup Boot menu. |
| The external monitor remains | The monitor is switched off. | Switch on the monitor. |
| dark. | The monitor is in "power save" mode. | Press any key on the keyboard. |
| | The brightness button has been set to dark. | Increase the screen brightness. For detailed infor- mation, refer to the monitor operating instructions. |
| | The power cord or the monitor cable is not connected. | Check whether the power cord has been properly connected to the monitor and to the system unit or to the grounded shockproof outlet. |
| | | Check whether the monitor cable has been properly connected to the system unit and to the monitor. |
| | | If the monitor screen still remains dark after you have performed these checks, please contact your technical support team. |
| The mouse pointer does not | The mouse driver is not loaded. | Check if the mouse driver is correctly installed. |

A.2 Troubleshooting

| Problem | Possible cause | Remedy |
|---|--|--|
| appear on the screen. | The mouse is not connected. | Check whether the mouse lead is connected to the system unit. If you are using an adapter or extension for the mouse lead, check the connectors. Should the mouse cursor still not be visible on- screen after completing these checks and measures, contact technical support. |
| Wrong time and/or date on the PC. | | Open the BIOS selection menu (see Technical specifications, section "BIOS description"). Select BIOS setup, "Main" menu. Set the time and date. |
| Although the BIOS setting is OK, the time and data are still wrong. | The backup battery is dead. | Replace the backup battery. |
| USB device not responding. | The USB ports are disabled in your BIOS. | Use a different USB port or enable the port. |
| | Operating system does not support the USB port. | Enable USB Legacy Support for the mouse and keyboard. For other devices you need the USB drivers for the respective operating system. |
| DVD: The front loader does not open. | The device is switched off or the open/close button is disabled by a software application. | Emergency removal of the data medium: Switch off the device Insert a pointed object, a pin for example, or an opened paper clip into the emergency extraction opening of the drive. Apply slight pressure to the contact until the front loader opens. Pull the loader further out. |
| The RAID software reports the following errors: | RAID is not activated | In this case, the messages have no negative influ- ence on the device function and can be ignored. |
| • The RAID plug-in failed to load, because the drive is not installed. | RAID is activated | Acknowledge the messages. Re-install the software from the supplied Documen- tation and Drivers DVD. |
| The Serial ATA plug-in failed to load, because the driver is not installed cor- rectly. | | |
| The Intel® Matrix Storage Console was unable to load a page for the follow- ing reason: | | |
| A plug-in did not pro- vide a page for the se- lected device | | |
| A plug-in failed to load | | |
| After changing the hard disk, the system does not boot from the RAID array | RAID array does not have highest boot priority | Set the RAID array to be first in the boot order |

A.2 Troubleshooting

| Problem | Possible cause | Remedy |
|--|--|---|
| After changing the hard disk, "unused" is indicated for the relevant SATA port | The system was booted without a functioning hard disk (the removable cartridge was possibly not turned on) | Reboot the system with a functioning hard disk |
| Computer does not boot or "Boot device not found" is displayed | The boot device is not first in the boot priority in the BIOS setup or is excluded as a boot device | Change the boot priority of the boot device in the Boot menu of the BIOS setup or permit boot device in the boot priority |

Meaning of the symbols on your device

B.1 Meaning of the symbols on your device

The following tables show all the symbols which may be found on your SIMATIC industrial PC, SIMATIC industrial monitor or SIMATIC Field PG in addition to the symbols which are explained in the operating instructions.

The symbols on your device may vary in some details from the symbols shown in the following tables.

B.2 Safety

| Symbol | Meaning | Symbol | Meaning |
|-------------|---|--------|-----------------------------|
| \triangle | Warning, observe the supplied docu- mentation. | Ŧ | Lock is closed |
| (!) | Attention, radio equipment | Î | Lock is open |
| | Disconnect the power plug before opening | ß | Opening for Kensington lock |
| | Attention ESD (Electrostatic sensitive device) | | Warning of hot surface |

B.3 Operator controls

| Symbol | Meaning | Symbol | Meaning |
|--------|--|--------|--------------|
| | On/off switch, without electrical isola- tion | | Eject CD/DVD |
| Φ | On/off switch, without electrical isola- tion | | |

B.4 Certificates, approvals and markings

The following table shows symbols relating to certificates, approvals and markings which may be on the device. You can find more information in the operating instructions for your device:

| Symbol | Meaning | Symbol | Meaning |
|--------|---|--------|---|
| | Approved for Australia and New Zea- land | EAC | Marking for the Eurasian Customs Union |
| | Approved for China | FM | ► Test mark of Factory Mutual Re- search |
| CE | CE markings for European countries | F© | Marking of Federal Communications Commission for the USA |
| | EFUP (Environment Friendly Use Period) marking for China | | Approved for Korea |
| cULus | Test mark of the Underwriters La- boratories | X | Disposal information, observe the local regulations. |

B.5 Interfaces

B.5 Interfaces

| Symbol | | Meaning | | Symbol | Meaning |
|----------------|---------------|--|---|----------------|-------------------------|
| | | Connection to the power supply | | Ą | PS/2 mouse interface |
| (] | | Protective conductor terminal | | :: | PS/2 keyboard-interface |
| <i>.</i> ,, | Ψ | Connection for functional earthing (equipotential bonding line) | | | Multimedia Card Reader |
| DPF |) | DisplayPort interface | | | Smart Card Reader |
| ٢. | | DVI-D interface | | ((*)) | Line In |
| LAN | | LAN interface, not approved for con- necting WAN or telephone | | ((-))→ | Line Out |
| (1010) |) | Serial interface | | D | Microphone input |
| •~ | → | USB port | - | 0 | Universal Audio Jack |
| •~ | + ■ | USB 2.0 HiSpeed interface | | | Headphone output |
| SS- | | USB 3.0 super-speed port | | | |
| SS-∕ | | USB 3.1 SuperSpeedPlus interface | | | |

B.6 Directives and declarations

Supplement to the chapter of the operating instructions.

Electromagnetic compatibility

This product meets the requirements of EU Directive 2014/30/EU "Electromagnetic Compatibility".

Low-voltage directive

The device with AC power supply complies with the requirements of the EU Directive 2014/35/EU "Low Voltage Directive".

Compliance with this standard has been verified according to EN 60950-1:2006 + A11:2009 + A1:2010 + A12:2011 + AC:2011 + A2:2013.

List of abbreviations

| Abbreviation | Term | Meaning |
|--------------|--|---|
| AC | Alternating current | Alternating current |
| ACPI | Advanced Configuration and Power Interface | |
| PLC | Programmable controller | |
| AGP | Accelerated Graphics Port | High speed bus system |
| AHCI | Advanced Host Controller Interface | Standardized controller interface for SATA devic- es. This is supported in Microsoft Windows XP as of SP1 and IAA driver. |
| APIC | Advanced Programmable Interrupt Controller | Extended programmable interrupt controller |
| APM | Advanced Power Management | Tool for monitoring and reducing power con- sumption of the PC |
| AS | Automation system | |
| ASIS | After Sales Information System | |
| AT | Advanced Technology | |
| ATA | Advanced Technology Attachment | |
| ATX | AT-Bus-Extended | |
| AWG | American Wire Gauge | US standard for the cable diameter |
| BIOS | Basic Input Output System | Basic Input Output System |
| CAN | Controller Area Network | |
| CD-ROM | Compact Disc – Read Only Memory | Removable storage medium for large data vol- umes |
| CD-RW | Compact Disc – Rewritable | Rewritable CD |
| CE | Communauté Européenne (CE symbol) | The product is in conformance with all applicable EC directives |
| CFast | CF + AST | The acronym CFast is the combination of CF (CompactFlash) and AST (ATA Serial Transport). |
| CGA | Color Graphics Adapter | Standard monitor interface |
| CLK | Clock pulse | Clock signal for controllers |
| CMOS | Complementary Metal Oxide Semiconductors | Complementary metal oxide semiconductors |
| COA | Certificate of authentication | Microsoft Windows Product Key |
| CoL | Certificate of License | License authorization |
| СОМ | Communications Port | Term for the serial interface |
| СР | Communication Processor | Communication computer |
| CPU | Central Processing Unit | CPU |
| CRT | Cathode Ray Tube | |

| Abbreviation | Term | Meaning |
|----------------|---|---|
| CSA | Canadian Standards Association | Canadian organization for tests and certifications according to own or binational standards (with UL / USA) standards |
| CTS | Clear To Send | Clear to send |
| DRAM | Dynamic Random Access Memory | |
| DC | Direct Current | DC current |
| DCD | Data Carrier Detect | Data carrier signal detection |
| DMA | Direct Memory Access | Direct memory access |
| DOS | Disk Operating System | Operating system without GUI |
| DPP | DisplayPort | New powerful digital monitor port |
| DQS | Deutsche Gesellschaft zur Zertifizierung von Qualitätsmanagement mBH | |
| DDRAM | Double Data Random Access Memory | Memory chip with high-speed interface |
| DSR | Data Set Ready | Ready for operation |
| DTR | Data Terminal Ready | Data terminal is ready |
| DVD | Digital Versatile Disk | Digital versatile disk |
| DVI | Digital Visual Interface | Digital display interface |
| DVI-I | Digital Visual Interface | Digital display interface with digital and VGA signals |
| ECC | Error checking and correction | Error correction code |
| ECP | Extended capability port | Extended parallel port |
| EFI | Extensible Firmware Interface | |
| EGA | Enhanced Graphics Adapter | PC to monitor interface |
| ESD | Electrostatic-sensitive components | |
| DM | Electronic Manual | |
| EIDE | Enhanced Integrated Drive Electronics | An enhancement of the IDE standard |
| EISA | Extended Industry Standard Architecture | Extended ISA standard |
| EMM | Expanded Memory Manager | Manages memory expansions |
| EM64T | Extended Memory 64 technology | |
| EN | European standard | |
| EPROM / EEPROM | Erasable Programmable Read-Only Memory / Electrically Erasable Programmable Read- Only Memory | Plug-in submodules with EPROM/EEPROM chips |
| EPP | Enhanced Parallel Port | Bi-directional Centronics interface |
| ESC | Escape character | Control character |
| EWF | Enhanced Write Filter | |
| FAQ | Frequently Asked Questions | FAQs |
| FAT 32 | File Allocation Table 32-bit | 32-bit file allocation table |
| FBWF | File Based Write Filter | |
| FD | Floppy disk | Disk drive, 3.5" |
| FSB | Front Side Bus | |
| GND | Ground | Chassis ground |
| HD | Hard disk | Hard disk |

| Abbreviation | Term | Meaning |
|--------------|--|---|
| HDA | High Definition Audio | |
| HDD | Hard Disk Drive | Hard disk drive |
| HU | Height unit | |
| HMI | Human Machine Interface | User interface |
| HORM | Hibernate Once - Resume Many | |
| HT | Hyper-Threading | |
| HTML | Hyper Text Markup Language | Script language for creating Internet pages. |
| HTTP | Hypertext Transfer Protocol | Protocol for data transfer on the Internet |
| Hardware | Hardware | |
| IAMT | Intel Active Management Technology | Technology that permits the diagnostics, man- agement and remote control of PCs |
| I/O | Input/Output | Data input/output on computers |
| IAA | Intel Application Accelerator | |
| IDE | Integrated Device Electronics | |
| IEC | International Electronical Commission | |
| IGD | Integrated Graphics Device | |
| IP | Ingress Protection | Degree of protection |
| IR | Infrared | Infrared |
| IRDA | Infrared Data Association | Standard for data transfer via IR module |
| IRQ | Interrupt Request | Interrupt request |
| ISA | Industry Standard Architecture | Bus for expansion modules |
| ITE | Information Technology Equipment | |
| L2C | Level 2 cache | |
| LAN | Local Area Network | Computer network that is limited to a local area. |
| LCD | Liquid Crystal Display | Liquid crystal display |
| LED | Light Emitting Diode | Light emitting diode |
| LPT | Line Printer | Printer port |
| LVDS | Low Voltage Differential Signaling | |
| LW | Drive | |
| MAC | Media access control | Media access control |
| MC | Memory Card | Memory card in credit card format |
| MLFB | Machine-readable product designation | |
| MMC | Micro Memory Card | Memory card of the format 32 mm x 24.5 mm |
| MPI | Multipoint-capable interface for programming devices | |
| MRAM | Magnetoresistive Random Access Memory | Non-volatile data memory. Data memory is re- tained without external power supply. |
| MS-DOS | Microsoft Disc Operating System | |
| MTBF | Mean Time Between Failures | |
| MUI | Multilanguage User Interface | Multilanguage operating system with Windows with language toggling; 5 languages: German, English, French, Spanish and Italian |
| NA | Not Applicable | |

| Abbreviation | Term | Meaning |
|--------------|---|---|
| NAMUR | Normenarbeitsgemeinschaft for Mess- und Regelungstechnik in der chemischen Industrie (standardization body for instrumentation and control technology in the chemicals industry) | |
| NC | Not Connected | Not connected |
| NCQ | Native Command Queuing | Automatic re-sorting of the file and disk access, for increased performance |
| NEMA | National Electrical Manufacturers Association | Syndicate of manufacturers of electrical components in the USA |
| NMI | Non Maskable Interrupt | Interrupt the processor can not reject |
| NTFS | New Techniques File System | Secure file system for Windows versions (2000, XP, 7) |
| ODD | Optical Disk Drive | |
| OPC | OLE for Process Control | Standardized interface for industrial processes |
| OSK | On Screen Keyboard | Screen keyboard emulated by operating system |
| PATA | Parallel ATA | |
| PC | Personal computer | |
| PCI | Peripheral Component Interconnect | High-speed expansion bus |
| PCle | Peripheral Component Interconnect express | High-speed serial, differential full-duplex PtP interface with high data rate. |
| PCMCIA | Personal Computer Memory Card Interna- tional Association | |
| PI | Protective Earth | Protective conductor |
| PEG | PCI Express Graphics | |
| PG | Programming device | |
| PIC | Programmable Interrupt Controller | Programmable interrupt controller |
| PIC-E | Peripheral Component Interconnect Express | |
| POST | Power On Self Test | |
| PXE | Preboot Execution Environment | Software for running new PCs without hard disk data via the network |
| RAID | Redundant Array of Independent Disks | Redundant hard disk array |
| RAL | Restricted Access Location | Installation of device in operating facilities with restricted access - for example, a locked switch- gear cabinet |
| RAM | Random Access Memory | |
| RI | Ring Input | Incoming call |
| ROM | Read-Only Memory | |
| RS 485 | Reconciliation Sublayer 485 | Bi-directional bus system designed for up to 32 nodes |
| RTC | Real Time Clock | Real-time clock |
| RTS | Reliable Transfer Service | Request to send |
| RxD | Receive Data | Data transfer signal |
| SATA | Serial Advanced Technology Attachment | |
| SCSI | Small Computer System Interface | |
| SDRAM | Synchronous DRAM | |

| Abbreviation | Term | Meaning |
|--------------|--|--|
| SELV | Safety Extra Low Voltage | Safety extra low voltage |
| SLC | Second Level Cache | |
| SMART | Self Monitoring Analysis and Reporting Tech- nology | Hard disk error diagnostics program |
| SMS | Short Message Service | Short message via telecommunication network |
| SNMP | Simple Network Management Protocol | Network protocol |
| SO-DIMM | Small Outline Dual Inline Memory Module | |
| SOM | SafeCard on Motherboard (SOM) | |
| SPP | Standard Parallel Port | Synonym for parallel port |
| SRAM | Static Random Access Memory | Static RAM |
| SSD | Solid State Drive | |
| SVGA | Super Video Graphics Array | Enhanced VGA standard with at least 256 colors |
| SVP | Serial number of the device | |
| SW | Software | |
| ТСО | Total Cost of Ownership | |
| TFT | Thin-Film-Transistor | Type of LCD flat-screen |
| TPM | Trusted Platform Module | Chip with security functions |
| TTY | Tele Туре | Asynchronous data transfer |
| TxD | Transmit Data | Data transfer signal |
| ТХТ | Trusted Execution Technology | Hardware implementation |
| TWD | Watchdog Time | Watchdog monitoring time |
| UEFI | Unified Extensible Firmware Interface | |
| UL | Underwriters Laboratories Inc. | US organization for tests and certifications ac- cording to own or binational standards (with CSA / Canada) standards. |
| UMA | Unified Memory Architecture | Video memory |
| URL | Uniform Resource Locator | Designation of the full address of an Internet page |
| USB | Universal Serial Bus | |
| UXGA | Ultra Extended Graphics Array | Graphic standard, maximum resolution 1.600 x 1.200 pixels. |
| V.24 | | ITU-T standardized recommendation for data transfer via serial ports |
| VCC | | Positive supply voltage of integrated circuits |
| VDE | Verein deutscher Elektrotechniker (Union of German Electrical Engineers) | |
| VGA | Video Graphics Array | Video adapter which meets industrial standard |
| VRM | Voltage Regulator Module | |
| VT | Virtualization Technology | Intel technology with which a virtually closed environment can be made available. |
| VT-D | Virtualization Technology for Directed I/O | Enables the direct assignment of a device (e.g. network adapter) to a virtual device. |
| W2k | Windows 2000 | |
| WAN | Wide Area Network | |

| Abbreviation | Term | Meaning |
|--------------|----------------------------|--|
| WAV | Wave Length Encoding | Loss-free file format for audio data |
| WD | Watchdog | Program monitoring with error detection and alarming. |
| WLAN | Wireless LAN | LWireless local area network |
| WoL | Wake on Local Area Network | |
| WWW | World Wide Web | |
| XD | Execute Disable Capability | Hardware implementation |
| XGA | Extended Graphics Array | Graphic standard, maximum resolution 1.024 x 768 pixels. |

Glossary

AHCI mode

| | AHCI is a standardized method to address the SATA controller. AHCI describes a structure in the RAM, which contains a general area for control and status, as well as a command list. |
|-----------------|--|
| APIC mode | Advanced peripheral interrupt controller. 24 interrupt lines are available. |
| Automation syst | em |
| | A programmable controller (PLC) of the SIMATIC S7 system consist of a central controller, one or several CPUs, and various I/O modules. |
| Backup | |
| | Duplicate of a program, data medium or database, used either for archiving purposes or for the protection of vital and non-replaceable data against loss when the working copy is corrupted. Certain applications automatically generate backup copies of data files, and manage both the current and the previous versions on the hard disk. |
| Baud | |
| | Physical unit for the step speed in signal transmission. Defines the number of transferred signal states per second. With only two states, one baud is equivalent to a transmission rate of 1 bps. |
| Boot disk | |
| | A boot disk is a disk with a "Boot" sector. This can be used to load the operating system from the disk. |
| Cache | |
| | High-speed access buffer for interim storage (buffering) of requested data. |
| CE marking | |
| | C ommunauté E uropéene The CE mark confirms compliance of the product with corresponding EC Directives, for example, with the EMC Directive. |

Chipset

Located on the motherboard, connects the processor with the PCI or PCIe bus and the external interfaces.

Cold restart

A start sequence, starting when the computer is switched on. The system usually performs some basic hardware checks within the cold start sequence, and then loads the operating system from the hard disk to work memory -> boot

COM interface

The COM interface is a serial V.24 interface. The interface is suitable for asynchronous data transfer.

CompactFlash card

CompactFlash is a digital storage medium in card format and without moving parts. The CF card contains the non-volatile memory and the controller. The interface of the CF card corresponds with the IDE interface. CF cards can be operated without additional electronics on PCMCIA or IDE hard disk controllers using a plug and socket adapter. There are two design forms: CF-I ($42.6 \times 36.4 \times 3.3 \text{ mm}$) and CF-II ($42.8 \times 36.4 \times 5 \text{ mm}$).

Configuration files

These are files containing data which define the configuration after restart. Examples of such files are CONFIG.SYS, AUTOEXEC.BAT and the registry files .

Configuration software

The configuration software updates the device configuration when new modules are installed . This is done either by copying the configuration files supplied with the module or by manual configuration using the configuration utility.

Controller

Integrated hardware and software controllers that control the functions of certain internal or peripheral devices (for example, the keyboard controller).

Device configuration

The configuration of a PC or programming device contains information on hardware and device options, such as memory configuration, drive types, monitor, network address, etc. The data are stored in a configuration file and enable the operating system to load the correct device drivers and configure the correct device parameters. If changes are made to the hardware configuration, the user can change entries in the configuration file using the SETUP program.

Drivers

Program parts of the operating system. They adapt user program data to the specific formats required by I/O devices such as hard disk, printers, and monitors.

EMC directive

Directive concerning Electromagnetic Compatibility. Compliance is confirmed by the CE symbol and the EC certificate of conformity.

Energy management

The energy management functions of a modern PC allow individual control over the current consumption of vital computer components (e.g. of the monitor, hard disk and CPU), by restricting their activity based on the current system or component load. Energy management is of particular importance for mobile PCs.

Energy options

The energy options can be used to reduce energy consumption of the computer, while keeping it ready for immediate use. This can be configured in Windows by selecting Settings > Control Panel > Energy options.

Enhanced Write Filter

Configurable write filter that allows you to, for example, boot Windows Embedded Standard from write-protected media (e.g., CD-ROM), set write protection for individual partitions, and adapt the file system performance to user requirements (when using memory cards, for example).

ESD Guideline

Guideline for using electrostatic sensitive components.

Ethernet

Local network (bus structure) for text and data communication with a transfer rate of 10/100/1000 Mbps.

Execute Disable Capability

Hardware implementation that prevents mutual memory accesses by programs and applications. It is only effective when all relevant system components, such as processors, operating systems and applications are supported.

Refers to the central interface between the firmware, the individual components of a computer and the operating system. EFI is located logically beneath the operating system and represents the successor to PC BIOS, focusing on 64-bit systems. File Based Write Filter Configurable write filter to protect individual files from write access. Formatting Basic partitioning of memory space on a magnetic data medium into tracks and segments. Formatting deletes all data on a data medium. All data media must be formatted prior to their first use. HORM Hibernate once, resume many is a method for fast booting from a single Hibernate file that only needs to be created once. HORM ensures restoration of a uniform, saved system state when booting. This minimizes write access, for example to a CompactFlash medium, when you start up and shut down Windows Embedded Standard 7. Hub A term in network technology. In a network, a device joining communication lines at a central location, providing a common connection to all devices on the network. Hyper Threading HT technology (multi-threading) enables the parallel computing of processes. HT is only effective when all relevant system components, such as processors, operating systems and applications are supported. IGD Integrated Graphics Device. Graphics interface integrated in the chipset. Image This refers to the image, for example, of hard disk partitions saved to a file in order to restore them when necessary. Intel Active Management Technology This technology permits the diagnostics, management and remote control of PCs. It is only effective when all relevant system components, such as processors, operating systems and applications are supported.

Extensible Firmware Interface

Intel VT

The Intel Virtualization Technology (IVT) is the implementation of a secure closed environment for applications. Special (visualization) software an a VT-capable processor is required for its use.

Interface

- Physical interconnection (cable) of hardware elements such as PLCs, PCs, programming devices, printers or monitors.
- Interface for interactive software applications.

LAN

Local Area Network: LAN is a local network that consists of a group of computers and other devices that are distributed across a relatively restricted range and are linked with communication cables. The devices connected to a LAN are called nodes. The purpose of networks is the mutual use of files, printers or other resources.

Legacy Boot Device

Conventional drives can be used as USB devices.

License key

The license key represents the electronic license stamp of a license. Siemens provides the license keys for protected software.

License key disk

The license key disk contains the authorizations or license keys required to enable protected SIMATIC software.

Low-voltage directive

EC Product Safety Directive relating to the safety of products which are operated on low voltage (50 V AC to 1000 V AC, 70 V DC to 1500 V DC) and not specified in other directives. Compliance is confirmed by the CE symbol and the EC certificate of conformity.

Module

Modules are plug-in units for PLCs, programming devices or PCs. They are available as local modules, expansion modules, interfaces or mass storage (Mass storage module).

Motherboard

The motherboard is the core of the computer. Here, data are processed and stored, and interfaces and device I/Os are controlled and managed.

| Operating system | | |
|------------------|--|--|
| | Generic term which describes all functions for controlling and monitoring user program execution, distribution of system resources to the user programs and the operating mode in cooperation with the hardware (for example, Windows 7 Ultimate). | |
| Pixel | | |
| | The pixel represents the smallest element that can be reproduced on-screen or on a printer. | |
| Plug&Play | | |
| | Generally, a reference to the ability of a computer to automatically configure the system for communication with peripheral devices (for example monitors, modems or printers). The user can plug in a peripheral and "play" it at once without manually configuring the system. A Plug&Play PC requires both a BIOS that supports Plug&Play and a Plug&Play expansion card. | |
| POST | | |
| | Self-test performed by the BIOS after the computer is switched on. Performs a RAM test and a graphics controller test, for example. The system outputs audible signals (beep codes) if the BIOS detects any errors; the relevant message indicating cause of error is output on the screen. | |
| Programmable c | ontroller | |
| J | The programmable controllers of the SIMATIC S5 system consist of a central controller, one or several CPUs and various other modules (for example, I/O modules). | |
| PXE server | | |
| | A P reboot Execution Environment server is part of a network environment and can provide software to connected computers even before they boot. This can involve operating system installations or servicing tools, for example. | |
| RAL | | |
| | Restricted Access Location: Installation of the device in a production facility with restricted access, for example, a locked control cabinet. | |
| Recovery CD | | |
| | Contains the tools for configuring hard disks and the Windows operating system. | |
| Reset | | |
| | Hardware reset: Reset/restart of the PC using a button/switch. | |

| Restart | Warm restart of a computer without switching the power off (Ctrl + Alt + Del) |
|-------------------------|---|
| Restore DVD | |
| | The Restore DVD is used to restore the system partition or the entire hard disk to factory state if the system has crashed. The bootable DVD contains all the necessary image files. You can also create a boot disk allowing restoration via the network. |
| ROM | |
| | Read-Only Memory ROM is a read-only memory in which every memory location can be addressed individually. The programs or data are permanently stored and are not lost in the event of a power failure. |
| S.M.A.R.T | |
| | The Self-Monitoring, Analysis and Reporting Technology (SMART or S.M.A.R.T.) is an industry standard integrated in storage media. It makes for permanent monitoring of important parameters and early detection of imminent problems. |
| SATA | |
| | Serial ATA Interface for hard disk drives and optical drives with serial data transmission rates of up to 300 Mbps. |
| SETUP (BIOS S | etup) |
| | A program in which information about the device configuration (that is the configuration of the hardware on the PC/PG) is defined. The device configuration of the PC/PG is preset with defaults. Changes must therefore be entered in the SETUP if a memory expansion, new modules or a new drive are added to the hardware configuration. |
| SSD (Solid State Drive) | |
| | A Solid State Drive is a drive that can be installed like any other drive; it does not contain a rotating disk or other moving parts because only semiconductor memory chips of similar capacity will be used. This design makes SSDs more rugged, provides shorter access times, low energy consumption and rapid data transfer. |
| STEP 7 | |
| | Programming software for the creation of user programs for SIMATIC S7 controllers. |

Troubleshooting

Error cause, cause analysis, remedy

Trusted Execution Technology

Hardware implementation that allows secured execution of programs and applications. It is only effective when all relevant system components, such as processors, operating systems and applications are supported.

Wake on LAN

Wake on Local area network. This function allows the PC to be started via the LAN interface.

Warm restart

The restart of a computer after a program was aborted. The operating system is loaded and restarted again. The CTRL+ ALT+ DEL hotkey can be used to initiate a warm restart.

Index

2

24 V DC power supply Connecting, 48

Α

Abbreviations, 198, 203 AC power supply, 137 Allocation of resources, 82 Antivirus software, 57 Assignment I/O addresses, 156 Australia, 119 Automatic Update, 57

В

Backup battery, 143 Battery monitoring, 69 Battery replacement, 106 BIOS Setup, 170 Exit menu, 175 Menu layout, 173 Boot sequence, 182 Buffer memory, 132 Bus board Design, 145 Removing, 109 Bus module, (Bus board)

С

CE marking, 120 Certificates, 120 Certifications and approvals, 117 Certifications and approvals, 36 Clamp, (Mounting bracket) Cleaning Agents, 99 Climatic conditions, 135 Clock frequency, 115 COA label, 30 COM1 port, 151 Components sensitive to electrostatic charge, 121 Condensation, 28 Connecting 24 V DC power supply, 48 Peripherals, 43 Power supply, 50 Power supply 120/230 V AC, 45 Connection elements, (Interfaces) Connector pin assignment PCI slot, 147 CP 1616 onboard, 52

D

Data exchange, 51 Degree of protection, 33, 131 Design Bus board, 145 Motherboard, 140 Device Mounting, 38 Open, 78 Power off. 61 Power on, 56 Device configuration, 176 Device driver CP16xx.sys, 53 Device fan, (See Fan), (See Fan), (See Fan) Device fan supply, 142 DiagBase software, 67 DiagMonitor, 15 Temperature monitoring, 68 DiagMonitor software, 67 Diagnostics, 67, 67 DiagBase software, 67 DiagMonitor software, 67 Error Messages, 182 Troubleshooting, 191 Dimension drawing, 124 **Dimensional drawings** Expansion card, 130 Dimensions, 124 Dimensions of the device, 124 Directive ESD Directive, 121 Display, 11, 26 DisplayPort Interface, 152 Disposal, 116 DPP, (DisplayPort)

Drive bay module Removing, 84 Drives, 132 DVD burner, 132 DVD burner drive Removing, 89 DVI-I port, 153

Ε

Earth connection, 64 Electromagnetic compatibility, 132 Enhanced Write Filter, 70 Equipotential bonding, 44 ESD, 121 ESD Directive, 121 Ethernet, 134 Ethernet address, 29 Ethernet interface, 154 Ethernet RJ45 port, 14 Ethernet strain relief, 53 EU Declaration of Conformity, 120 EWF (Enhanced Write Filter), 70 Exit menu, 175 Expansion Memory, 79 Expansion module, (Expansion card) Expansion slots, 132

F

Fan, 100, 102, 112 Removal, 100, 102, 112 FBWF (File Based Write Filter), 73 FCC Rules (USA), 119 File Based Write Filter, 73 Fire protection covering, 35 Fire protection enclosure, 35 Firewall, 57

G

Graphic controller, 133

Η

Hard disk Removing, 85 Hard disk drive, 132 Hard disks Partitions, 58

I/O addresses Assianment, 156 Image & Partition Creator, 15 Initial commissioning, 56 Installation Memory modules, 79 Installation guidelines, 35 Installation information, 35 Installing Expansion card, 81 Memory modules, 80 Installing drives, 83 Installing expansion cards 627D, 81 Interfaces, 16, 134, 134, 141 COM1, 151 COM2, 151 DisplayPort, 152 DVI-I, 153 Ethernet RJ 45, 51 PROFIBUS, 51, 155 PROFIBUS/MPI, 14, 51, 51, 51 **PROFINET**, 51, 155 RJ45 Ethernet, 14 USB, 14 VGA, 14 Interference emission, 132 Internal interfaces, 142 Interrupt reaction time, 162

Κ

KC Mark, 119 Korea KC Mark, 119 Korean Certification, 119

L

Limitation of liability, 98 Lithium battery, 106 Localized information, 46

Μ

Main circuit board, (Motherboard) Main memory, 132 Mainboard, (Motherboard) Marking EU Declaration of Conformity, 120 Mechanical ambient conditions, 135 Memory configuration, 80 Memory expansion, 79 Memory media Drives, 132 Memory modules, 132 Installing, 79, 80 Removing, 80 Messages On the screen, 182 Modules Installing, 79 Module bracket, 81 Monitoring Status displays, 19, 19 Motherboard, 132, (Motherboard) Design, 140 Internal interfaces, 142 Location of the interfaces, 141 Mounting Device, 38 with latch fasteners. 40 Mounting clamp, (Mounting clip) Mounting clip Mounting, 38 Mounting cutout Dimensions, 33 Preparing, 33 Mounting positions, 31

Ν

New Zealand, 119 Note, 35 General Information, 25 Installation guidelines, 35

0

Online ordering system, 51 On-screen error messages, 182 Open Device, 78 Operating system Initial commissioning, 56 Operating systems, 14 Operation Capacitive multi-touch screen, 64 Single touch screen, 63 Touch screen, 62

Ρ

Package contents, 27 Checking, 27 Packaging, 27 Checking, 27 Removing, 27 Partitions Hard disks, 58 PCI Express Pin assignment, 149 PCI hardware interrupt, 162 PCI slot Connector pin assignment, 147 PE conductor, 64 Pin assignment PCI Express slot, 149 Pixel. 26 Defective pixel, 26 Plug-in card, (Expansion card) Ports, (Interfaces) RJ45 Ethernet, 154 USB 3.0. 154 Power consumption, 131 Power factor correction, 137 Power Good signal, 138 Power requirements, 136 Power supply, 45, (Removing), (Power supply) AC voltage supply, 137 DC voltage supply, 139 WinAC module, 148 Power supply fan Removal, 110 Power supply unit, (Power supply) Processor, 132 Removal, 114 Processor type, 115 PROFIBUS, 51 Interface, 155 PROFIBUS/MPI, 51, 51, 51, 134 PROFIBUS/MPI interface, 14 PROFINET, 29, 51, 52, 134, 165 Interface, 155 Protective measure Static electricity, 123

R

Radiation, 22 High frequency radiation, 22 RAID Level 1, 58 **RAID** system Checking status, 93 Displaying the defective HDD in the RAID software, 94 Integrating a new hard disk, 96 Management functions, 58, 92 Management functions, 58, 92 **RAID1** system Mounting locations for hard disks, 104 Replacing a defective hard disk, 104 Status displays of the hard disks, 104 Recycling, 116 Removing Bus board, 109 Drive bay module, 84 DVD burner drive, 89 Fan, 100, 102, 112 Hard disk. 85 Memory modules, 80 Power supply, 108 Power supply fan, 110 Processor, 114 Repairs, 97 Replacing Battery, 106 Resolution, 11 RJ45 Ethernet, 51

S

Safety information Storage, 28 Transportation, 28 Scope, 3 Scope of application, 12 Serial number, 29 Setup, (BIOS Setup) SIMATIC S7, 51 Single touch screen Operation, 63 Slot cover, 81 SOFTNET S7, 51 Startup, 182 Static electricity Protective measures, 123 Status displays, 19, 19

Strain relief Ethernet cable, 53 PROFINET cable, 54 Supply voltage, 46, 131 Switching on the device Configure automatic startup, 57 System resources, 156 I/O address allocation, 156

Т

Temperature monitoring, 68 TFT technology, 11 Third-party expansion cards, 191 Touch screen Operation, 62 Troubleshooting/FAQs, 191

U

Update, 57 USA FCC Rules, 119 USB 3.0 Port, 154 USB port, 14 User Account Control, 57

V

Ventilation slits, 35 VGA port, 14

W

Warranty, 21 Watchdog, 68 Monitoring function, 68 Monitoring times, 69 Weight, 131 WinAC module Power supply connection, 148 Windows Action Center, 57